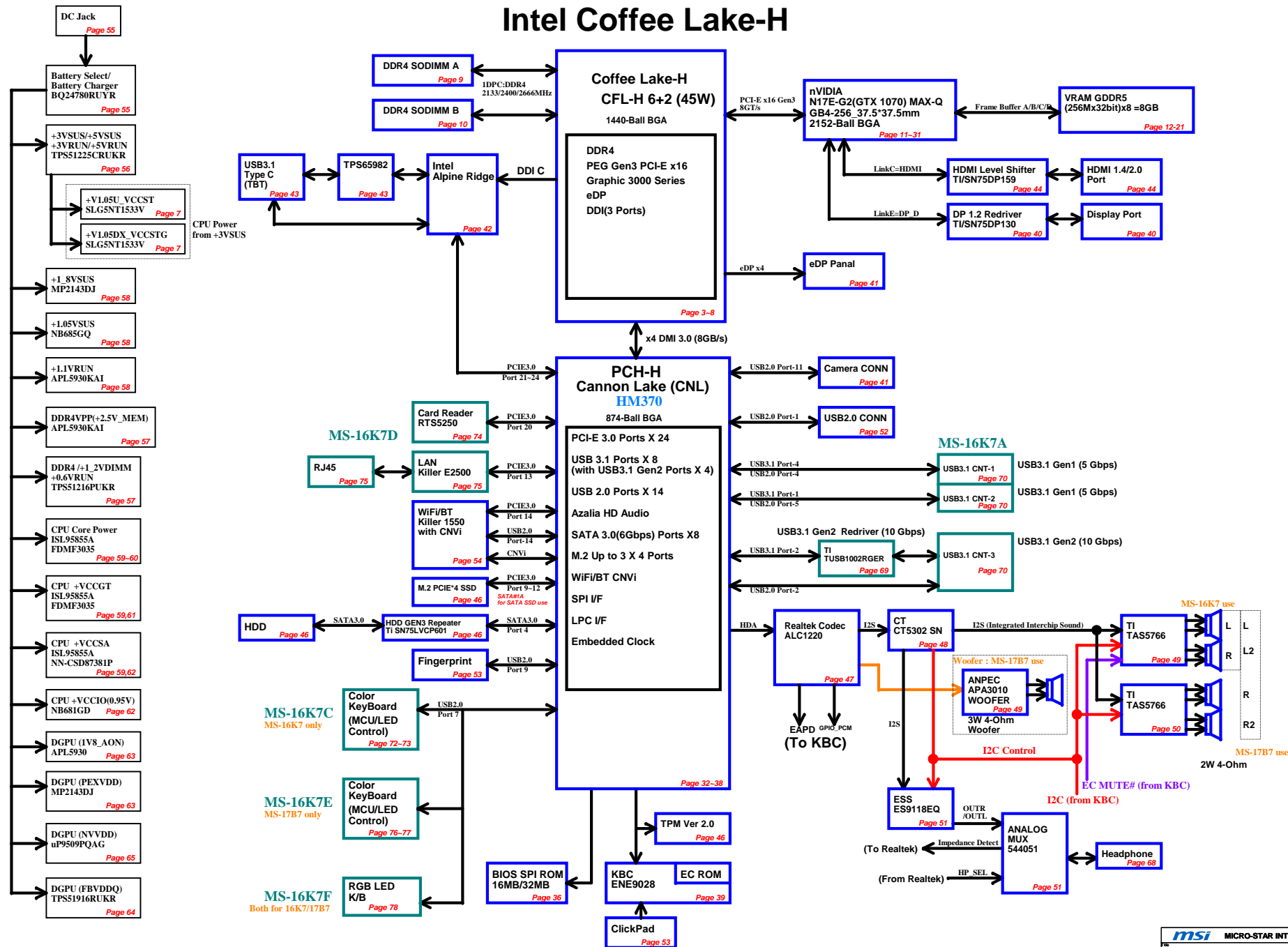
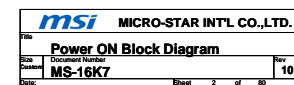


MS-16K7/17B7 Ver : 10

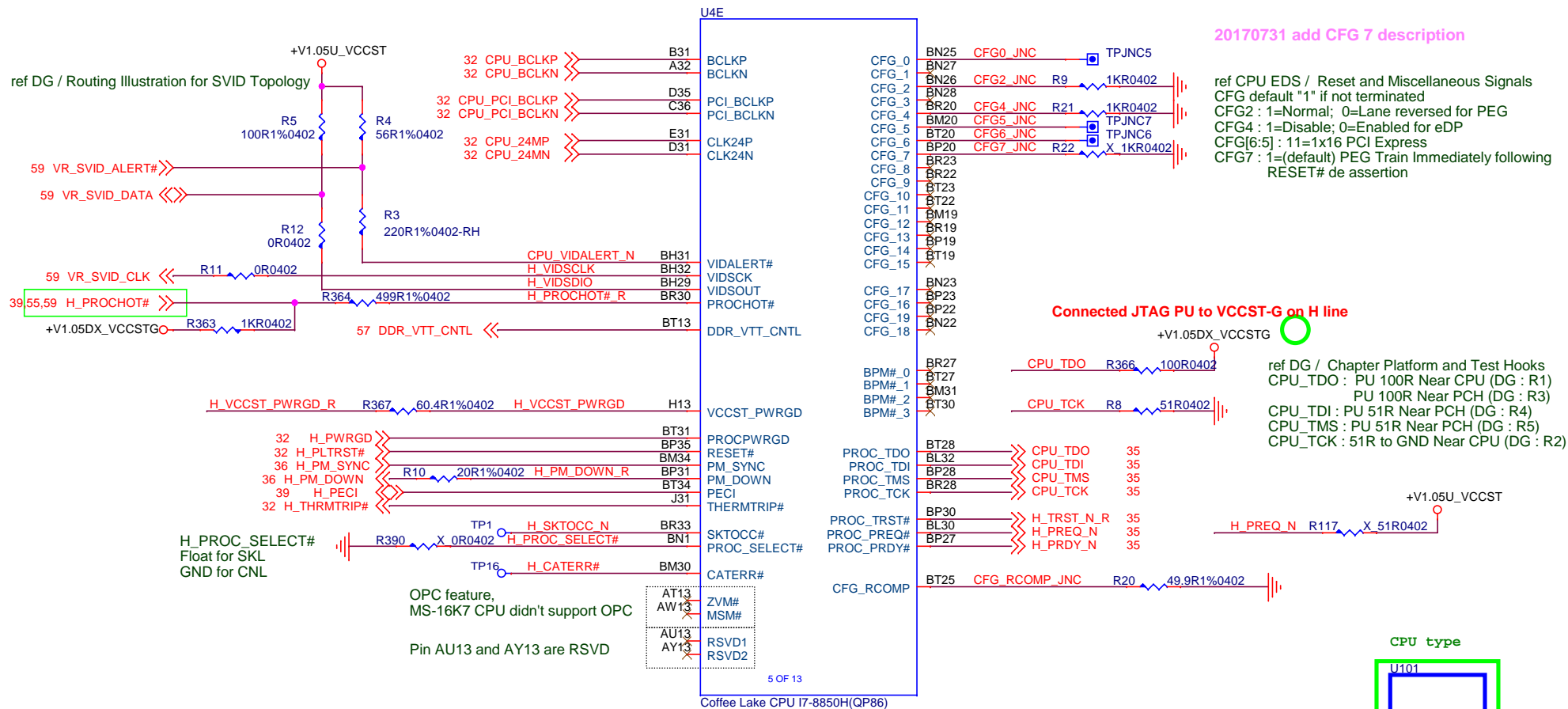
Intel Coffee Lake-H



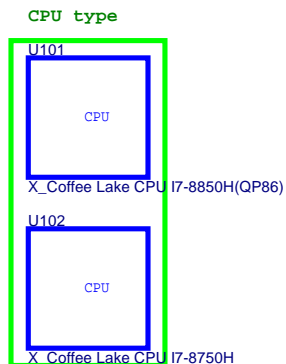
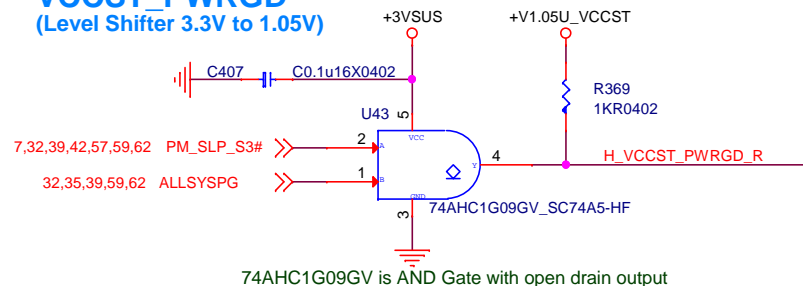
ref DG Chapter45 Power Sequencing Spec



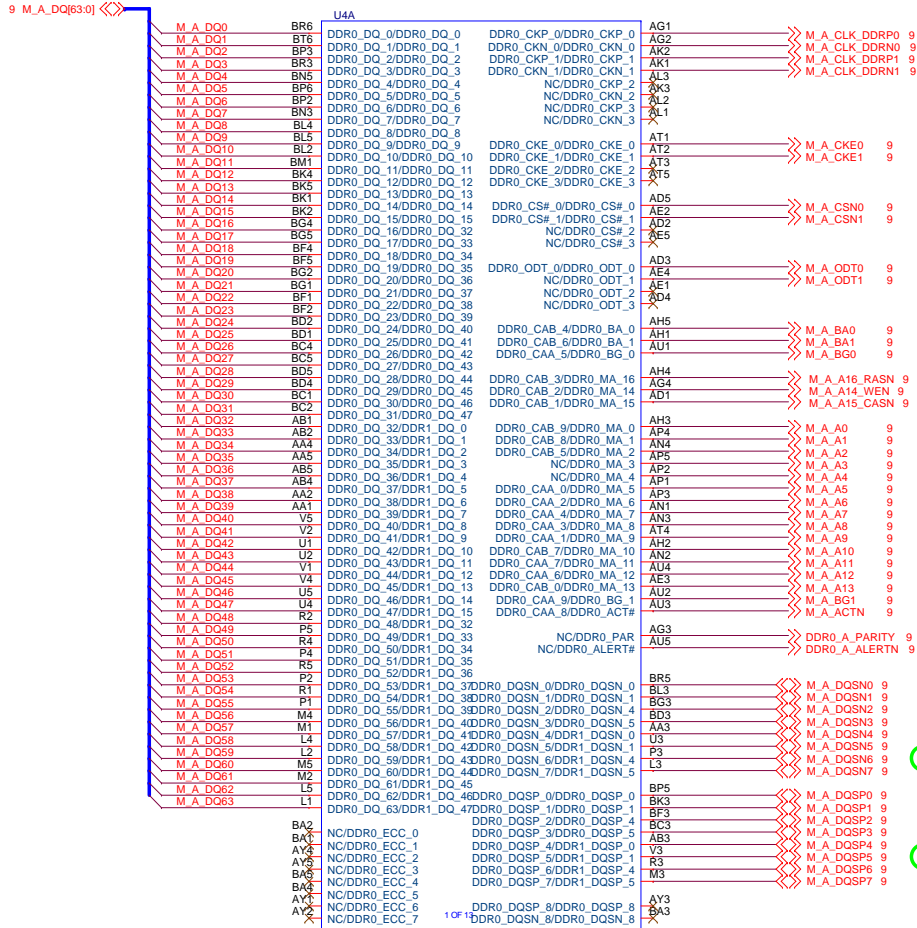
CFL-H (HOST)



VCCST_PWRGD (Level Shifter 3.3V to 1.05V)

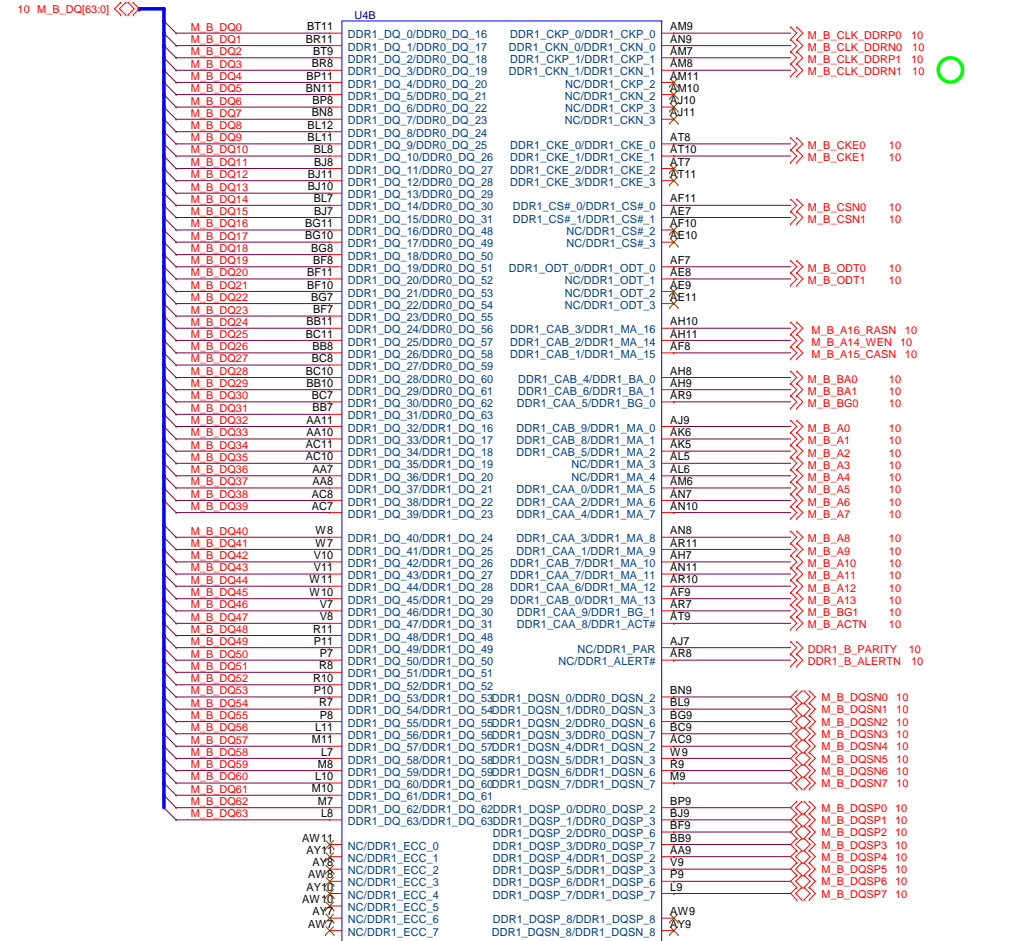


DDR Channel A

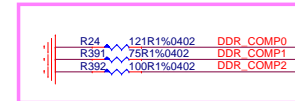


DDR CHANNEL A
Coffee Lake CPU I7-8850H(QP86)

DDR Channel B



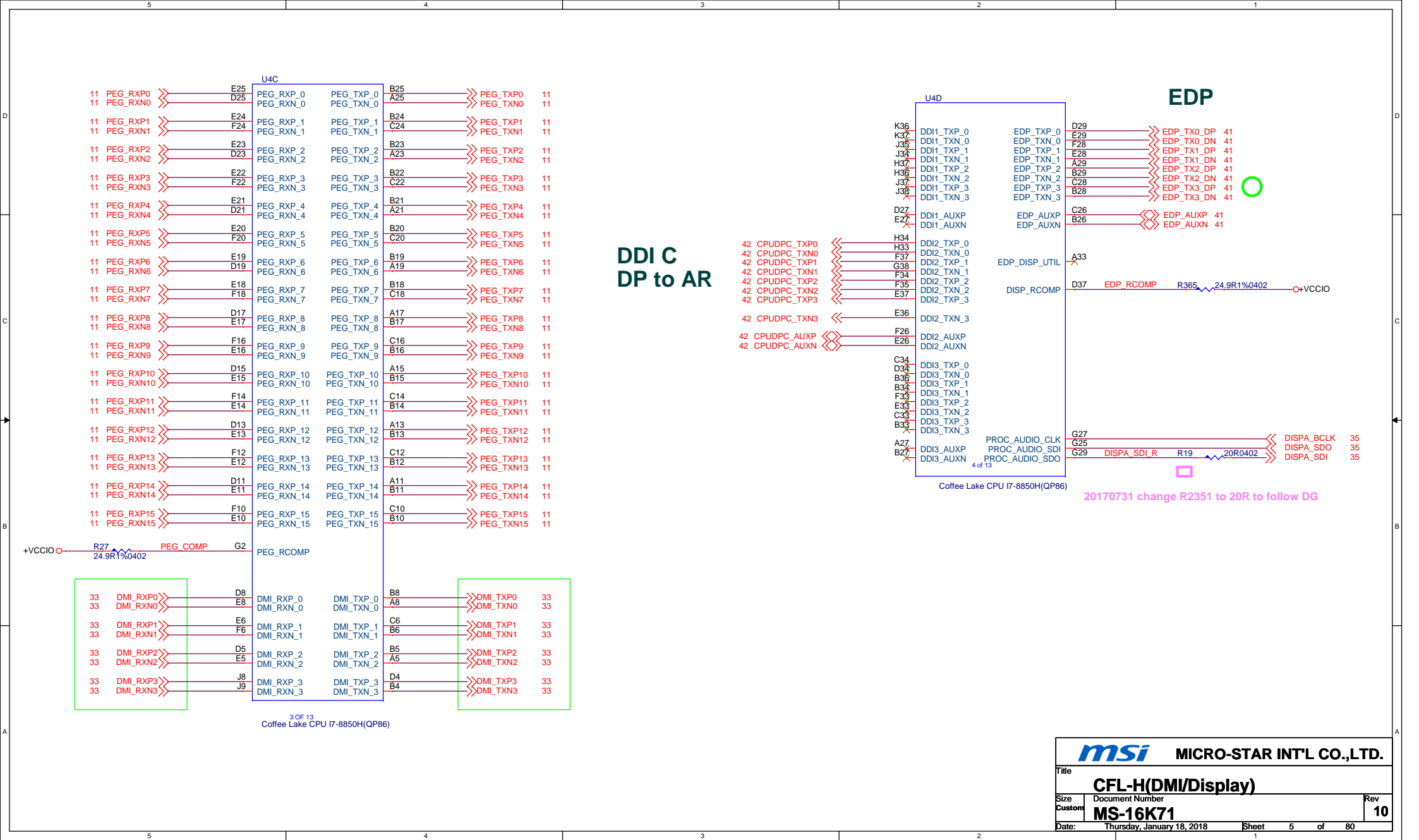
DDR CHANNEL B
Coffee Lake CPU I7-8850H(QP86)



20170731 the three Resistance close CPU

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Title	
CFL-H(DDR4)	
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+VCC_CORE

remove three 220uF Cap (Power repeat)

Follow CRB v0.7
+VCCCORE
3 x 220uF POSCAP
12 x 22uF 0603
42 x 10uF 0402
48 x 1uF 0201

+VCC_CORE

+VCC_CORE

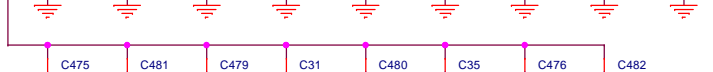
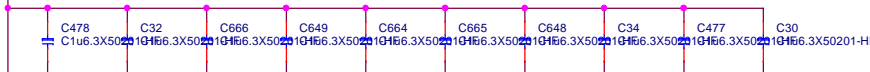
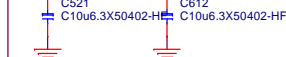
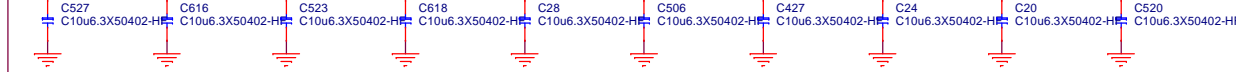
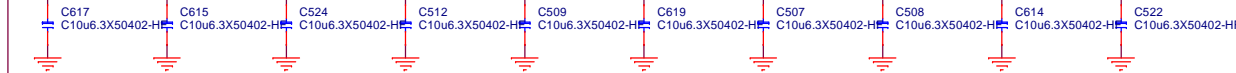
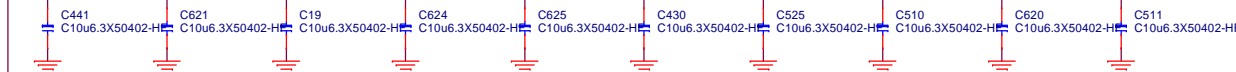
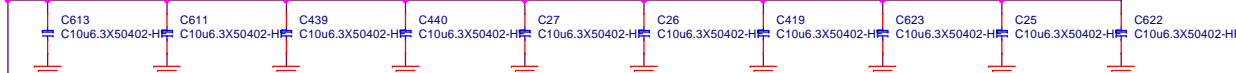
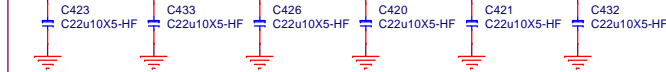
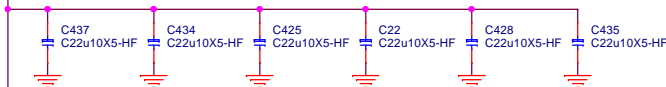
+VCC_CORE

+VCC_CORE

U4I	128A
AA13	VCC1
AA31	VCC2
AA32	VCC3
AA33	VCC4
AA34	VCC5
AA35	VCC6
AA36	VCC7
AA37	VCC8
AA38	VCC9
AB29	VCC10
AB30	VCC11
AB31	VCC12
AB32	VCC13
AB35	VCC14
AB36	VCC15
AB37	VCC16
AB38	VCC17
AC13	VCC18
AC14	VCC19
AC29	VCC20
AC30	VCC21
AC31	VCC22
AC32	VCC23
AC33	VCC24
AC34	VCC25
AC35	VCC26
AC36	VCC27
AD13	VCC28
AD14	VCC29
AD31	VCC30
AD32	VCC31
AD33	VCC32
AD34	VCC33
AD35	VCC34
AD36	VCC35
AD37	VCC36
AD38	VCC37
AE13	VCC38
AE14	VCC39
AE30	VCC40
AE31	VCC41
AE32	VCC42
AE35	VCC43
AE36	VCC44
AE37	VCC45
AE38	VCC46
AF29	VCC47
AF30	VCC48
AF31	VCC49
AF32	VCC50
AF33	VCC51
AF34	VCC52
AF35	VCC53
AF36	VCC54
AF37	VCC55
AF38	VCC56
AG14	VCC57
AG31	VCC58
AG32	VCC59
AG33	VCC60
AG34	VCC61
AG35	VCC62
AG36	VCC63

VCC_SENSE
VSS_SENSE

Coffee Lake CPU I7-8850H(QP86)



U4J	W35
K14	VCC1
L13	VCC2
L14	VCC3
N13	VCC4
N14	VCC5
N30	VCC6
N31	VCC7
N32	VCC8
N35	VCC9
N36	VCC10
N37	VCC11
N38	VCC12
P13	VCC13
P14	VCC14
P29	VCC15
P30	VCC16
P31	VCC17
P32	VCC18
P33	VCC19
P34	VCC20
P35	VCC21
P36	VCC22
R13	VCC23
R31	VCC24
R32	VCC25
R33	VCC26
R34	VCC27
R35	VCC28
R36	VCC29
R37	VCC30
R38	VCC31
T29	VCC32
T30	VCC33
T31	VCC34
T32	VCC35
T35	VCC36
T36	VCC37
T37	VCC38
T38	VCC39
U29	VCC40
U30	VCC41
U31	VCC42
U32	VCC43
U33	VCC44
U34	VCC45
U35	VCC46
U36	VCC47
V13	VCC48
V14	VCC49
V31	VCC50
V32	VCC51
V33	VCC52
V34	VCC53
V35	VCC54
V36	VCC55
V37	VCC56
V38	VCC57
W13	VCC58
W14	VCC59
W29	VCC60
W30	VCC61
W31	VCC62
W32	VCC63

10 OF 13
Coffee Lake CPU I7-8850H(QP86)

VCCORE_VCC_SEN 59

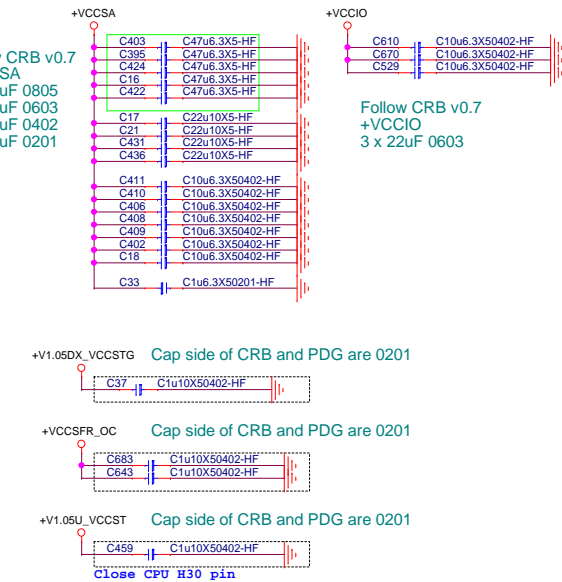


VCCORE_VSS_SEN 59

msi

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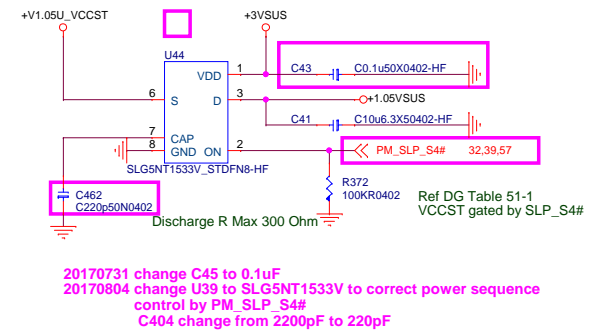
Title	CFL-H(Power1)	Rev	10
Size	Document Number		
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+V1.05U_VCCPLL

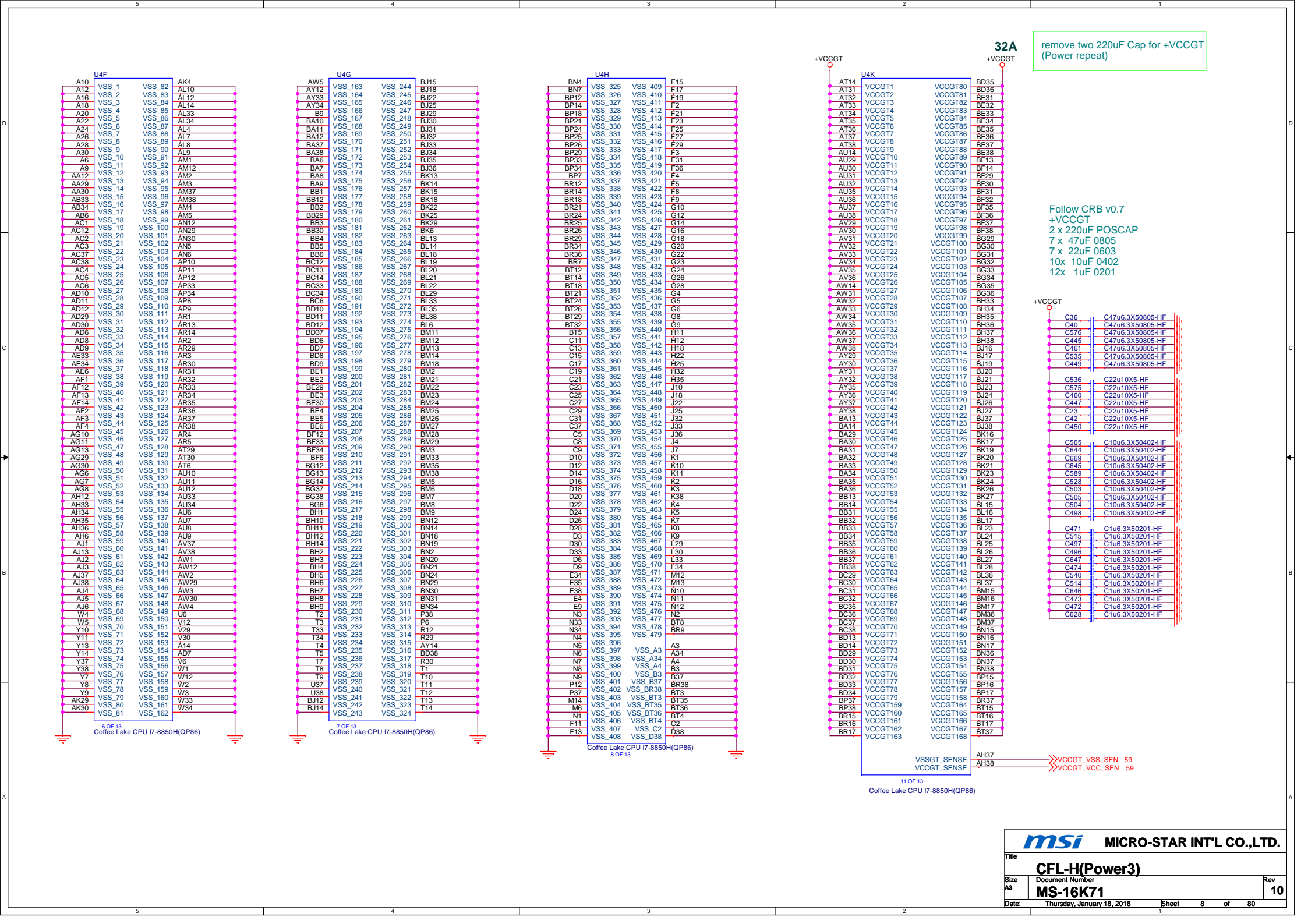
C500 C1u10X50402-HF

Close CPU H28 and J28 pin

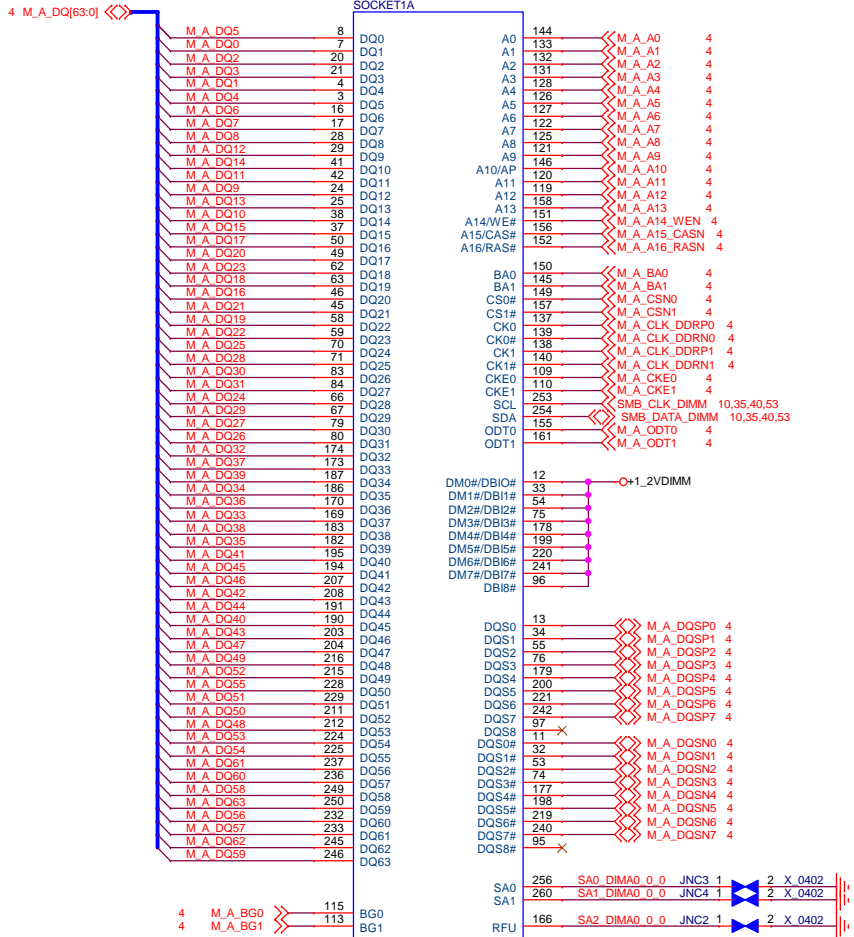


PN : T3E-1GT0800-O05 MC74VHC1GT08 AND Gate Level Shifter		VCC	Min	Max
	VIH	3V	1.4V	
	VIL	3V		0.53V

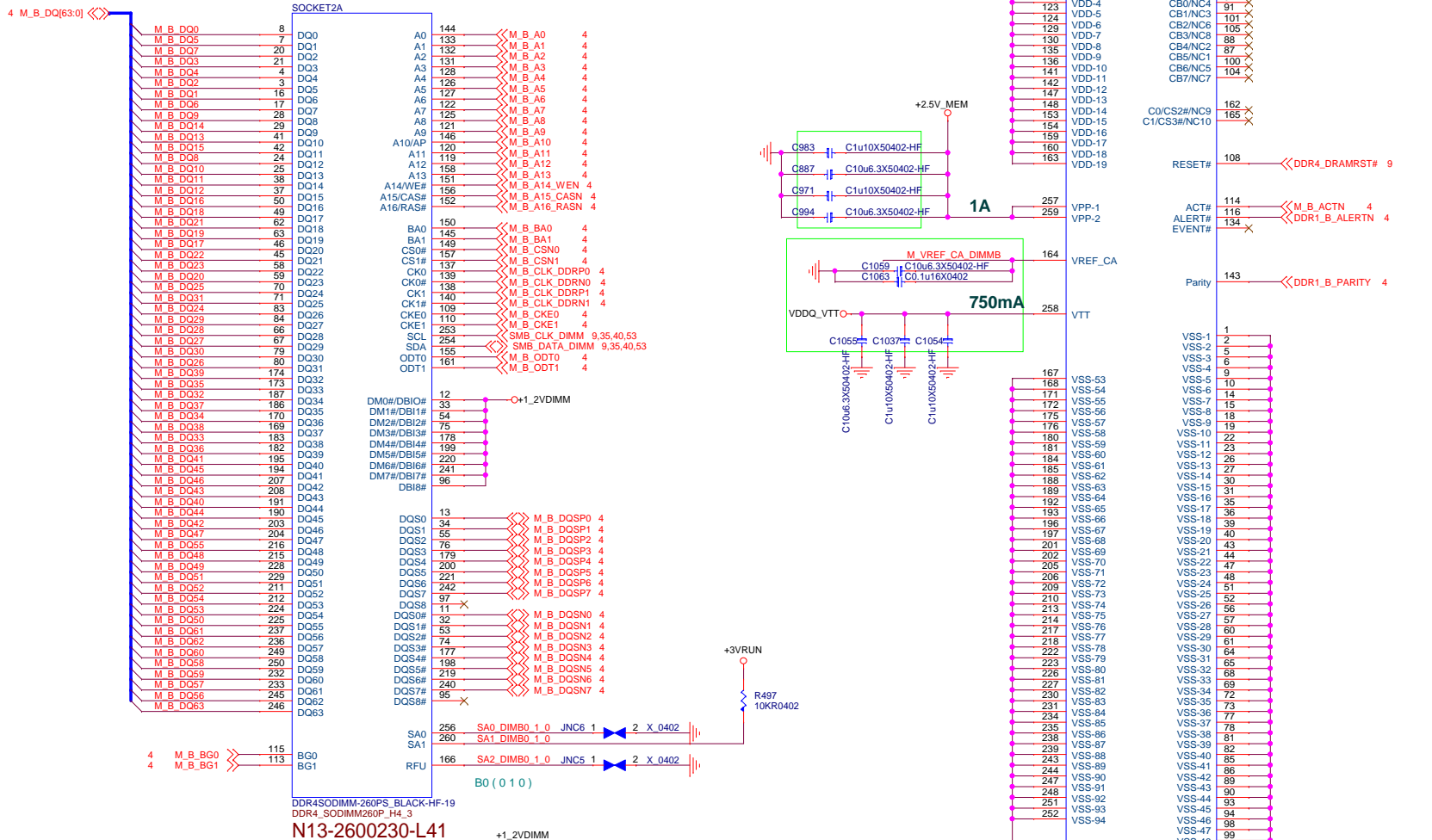
20170913 add R604 to follow DG



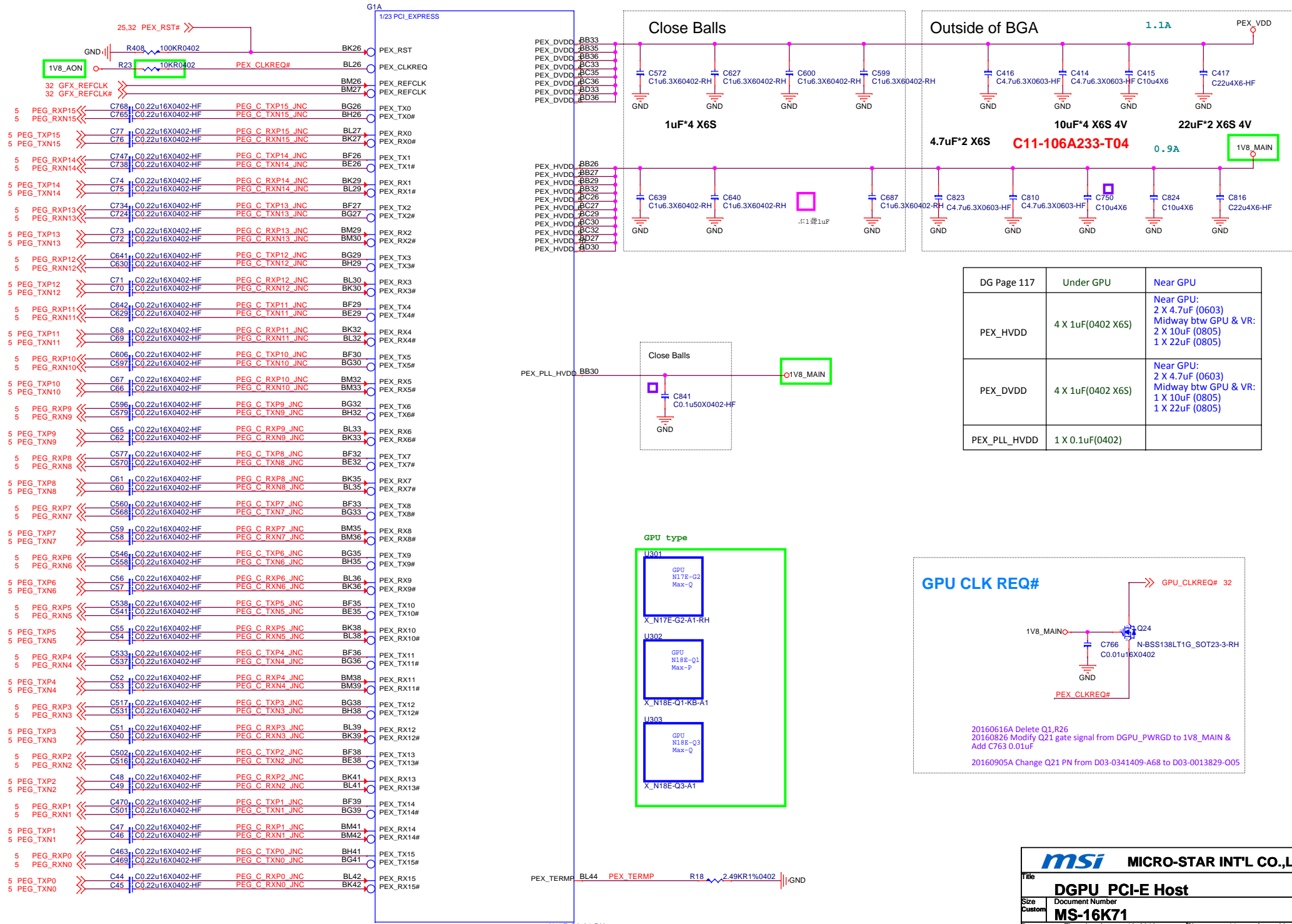
SODIMM_A0 (TOP-Reverse)



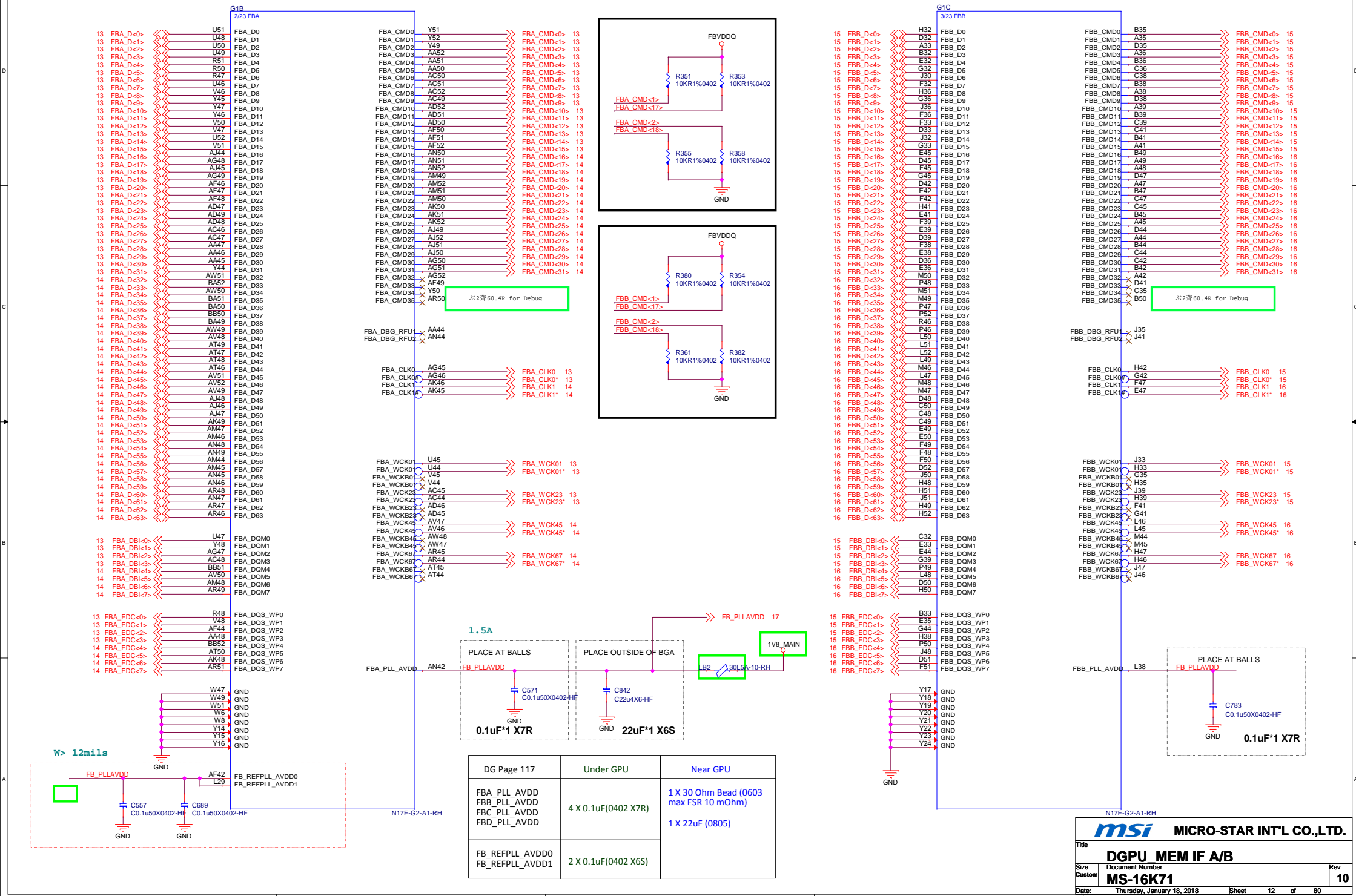
SODIMM_B0 (TOP-Standard)



GPU PCI EXPRESS

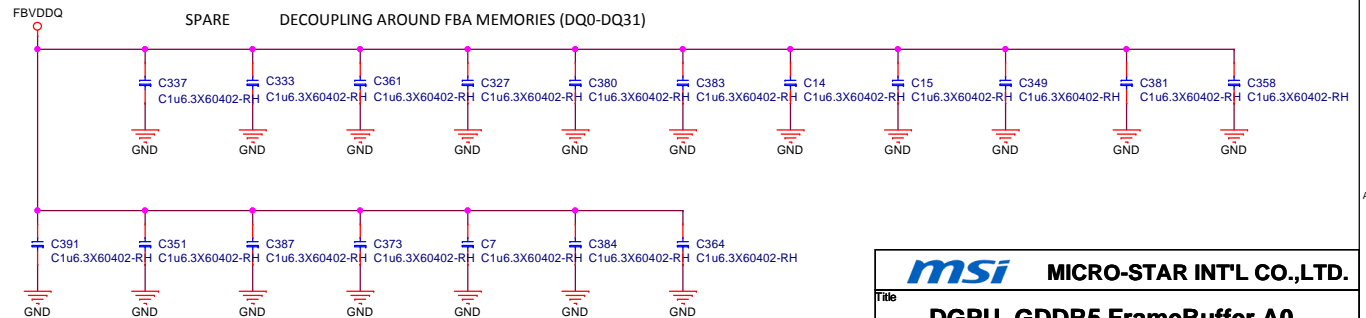
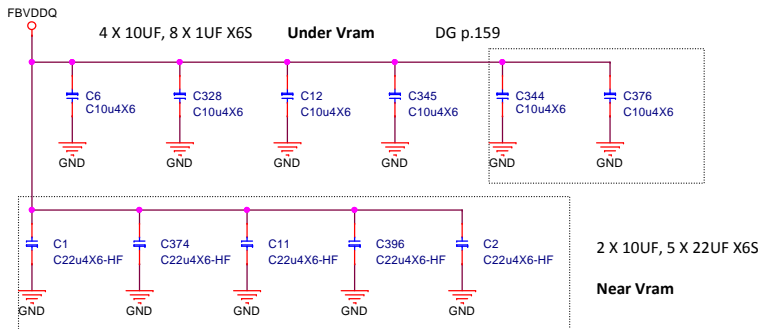
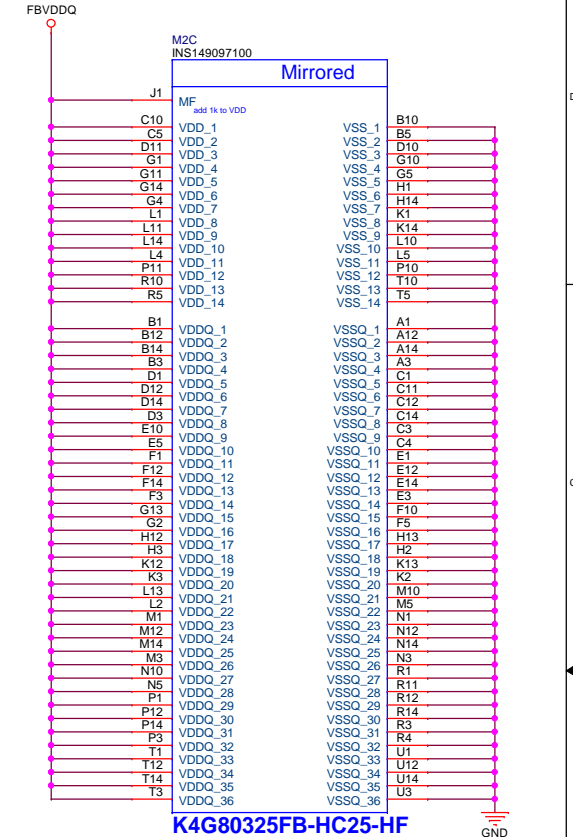
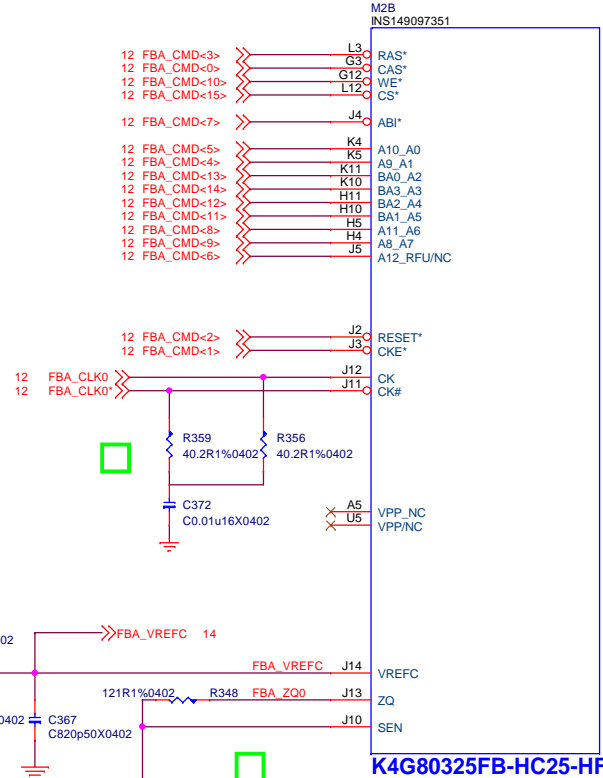
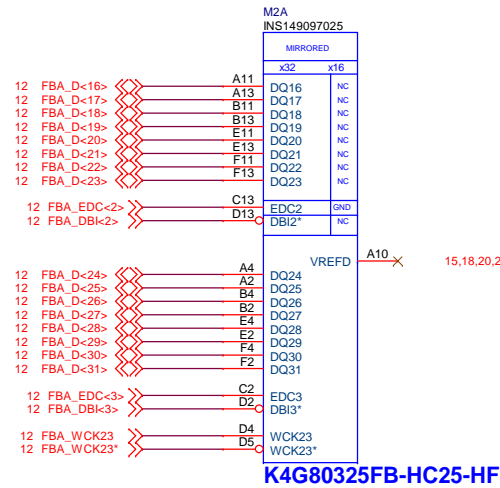
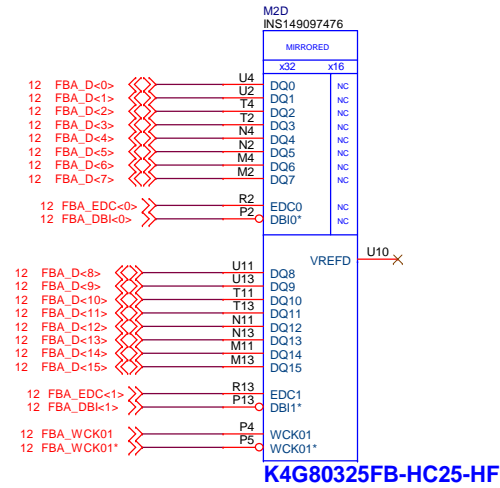


GPU Frame Buffer Partition A/B

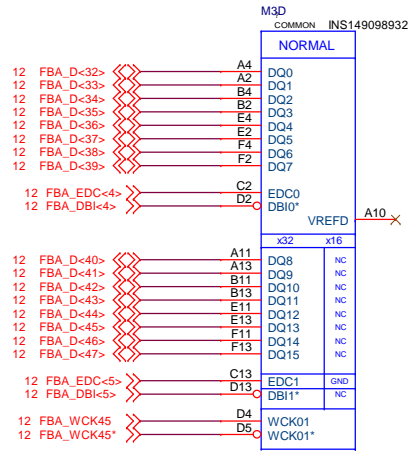


Hynix PN : M12-5GC2H05-H23 2G(64Mx32bit)
Samsung PN : M12-2032585-S02 2G(64Mx32bit)

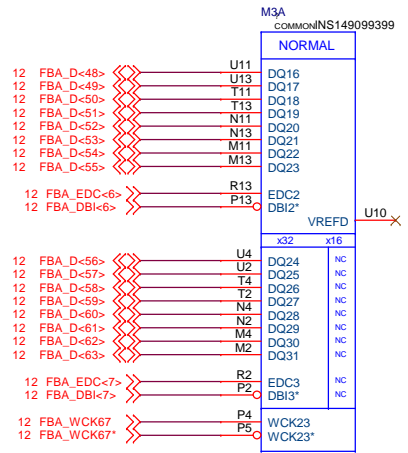
DGPU_GDDR5 FrameBuffer A0



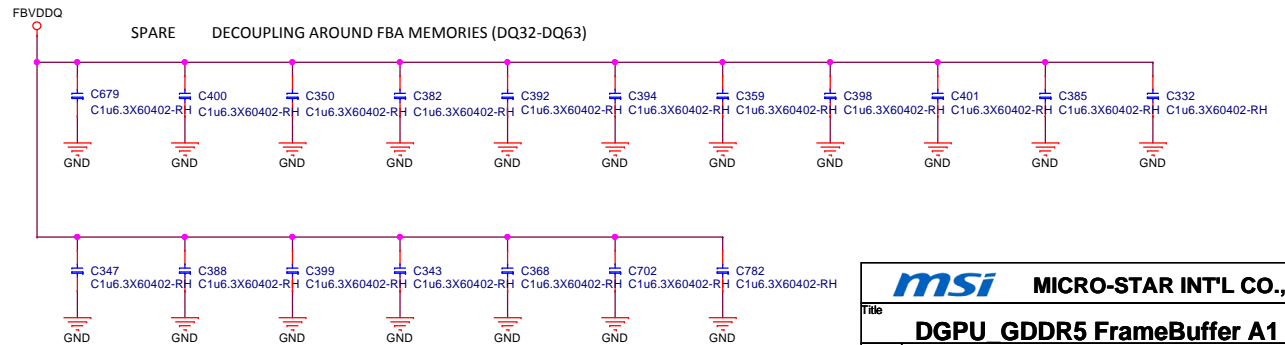
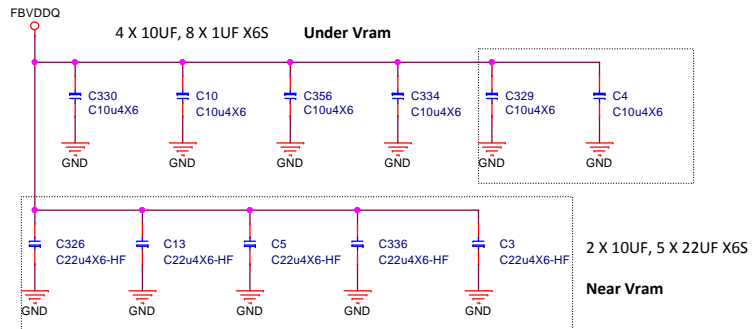
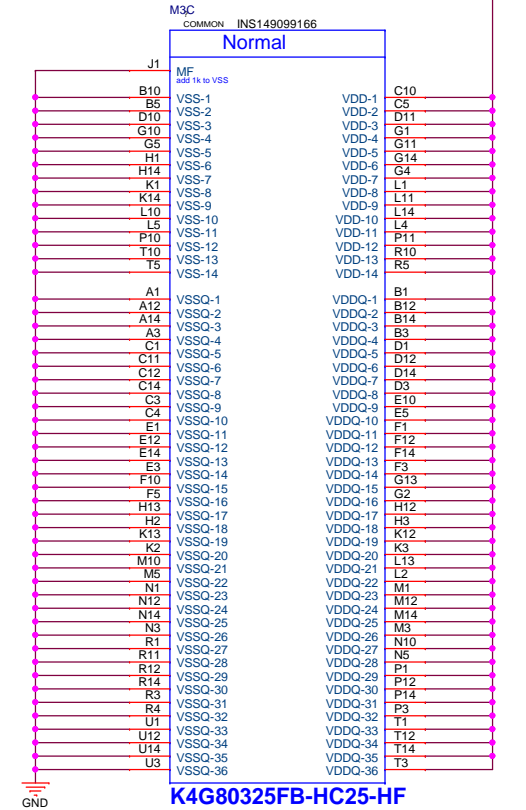
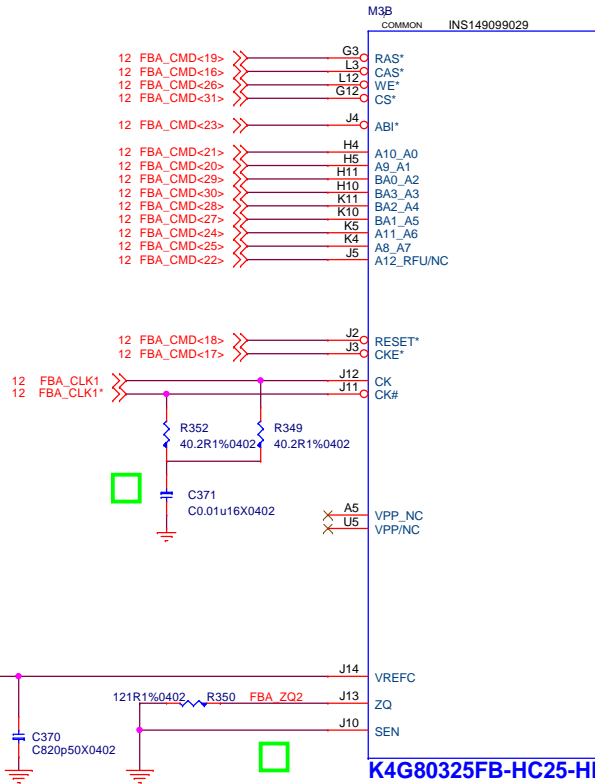
DGPU_GDDR5 FrameBuffer A1



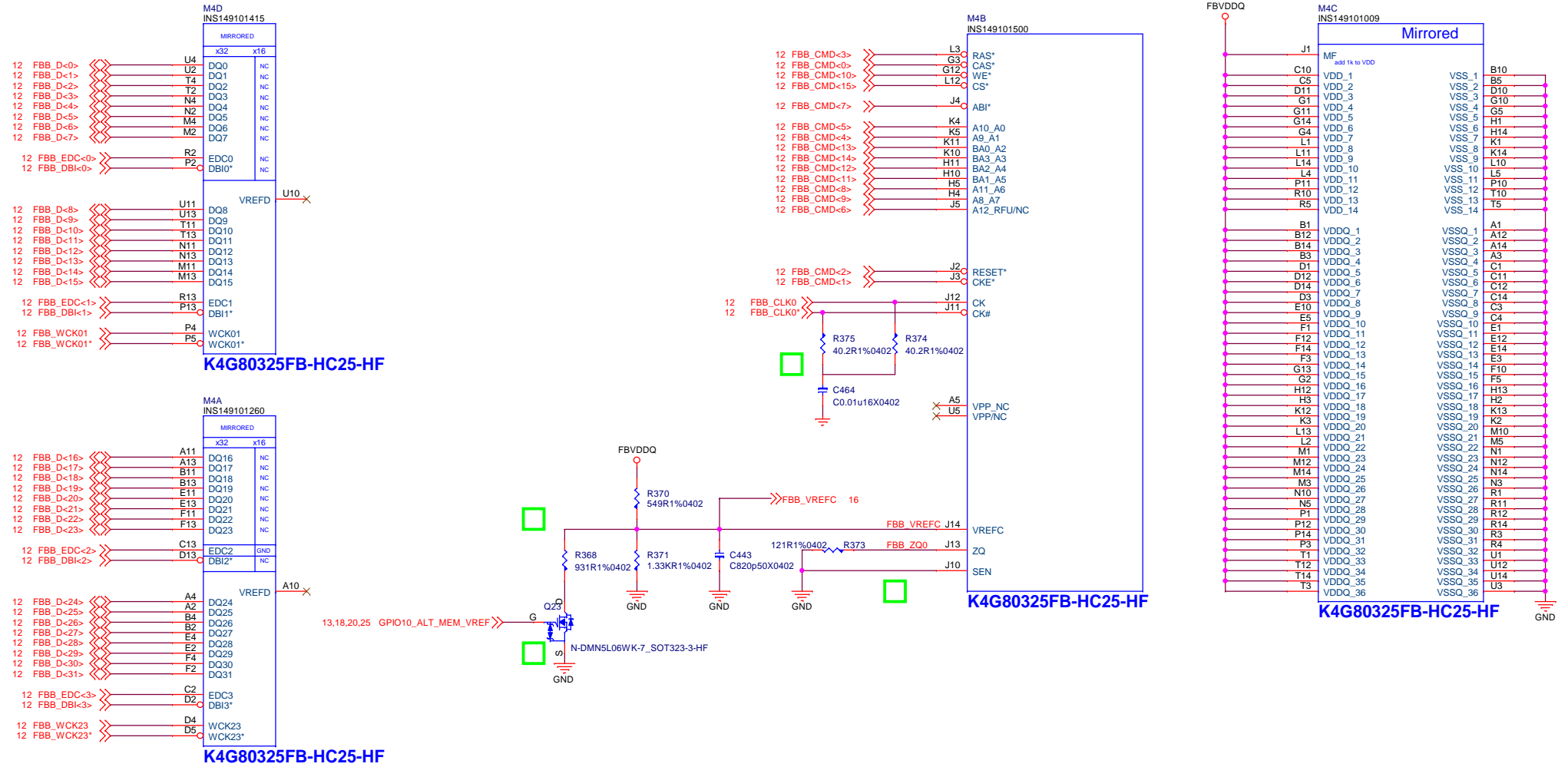
K4G80325FB-HC25-HF



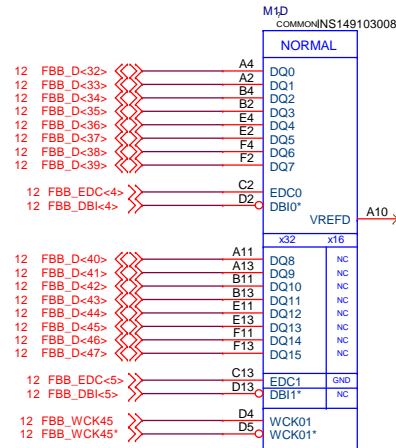
K4G80325FB-HC25-HF



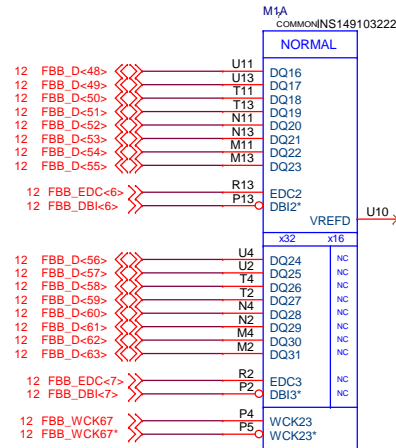
DGPU_GDDR5 FrameBuffer B0



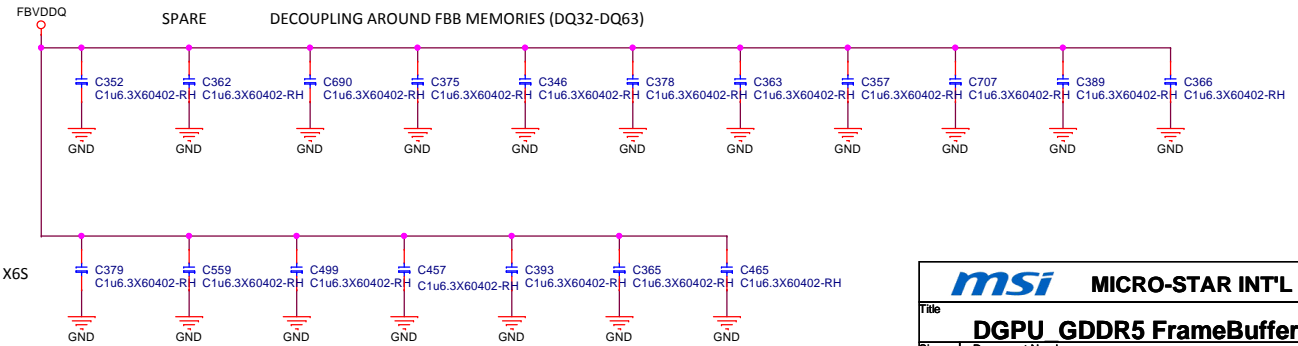
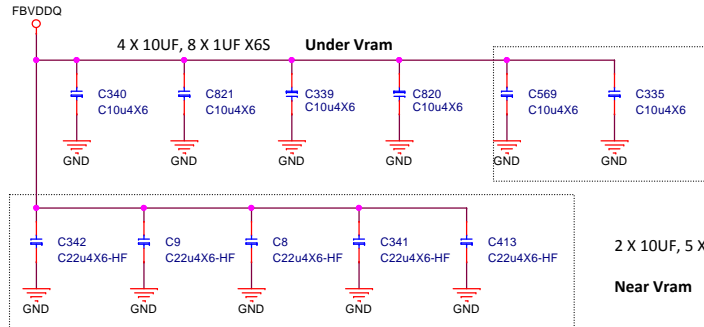
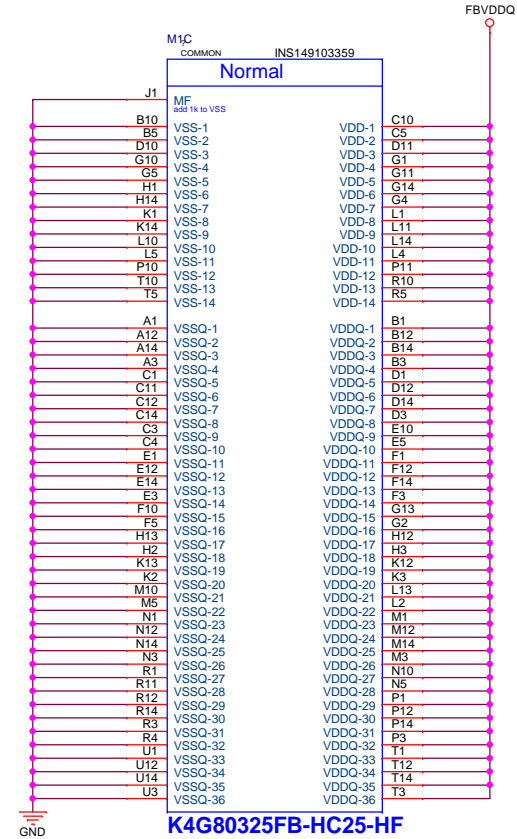
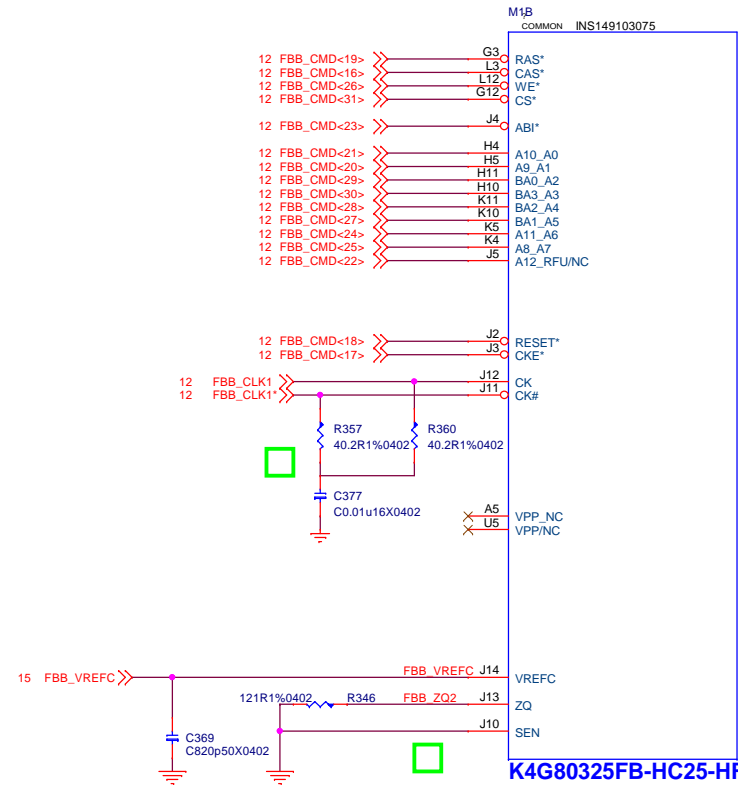
DGPU_GDDR5 FrameBuffer B1



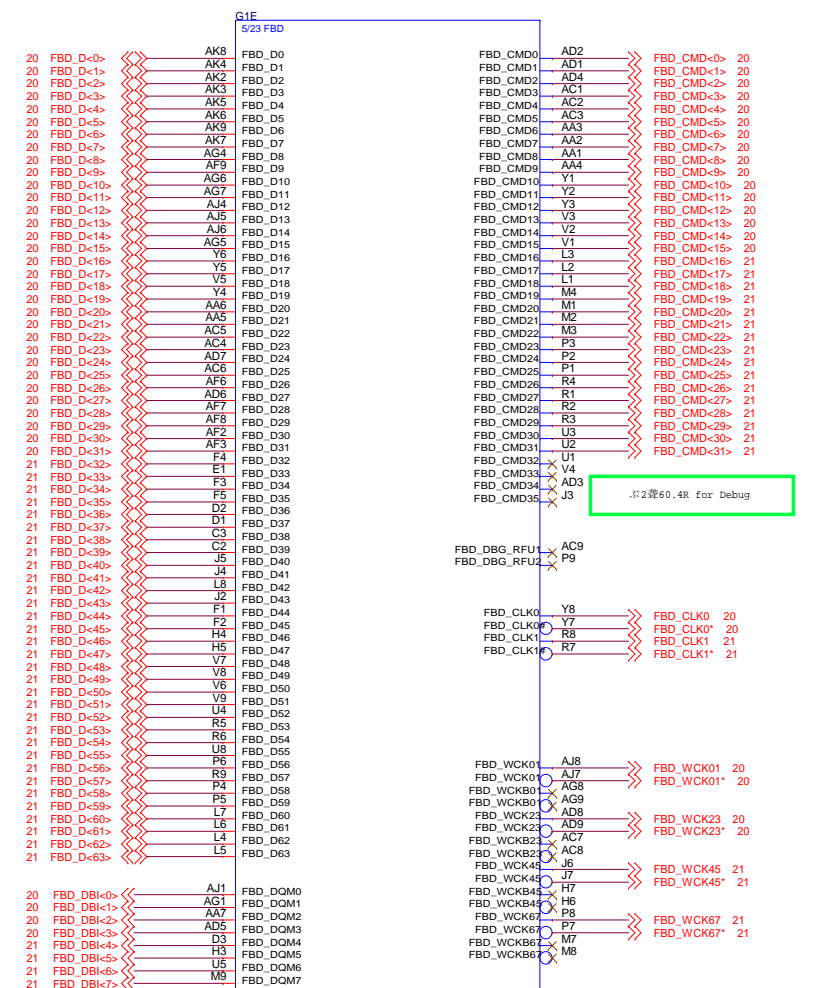
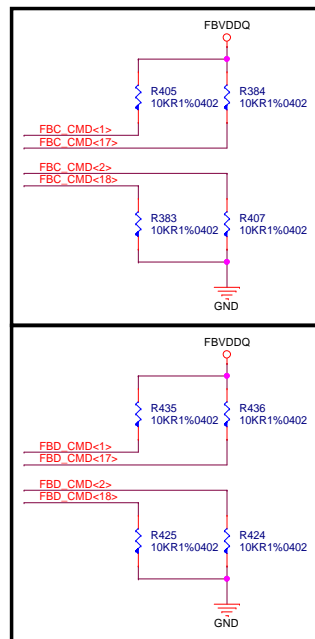
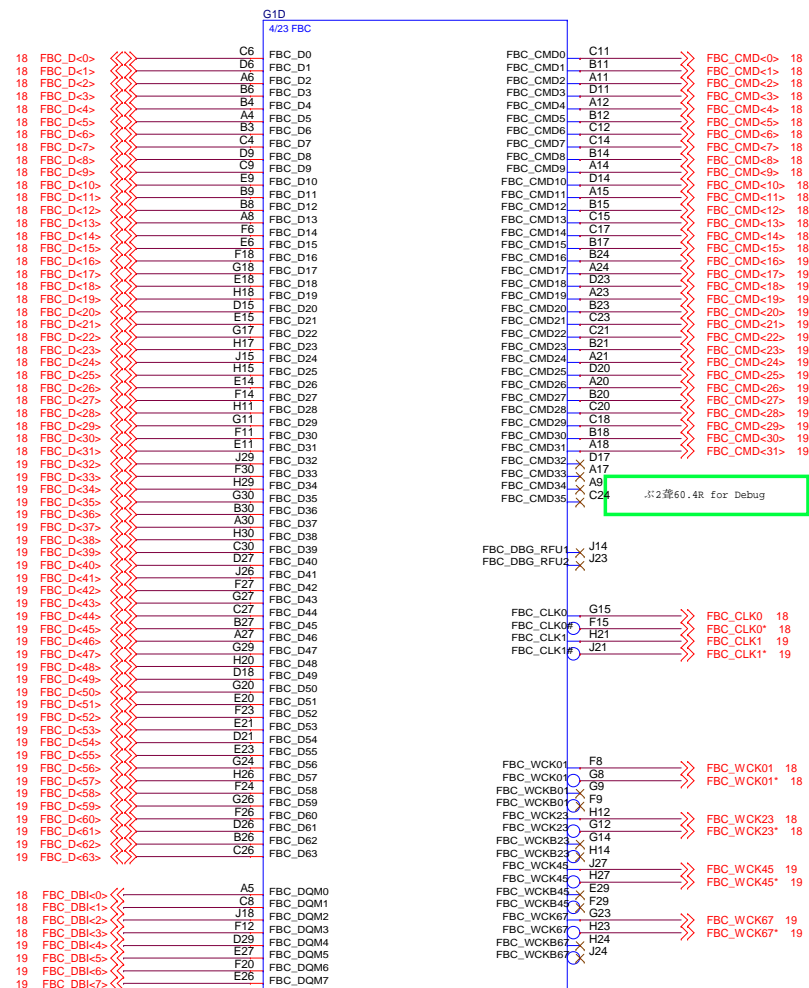
K4G80325FB-HC25-HF



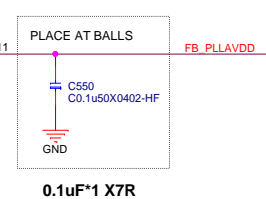
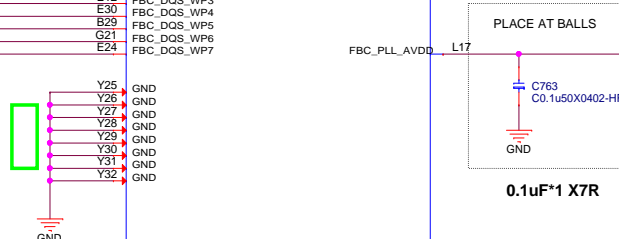
K4G80325FB-HC25-HF



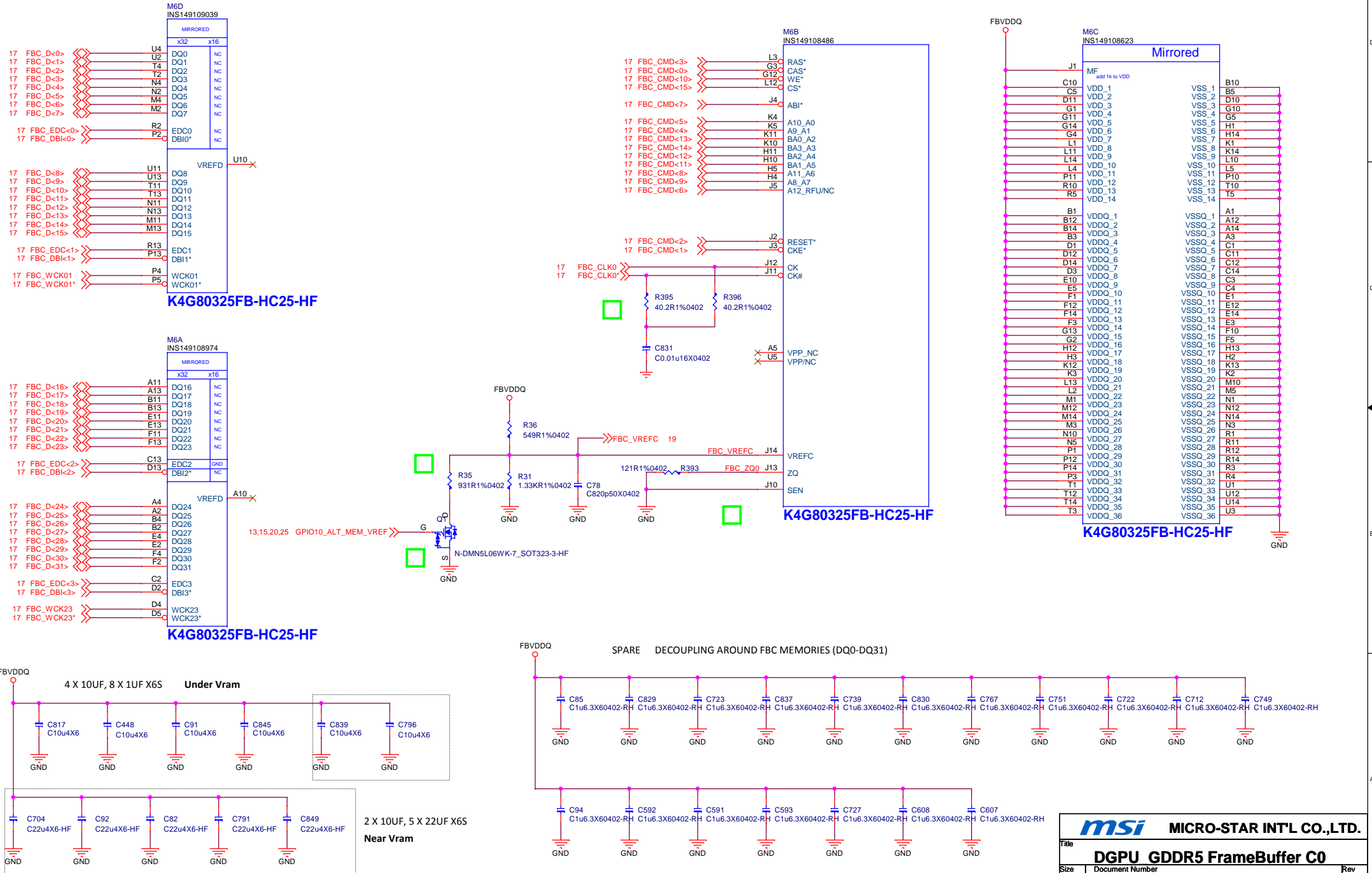
GPU Frame Buffer Partition C/D

GDDR5 Mapping By GB4-256

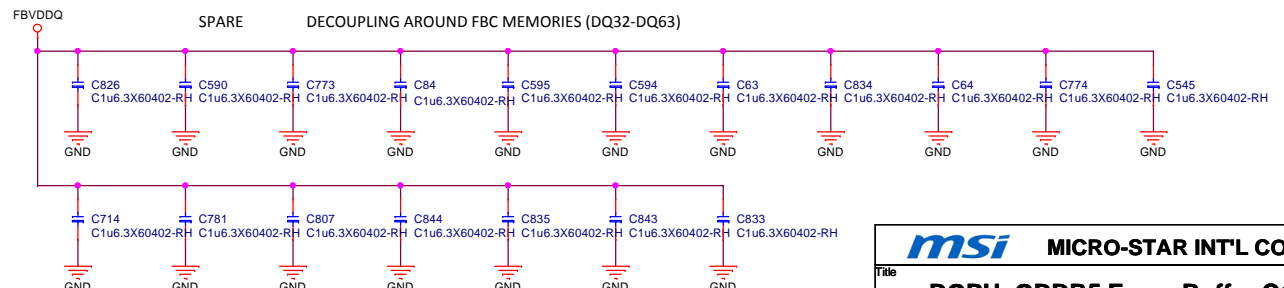
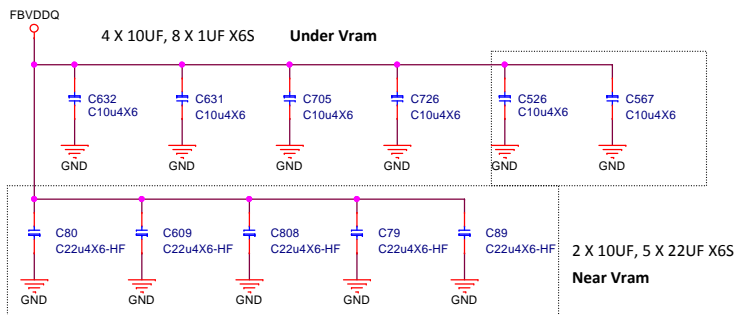
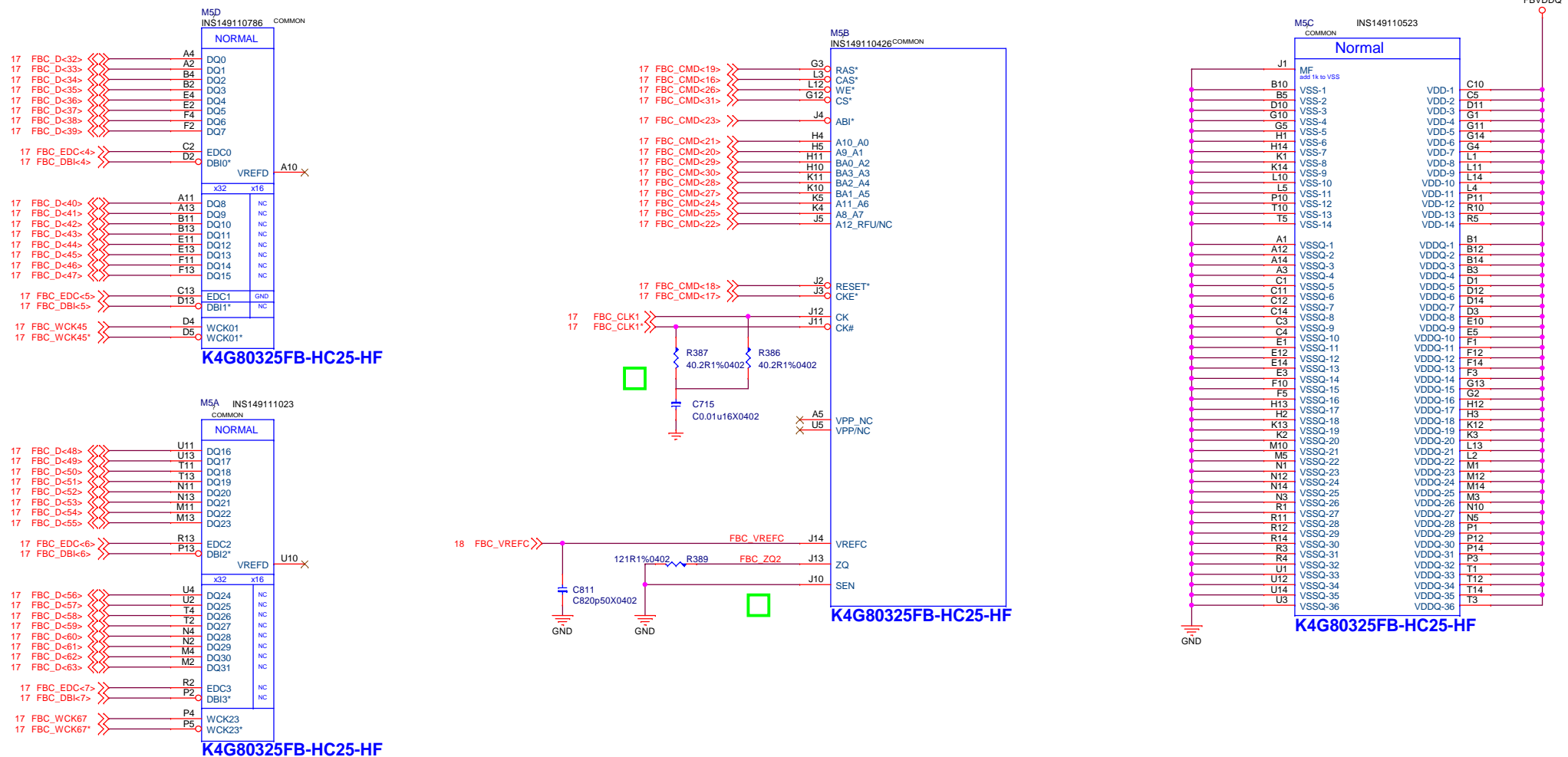
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CMD1	CKE*	
CMD2	RST*	
CMD3	RAS*	
CMD4	A1 A9	
CMD5	A0 A10	
CMD6	A12 RFU	
CMD7	ABI*	
CMD8	A6 A11	
CMD9	A7 A8	
CMD10	WE*	
CMD11	A5 BA1	
CMD12	A4 BA2	
CMD13	A2 BA0	
CMD14	A3 BA3	
CMD15	CS*	
CMD16		CAS*
CMD17		CKE*
CMD18		RST*
CMD19		RAS*
CMD20		A1 A9
CMD21		A0 A10
CMD22		A12 RFU
CMD23		ABI*
CMD24		A6 A11
CMD25		A7 A8
CMD26		WE*
CMD27		A5 BA1
CMD28		A4 BA2
CMD29		A2 BA0
CMD30		A3 BA3



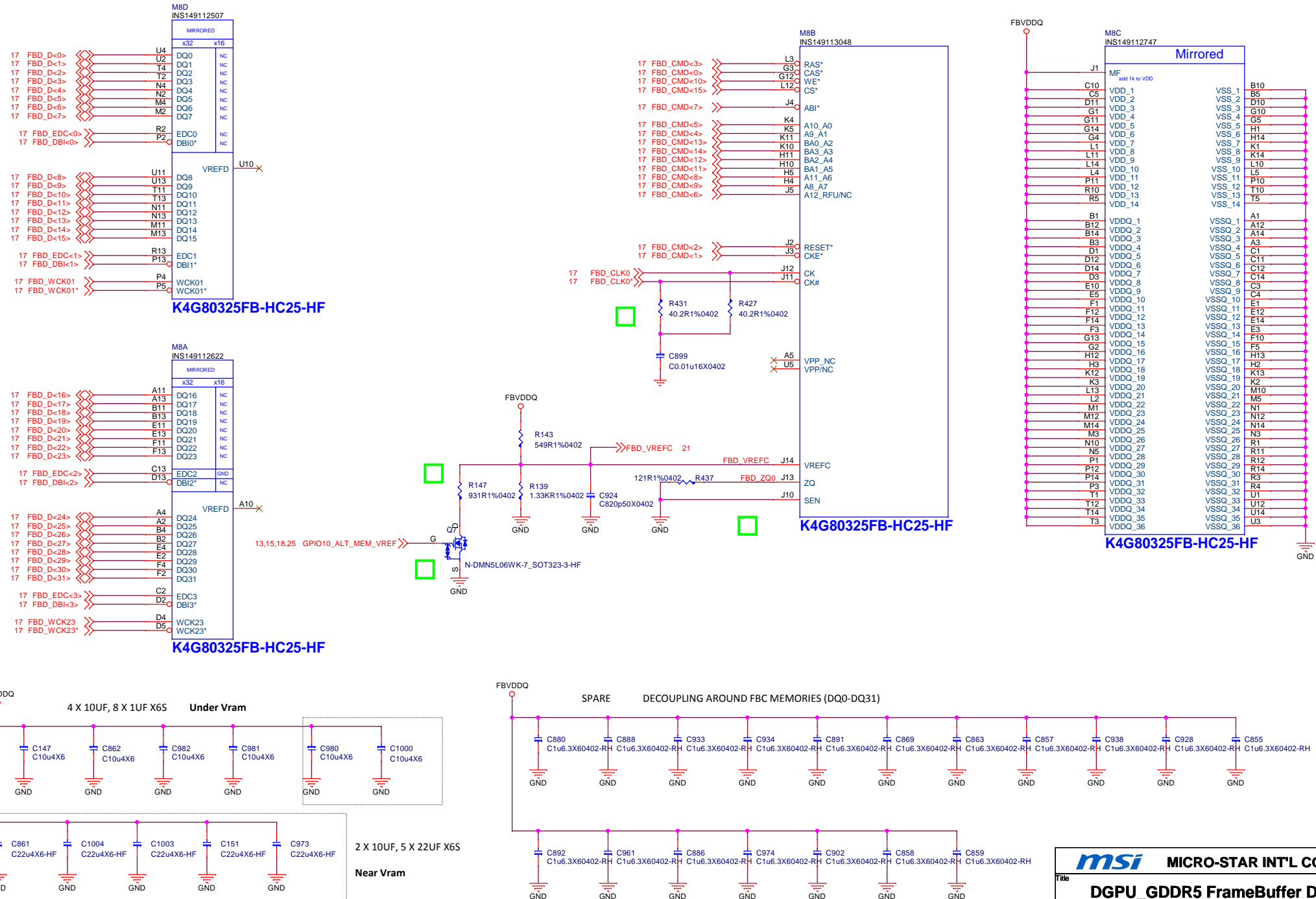
DGPU_GDDR5 FrameBuffer C0



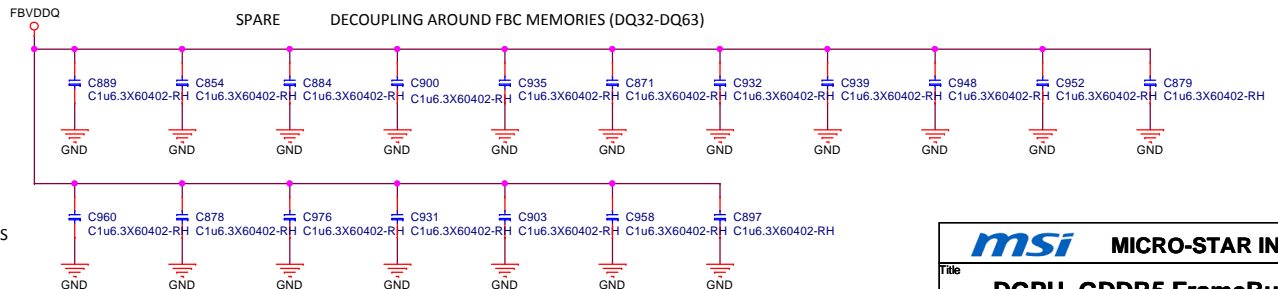
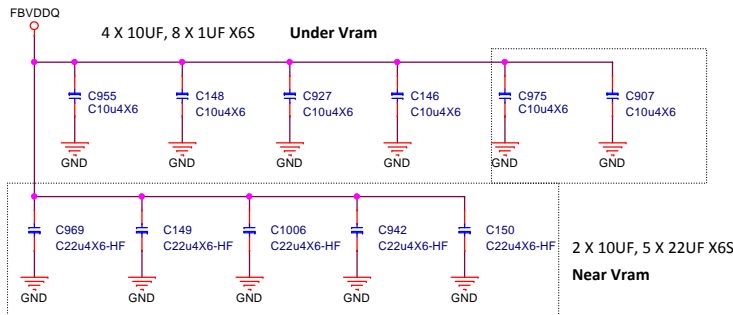
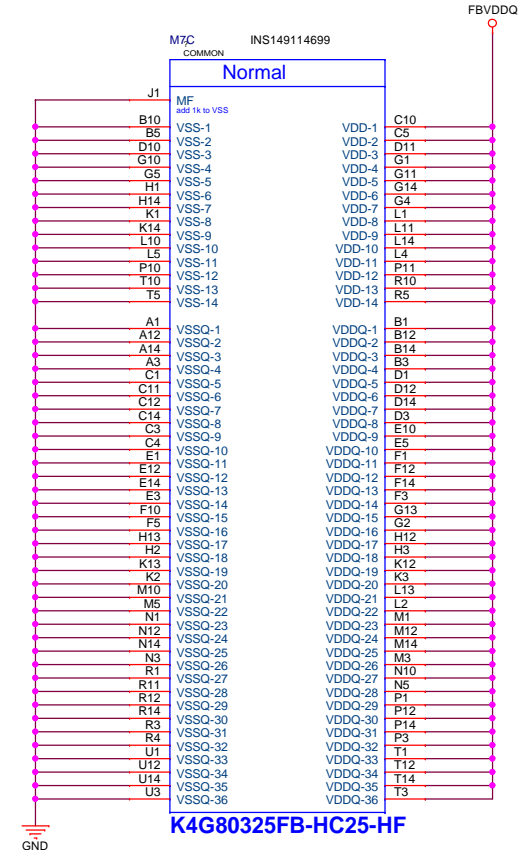
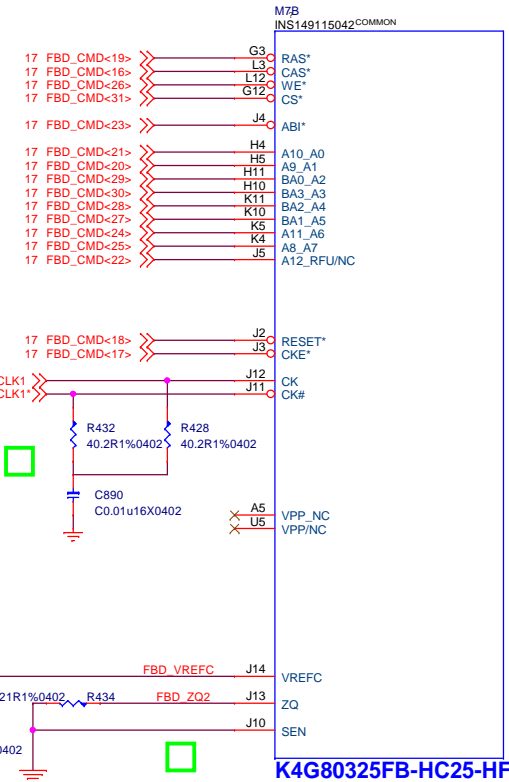
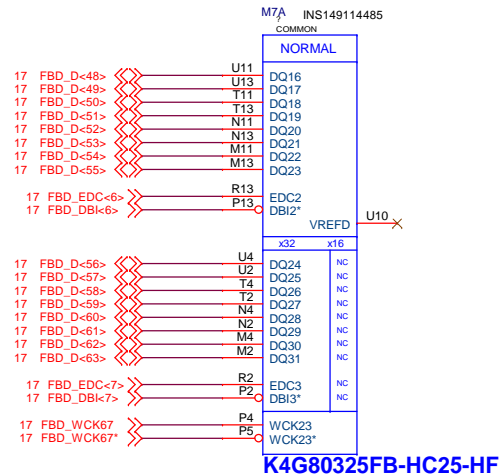
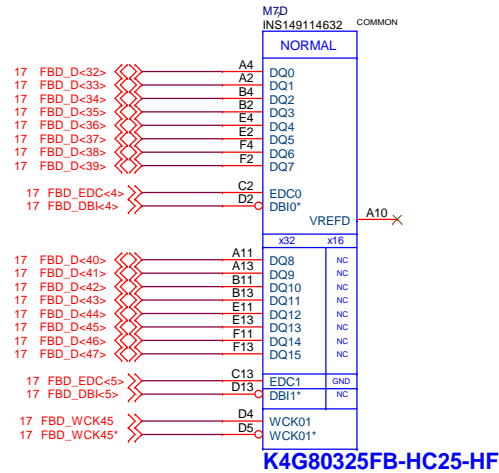
DGPU_GDDR5 FrameBuffer C1



DGPU_GDDR5 FrameBuffer D0



DGPU_GDDR5 FrameBuffer D1



GPU DECOUPLING A

20160819 Change NVVDD5 to NVVDD

1V8_MAIN

1V8_AON

place 1* 0.1uF cap near BA10

Remove CAP

place 1* 0.1uF cap for BB14 and BC14 to share

		DG Page 116	CRB
NVVDD	Under GPU	49 X 1uF(0402 X6S) 11 X 10uF(0603 X6S) 4 X22uF(0805 X6S) 2 X 47uF (0805 X6S)	49 X 1uF(X7R 6.3V) 11 X 10uF(X6S 6.3V) 4 X22uF(X6S 6.3V) 2 X 47uF (X6S 4V)
	Near GPU	2 X 330uF (Poscap)	2 X 330uF (Poscap) 4 X 100uF (X5R 4V) add
NVVDD5	Under GPU	16 X 1uF(0402 X6S) 4 X 10uF(0603 X6S)	16 X 1uF(X6S 6.3V) 4 X 10uF(0603 X6S 4V)
	Near GPU	1 X 47uF (0805 X6S) 1 X 330uF (Poscap)	1 X 47uF (0805 X5R 4V) 1 X 330uF (AL-Polymer)

		DG Page 117	CRB
1V8_MAIN	Under GPU	7 X 0.1uF(0402)	7 X 0.1uF(0402 X7R)
	Near GPU	3 X 1uF (0402) 3 X 4.7uF (0603)	3 X 1uF (0603 X7R) 3 X 4.7uF (0603 X6S)
1V8_AON	Under GPU	2 X 0.1uF(0402)	2 X 0.1uF(0402 X7R)
	Near GPU	1 X 1uF (0402) 1 X 4.7uF (0603)	1 X 1uF (0603 X7R) 1 X 4.7uF (0603 X6S)

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File: DGPU_GPU DECOUPLING A

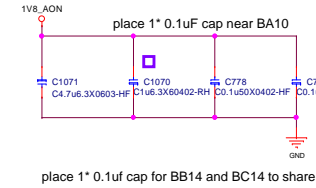
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Document Number: MS-16K71

Date: Thursday, January 18, 2018

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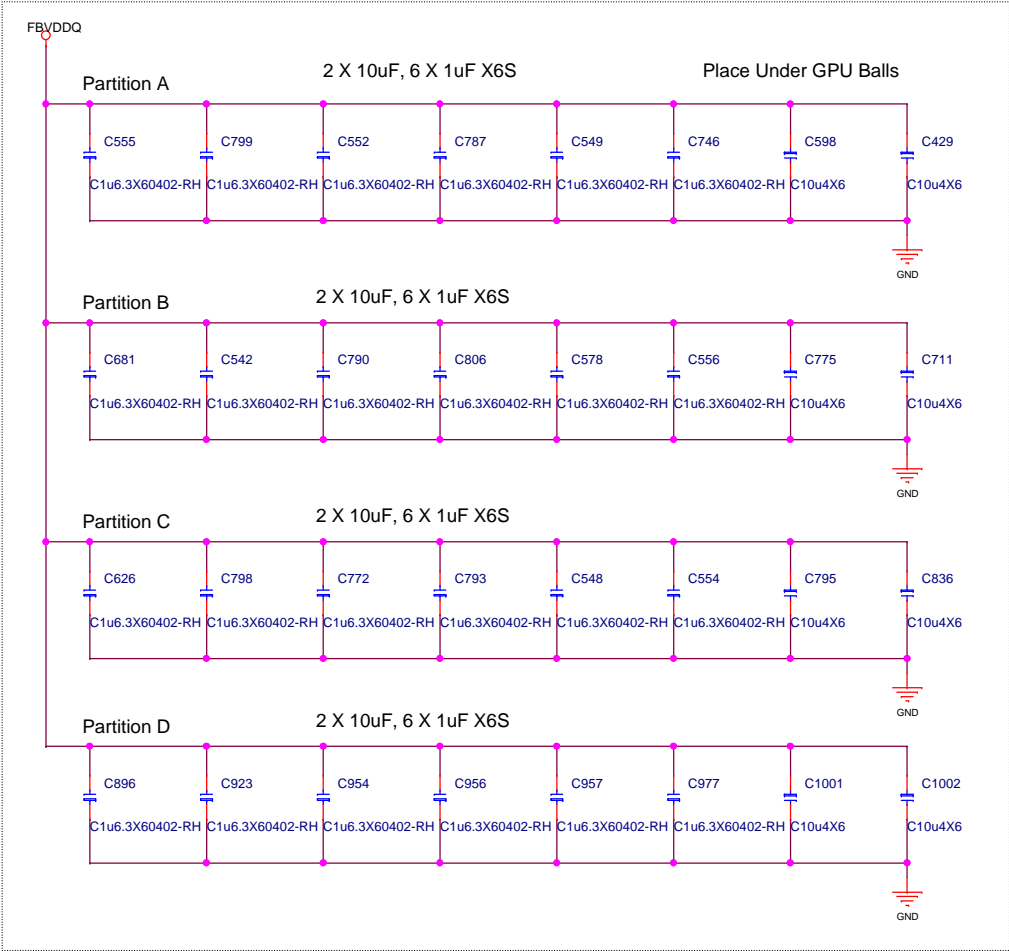
Rev: 10



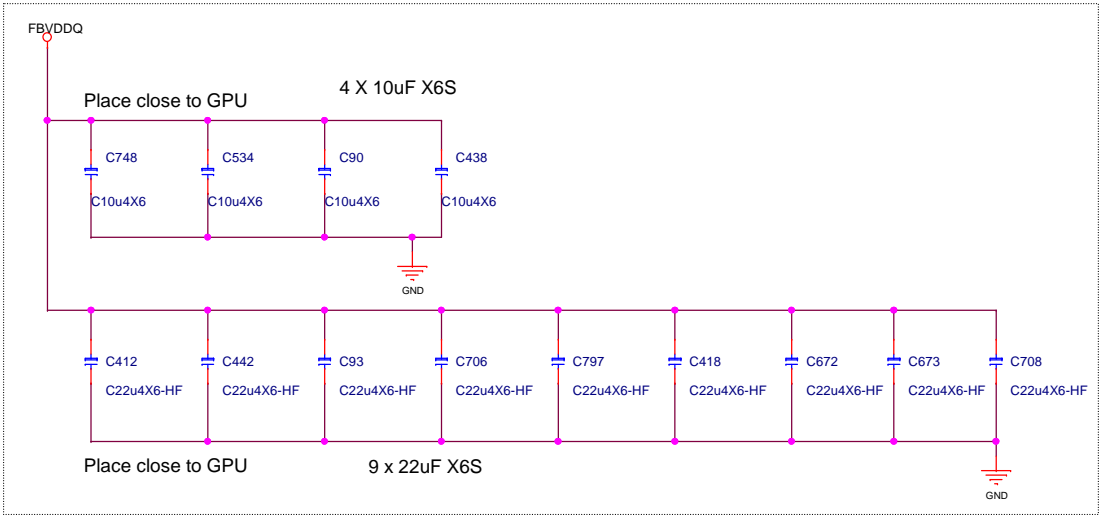
		DG Page 117	CRB
1V8_MAIN	Under GPU	7 X 0.1uF(0402)	7 X 0.1uF(0402 X7R)
	Near GPU	3 X 1uF (0402) 3 X 4.7uF (0603)	3 X 1uF (0603 X7R) 3 X 4.7uF (0603 X6S)
1V8_AON	Under GPU	2 X 0.1uF(0402)	2 X 0.1uF(0402 X7R)
	Near GPU	1 X 1uF (0402) 1 X 4.7uF (0603)	1 X 1uF (0603 X7R) 1 X 4.7uF (0603 X6S)

FBVDDQ

GPU DECOUPLING B

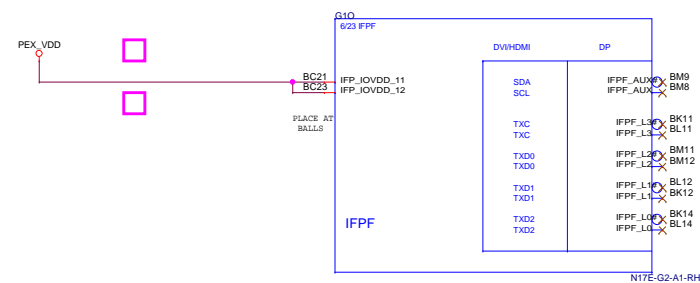
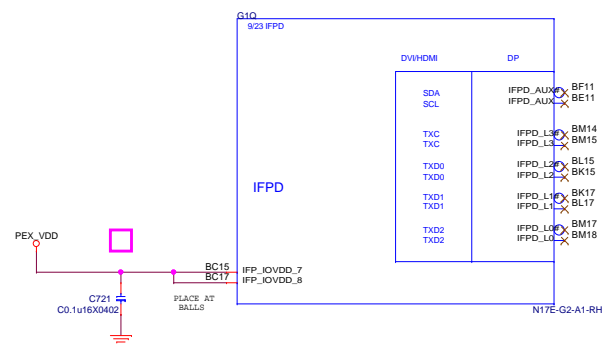
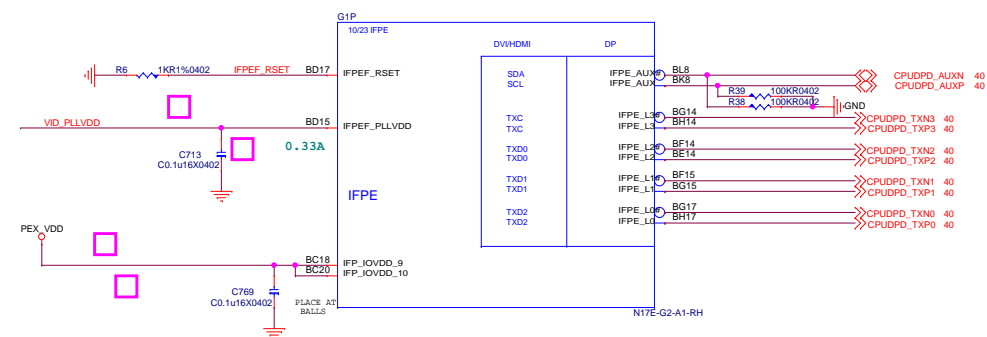
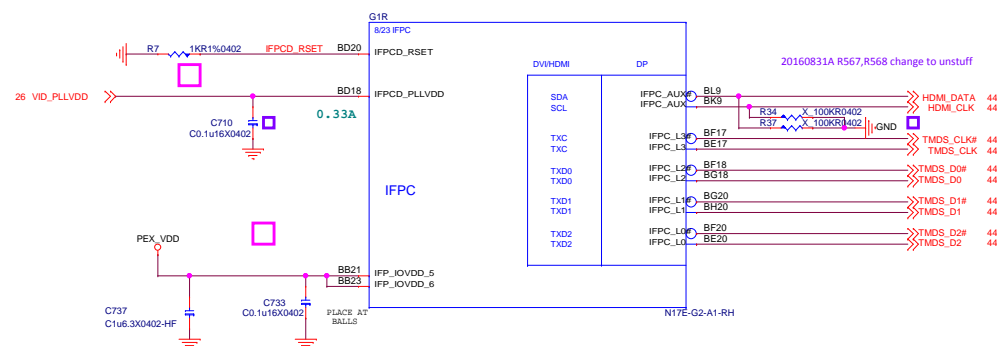
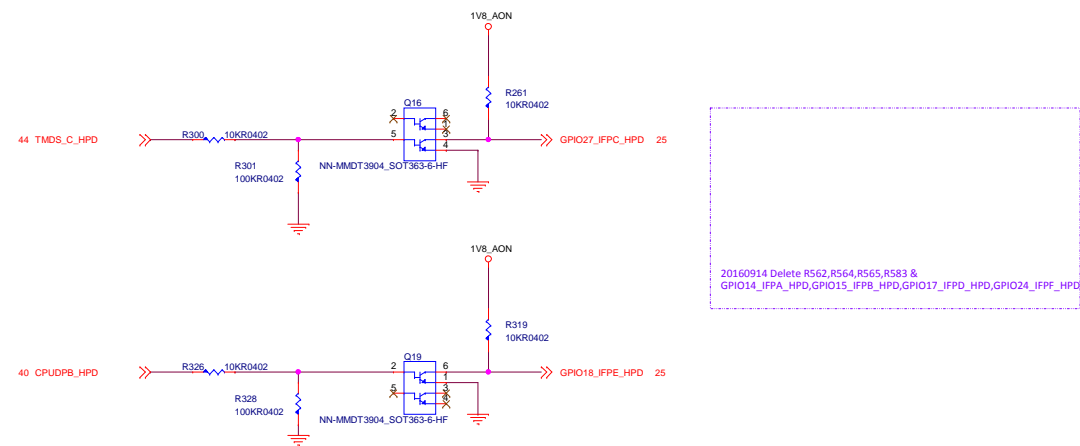
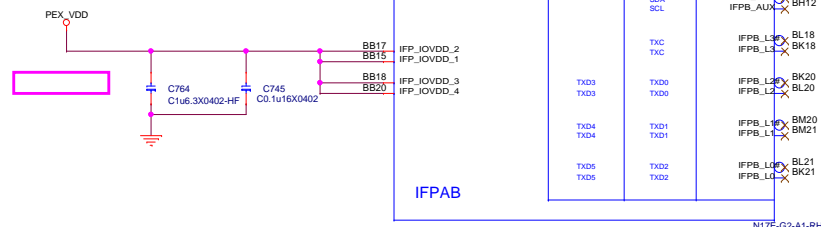


		DG Page 116	CRB
FBVDDQ (GPU side)	Under	24 X 1uF(0402 X6S) 5 X 10uF(0603 X6S)	24 X 1UF(0402 X6S 6.3V) 5 X 10uF(X6S 4V)
	Near	7 X 10uF(0603 X6S) 9 X 22uF(0603 X6S)	7 X 10uF(0603 X6S 4V) 9 X 22UF(0603 X6S 4V)



DG Page 117	Under GPU	Near GPU
IFP_IOVDD	12 X 0.1uF(0402 X6S)	3 X 4.7uF (0603) 3 X 1uF (0402)

0.305A for each IFP_IOVDD in use

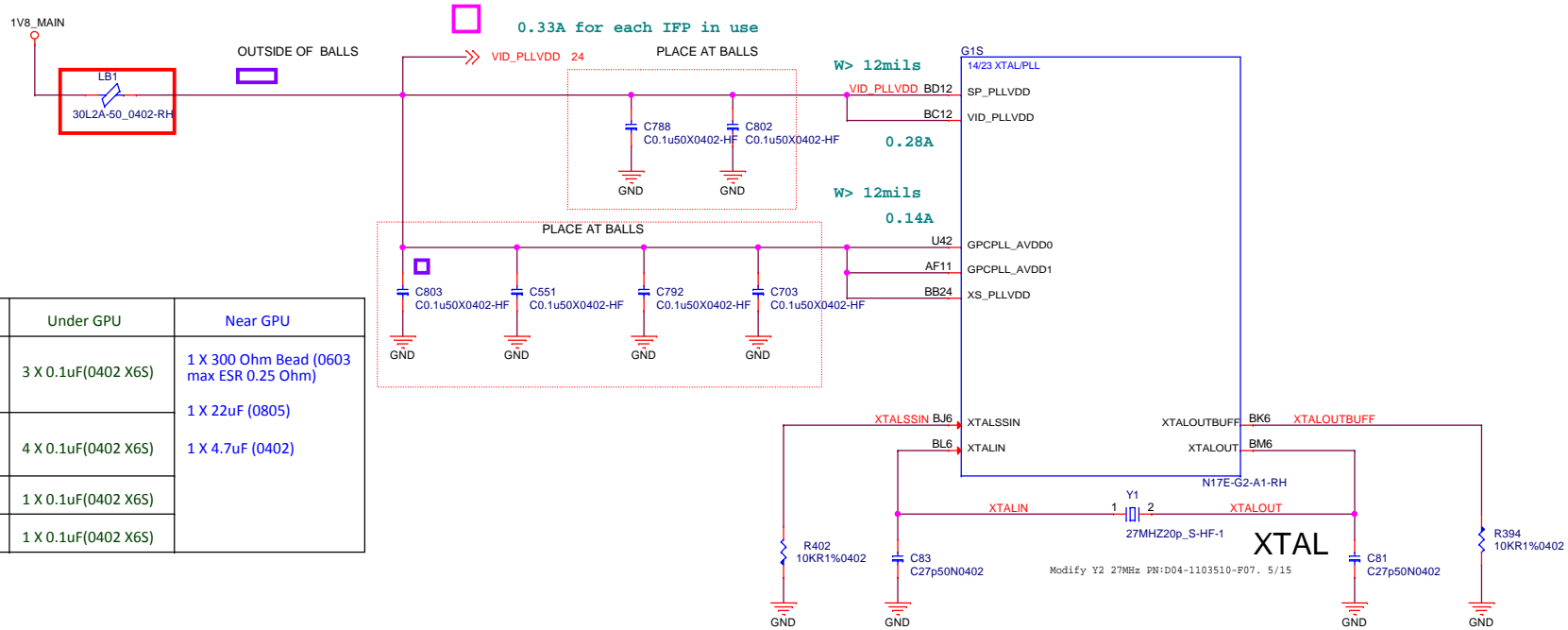


	20160831A Delete GC62.0 circuit (R59,R60,R63,R64,C107,U6)
P0/GPIO24_IFFP_HPD	



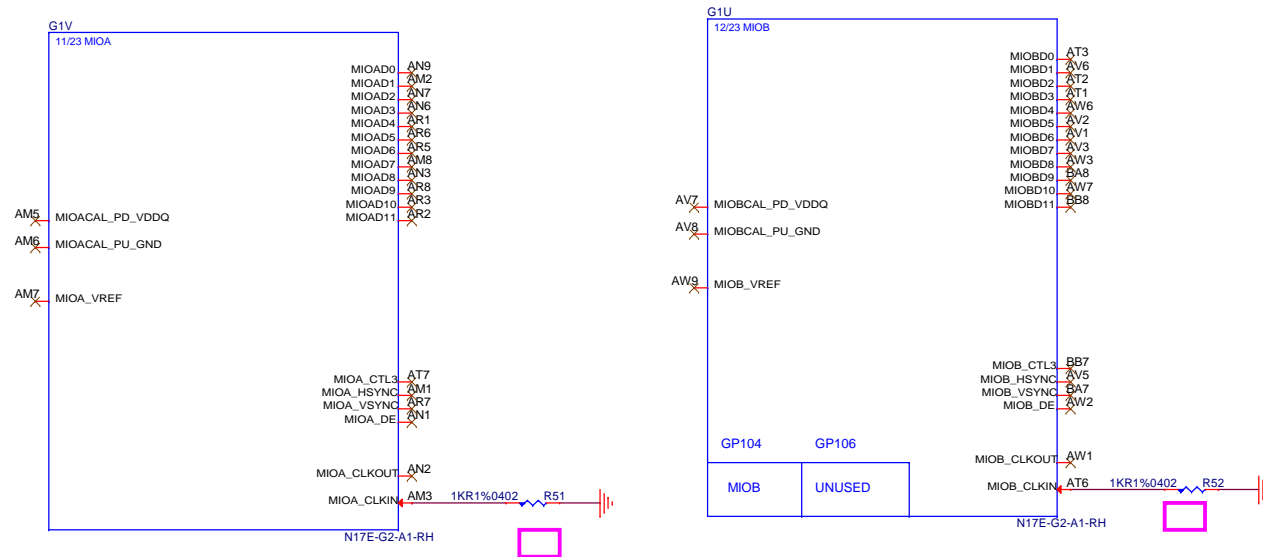
20160704 Add C1041 22uF & C1038 4.7uF & C1040 0.1uF for VID_PLLVDD
20160912A Delete C1041 & C1038

DGPU MIO & XTAL

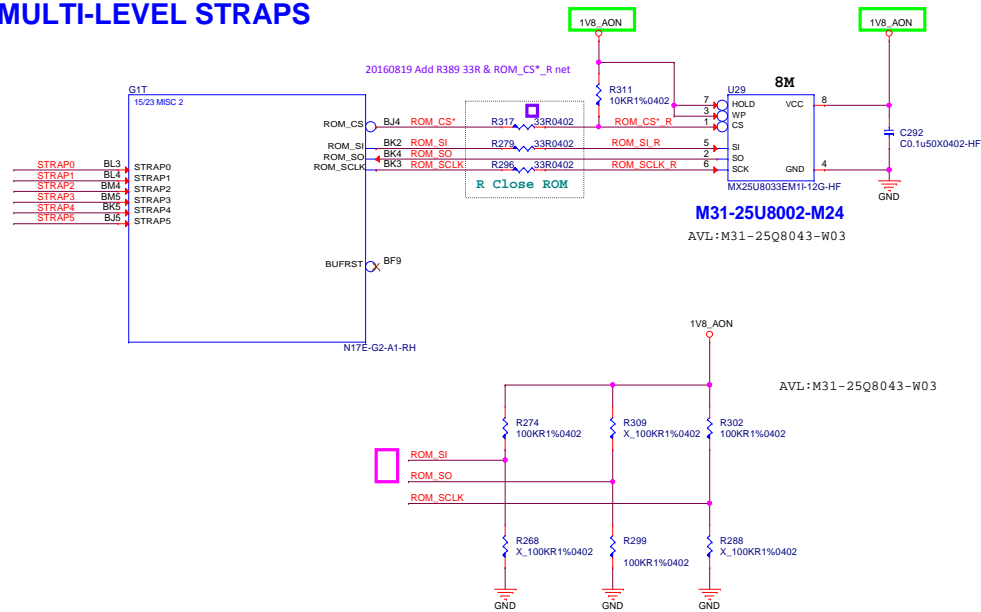


DG Page 117	Under GPU	Near GPU
IFPAB_PLLVDD IFPCD_PLLVDD IFPEF_PLLVDD	3 X 0.1uF(0402 X6S)	1 X 300 Ohm Bead (0603 max ESR 0.25 Ohm) 1 X 22uF (0805)
GPCPLL_AVDDx XS_PLLVDD	4 X 0.1uF(0402 X6S)	1 X 4.7uF (0402)
SP_PLLVDD	1 X 0.1uF(0402 X6S)	
VID_PLLVDD	1 X 0.1uF(0402 X6S)	

Multi-use IO(MIO) Interface



ROM, MULTI-LEVEL STRAPS



STRAP2	STRAP1	STRAP0	RAMCFG[2:0]	
L	L	L	00000	V
L	L	H	00001	V
L	H	L	00010	
L	H	H	00011	
H	H	L	00110	
H	H	H	00111	

H=High :Tied to 1.8V
M=Middle:Tied to 0.9V
L=Low :Tied to 0V

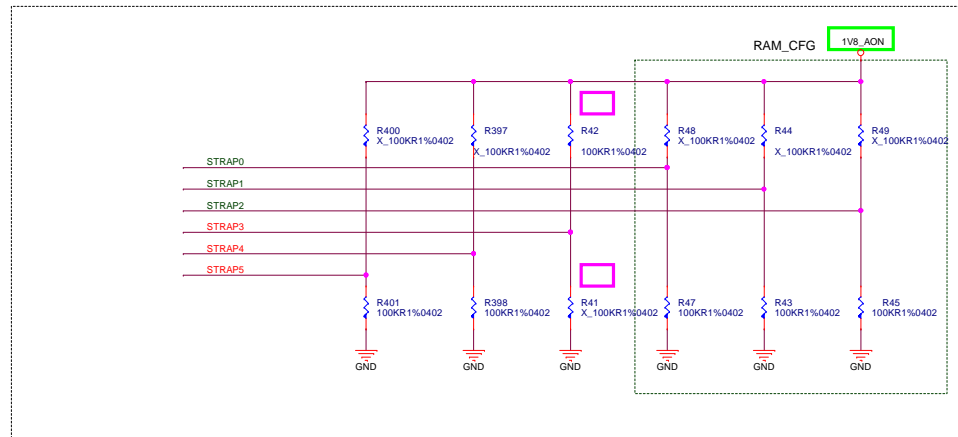
256M*32
SAMSUNG 0X0
MICRON 0X1
HYNIX 0X2

ROM_SO	ROM_SI	ROM_SCLK	SOR_EXPOSED[3:0]	1:ENABLE 0:DISABLE
L	L	L	1111 DEFAULT	SOR0/1/2/3 ENABLE
L	L	H	1110	
L	H	L	1101	
L	H	H	1100	V
H	L	L	1011	
H	L	H	1010	
H	H	L	1001	
H	H	H	1000	
L	L	M	0111	
L	M	L	0110	
L	M	H	0101	
L	H	M	0100	
H	L	M	0011	
H	M	L	0010	
H	M	H	0001	
H	H	M	0000	

SOR_EXPOSED :GPU AUDIO SETTING

STRAP5	STRAP4	STRAP3	SMB_ALT_ADDR	DEVID_SEL	PCIE_CFG	VGA_DEVICE
M	H	H	1	1	1	1
M	H	L	1	1	1	0
M	L	H	1	1	0	1
M	L	L	1	1	0	0
L	H	M	1	0	1	1
L	M	H	1	0	1	0
L	M	L	1	0	0	1
L	L	M	1	0	0	0
H	H	H	0	1	1	1
H	H	L	0	1	1	0
H	L	H	0	1	0	1
H	L	L	0	1	0	0
L	H	H	0	0	1	1
L	H	L	0	0	1	0
L	L	H	0	0	0	1 DEFAULT
L	L	L	0	0	0	0

1:SMB_ALT_ADDR ENABLE (DUAL GPU)
0:SMB_ALT_ADDR DISABLE (SINGLE GPU)
1:DEVID_SEL REBRAND
0:DEVID_SEL ORIGINAL
1:PCIE_CFG LOW SWING POWER
0:PCIE_CFG HIGH SWING POWER
1:VGA_DEVICE ENABLE
0:VGA_DEVICE DISABLE

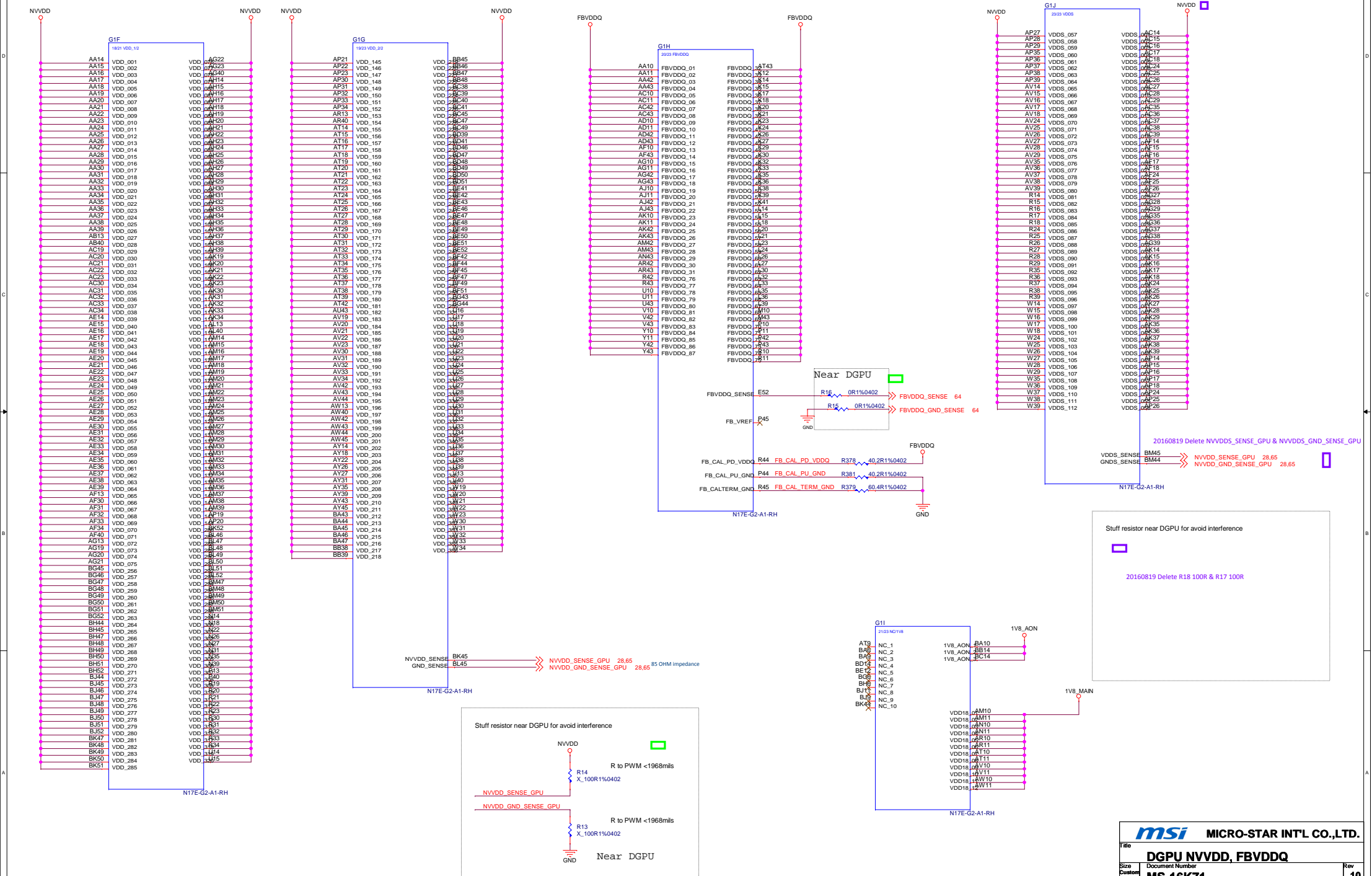


DEFAULT SETTING	<input checked="" type="checkbox"/> 5010	256M*32
SAMSUNG	M12-8032535-S02	
	X_K4G80325FB-HC25-HF	
MICRON	<input type="checkbox"/> 5010	256M*32
	M12-2563215-M30	
	X_MT51J256M32HF-80-A-HF	

20160817 Delete V_TOP3 M12-5GQ4H45-H23 and V_TOP4 M12-41325D5-502

GPU NVVDD, FBVDDQ

20160819 Change VDDS connect to NVVDD



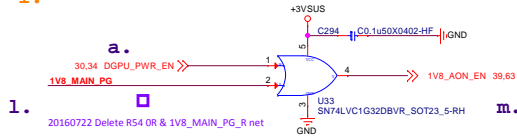


nVIDIA Power Sequence Control

Power on = 1V8_AON -> 1V8_MAIN -> 3V3_NV -> NVVDD -> PEX_VDD -> FBVDDQ -> DGPUPWRGD

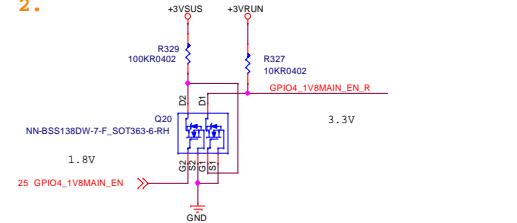
Power off = DGPUPWREN->(PEX_VDD->NVVDDQ->3V3_NV)->FBVDDQ->1V8_MAIN->1V8_AON

1.

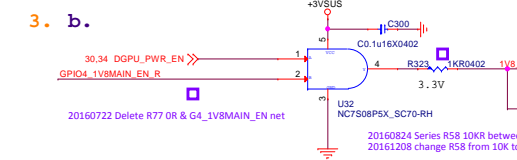


1. 20160722 Delete R54 OR & 1V8_MAIN_PG_R net

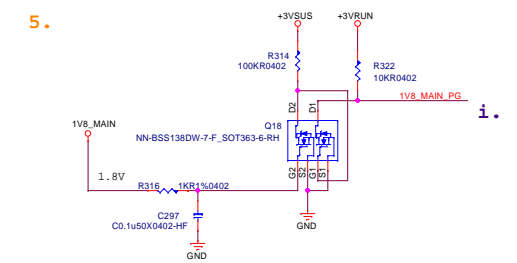
2.



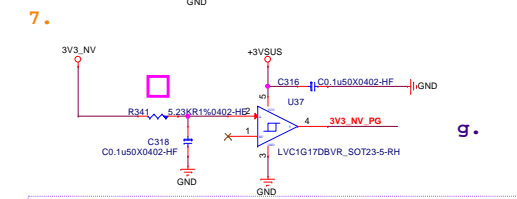
3. b.



5.



7.

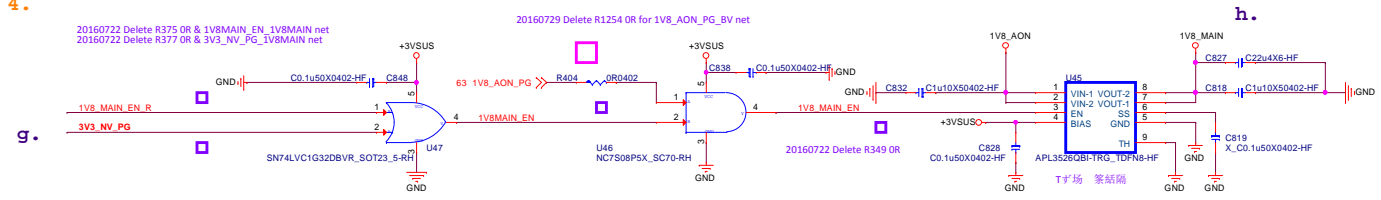


1V8_AON Power Good By Voltage and delay

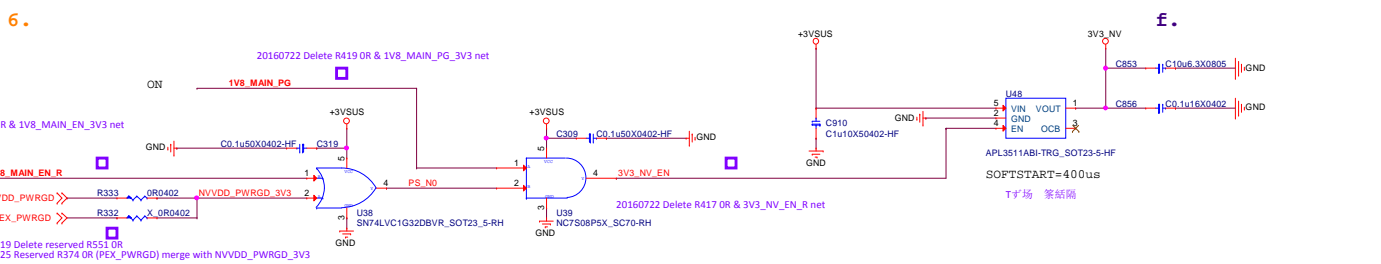
20160729 Delete U74 C2892 C8601 R605 for 1V8_AON_PG_BV ent

The ramp time for any rail must be more than 40us and is recommended to be less than 2ms
From 1V8_MAIN_EN to PEX_VDD must NOT exceed 4ms

4.



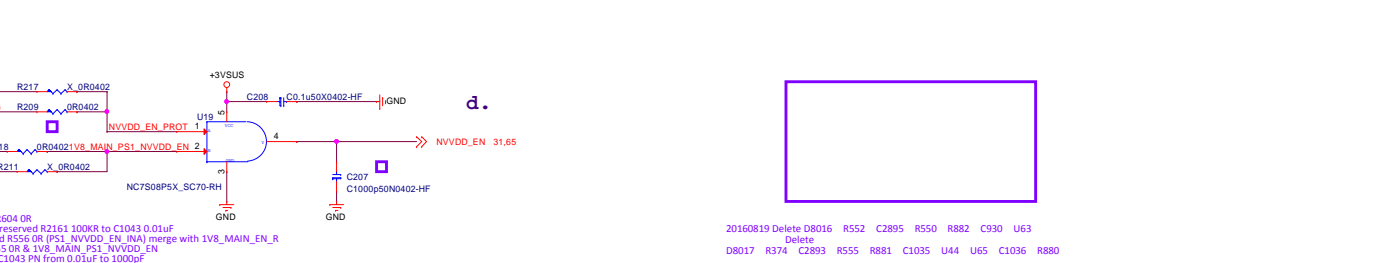
6.



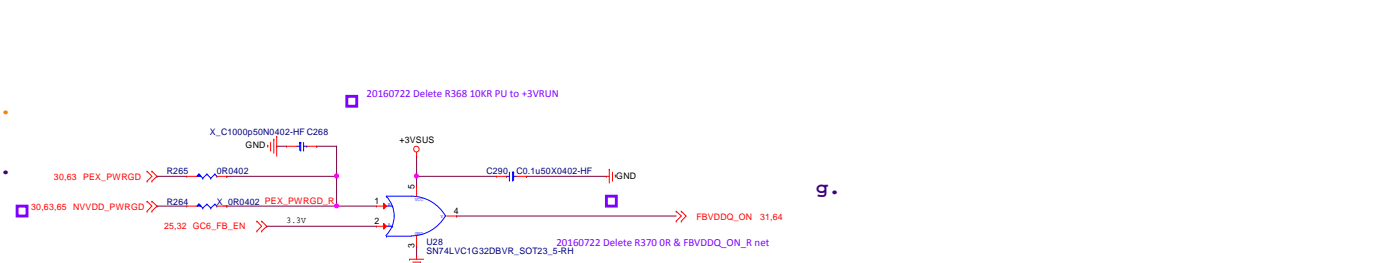
NVVDD Power Enable

The propagation delay between 1V8_MAIN_EN and the NVVDD_EN needs to be less than 300us during both power up and power down

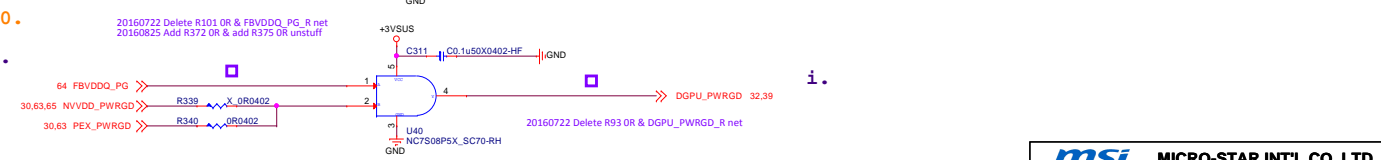
8.



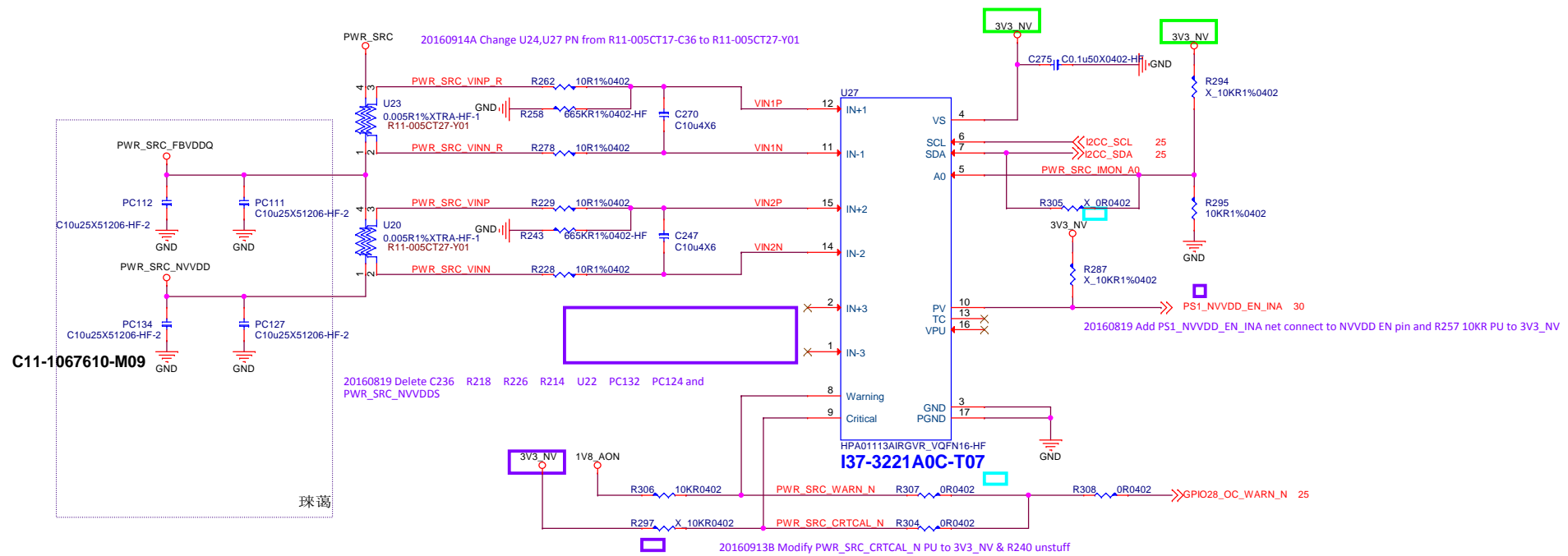
9.



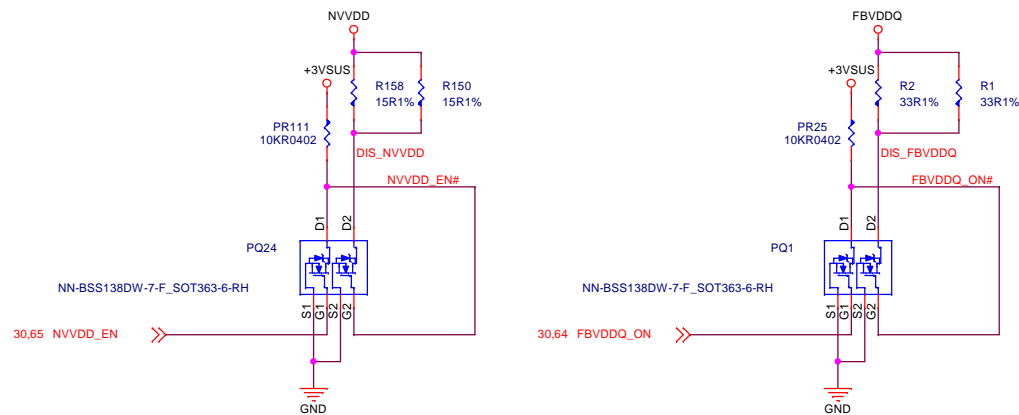
10.



DGPU_Power Control

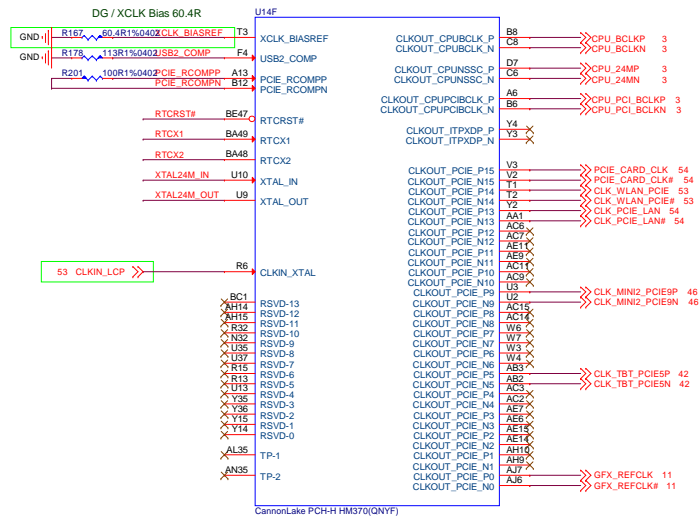


Discharge

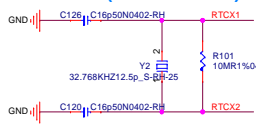


PEX_VDD ず场 策4ms
 3V3_AON ず场 策 2ms
 1V8AON ず场 策2ms
 1V8_MAIN ず场 策320us

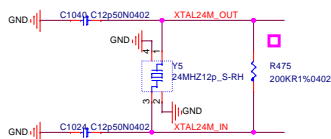
HM370 (RTC/PCIE_Clock/Clock/RSVD)



RTC Block(Close to PCH)

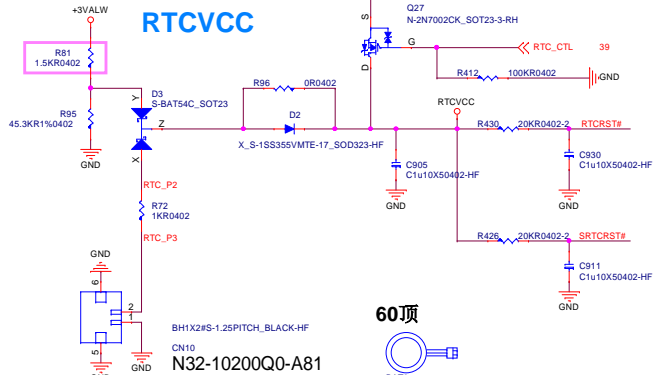


24MHz Clock



20170828 R2175 change to 200K
to follow DG and CRB

RTCVCC

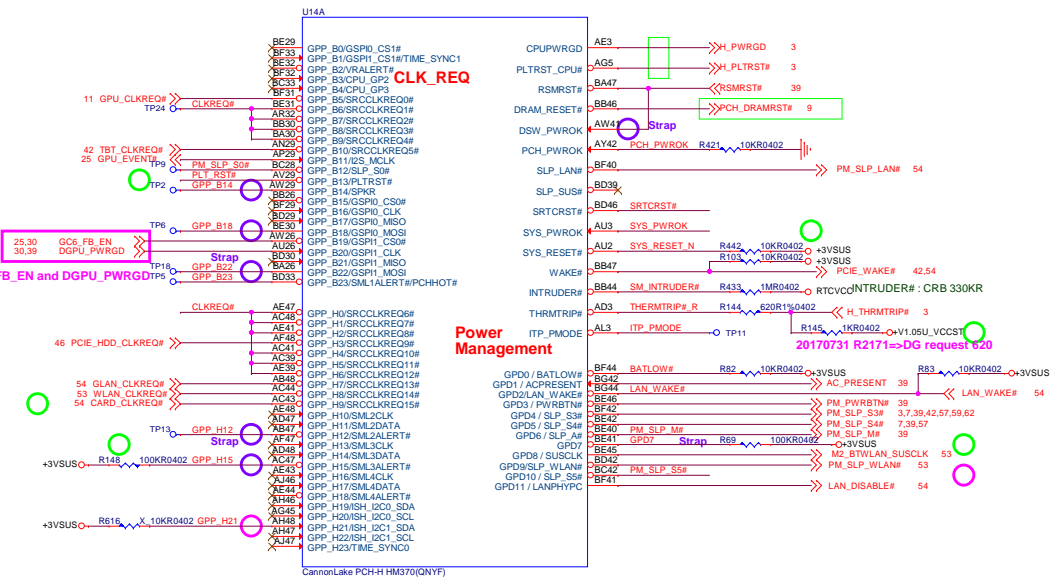


60顶



BAT2
BCR2032H11.0VMAXB
D06-0106601-K26

HM370 (CLKREQ/ACPI)



Functional Strap Definitions

SPKR / GPP_B14

The signal has a weak internal pull-down.
0 = Disable Top Swap mode. (Default)

GSPI0_MOSI / GPP_B18

The signal has a weak internal pull-down.
0 = Disable No Reboot mode. (Default)
1 = Enable No Reboot mode

GSP11_MOSI / GPP_B22

This Signal has a weak internal pull-down	
Bit 6 Boot BIOS	Destination
0	SPI (Default)
1	LPC

SML1ALERT# / PCHHOT# / GPP_B23

This signal has an internal pull-down.

GPP H12

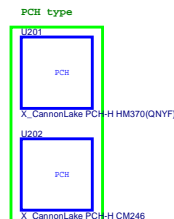
This signal has a weak internal pull-down

GPP_H15

External pull-up is required. Recommend 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.

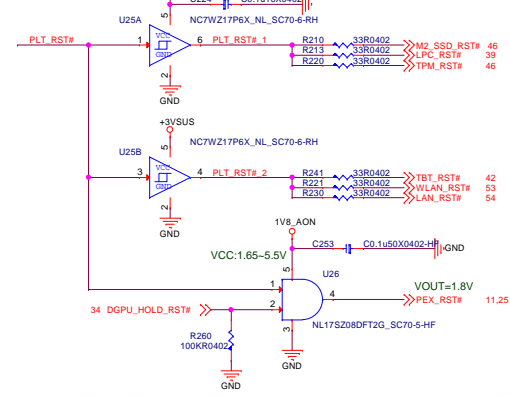
GPPD7
External pull-up is required. Recommend 100K.
This strap should sample HIGH. There should NOT be any on-board device driving it to opposite direction during strap sampling

DG/ RTC Well Input Strap

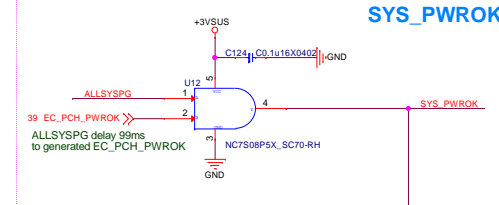
RSMRST# & DSW_PWROK, PCH_PWROK : PD
RTCRST#, SRTCRST#, INTRUDER# : PU

PLT_RST#

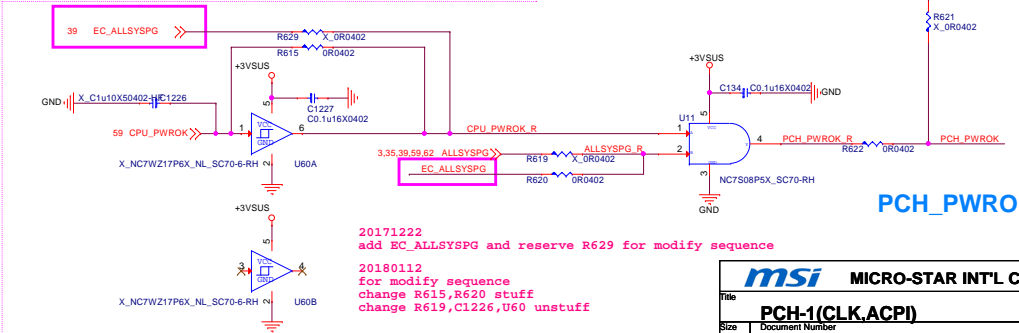
Strap pin
GPP_H21 pull-up for 24 MHz XTAL operation for PCH-LF
20171005 change to unstuff for PCH-H



SYS_PWROK



PCH_PWROK



```
20171222
add EC_ALLSYSPG and reserve R629 for modify sequence
```

```
20180112
for modify sequence
change R615,R620 stuff
change R619,C1226,U60 unstuff
```


HM370 (DMI/PCIE/USB3.1/USB2.0/CNVi)

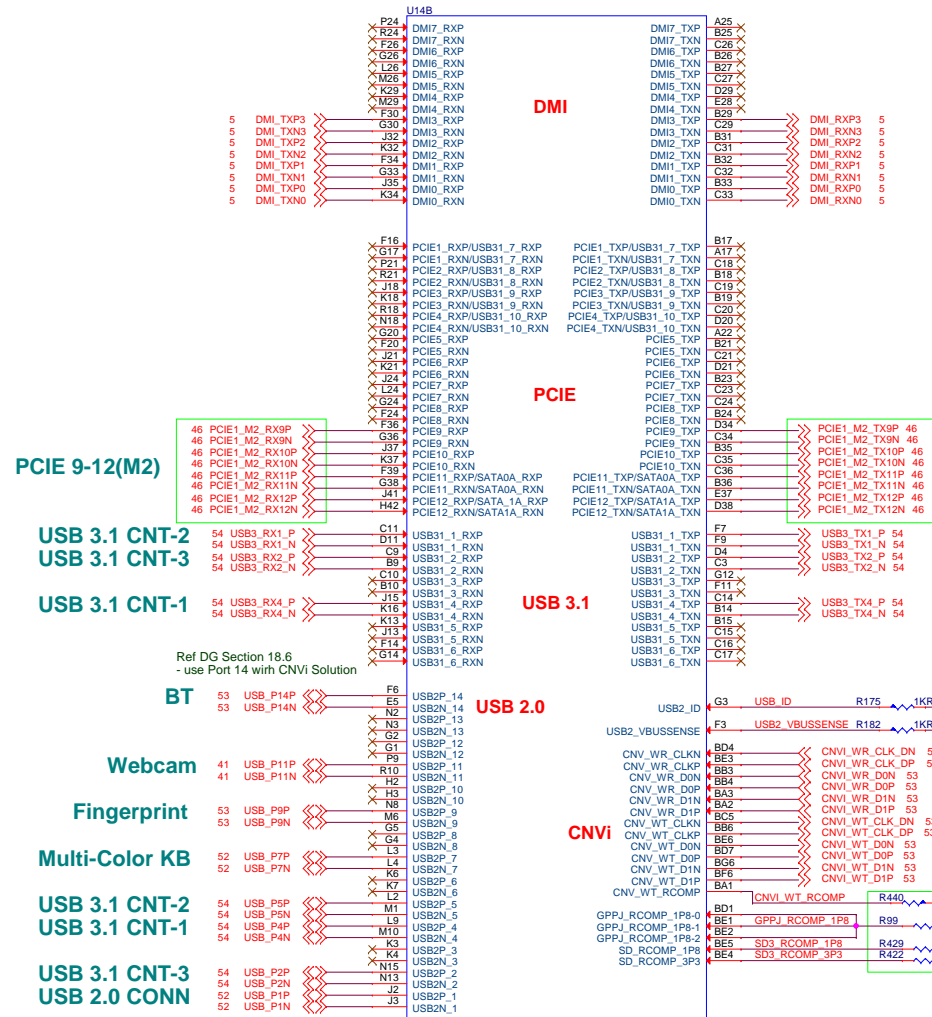


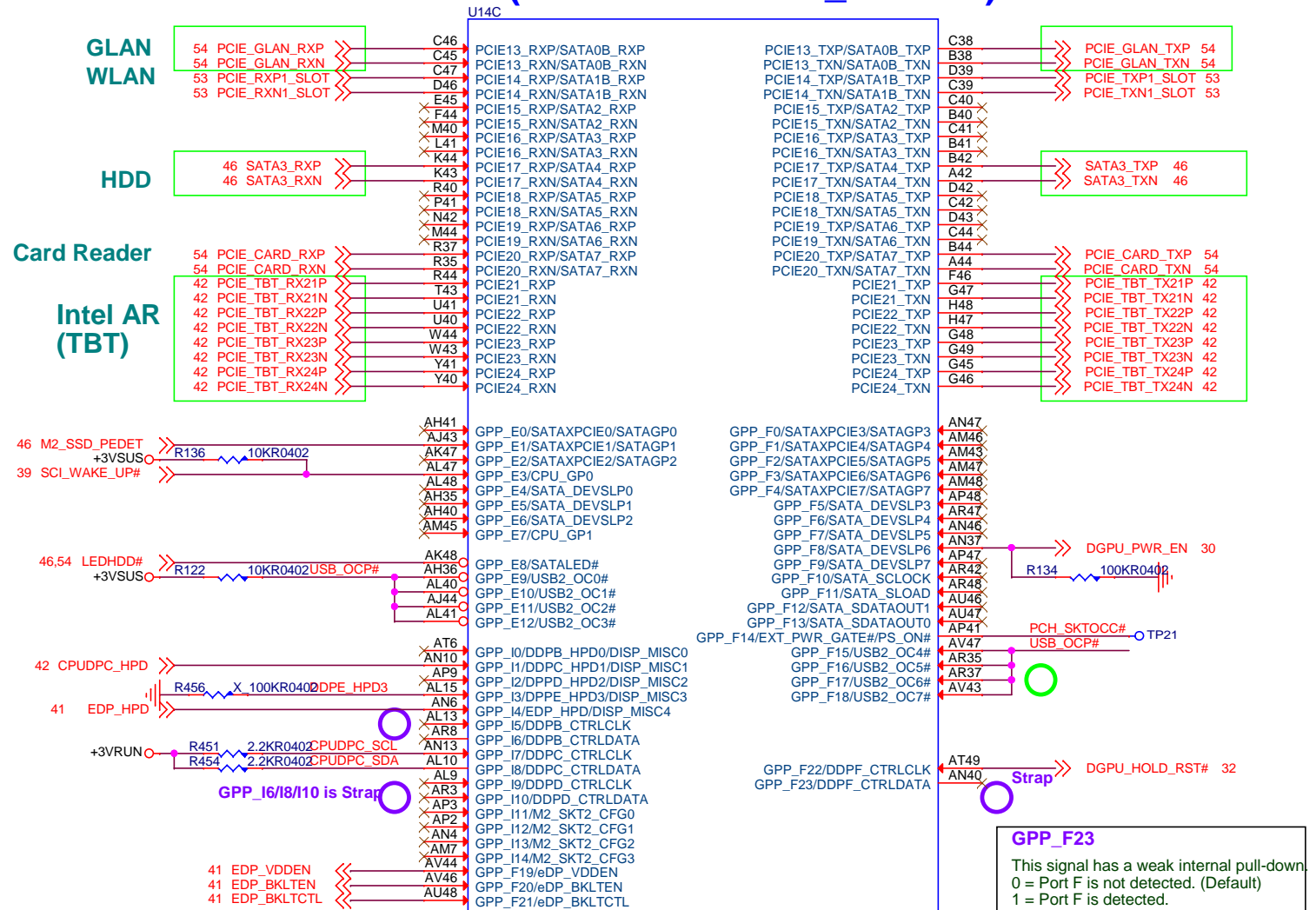
Figure 14-1. High Speed I/O (HSIO) Lane Multiplexing in PCH-H

Flex I/O Lane	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29
High Speed I/O (HSIO) Type and Lane	USB3.1 Gen1/Gen2 #1	USB3.1 Gen1/Gen2 #2	USB3.1 Gen1/Gen2 #3	USB3.1 Gen1/Gen2 #4	USB3.1 Gen1/Gen2 #5	USB3.1 Gen1/Gen2 #6	USB3.1 Gen1 #7	USB3.1 Gen1 #8	USB3.1 Gen1 #9	USB3.1 Gen1 #10	PCIe* #5	PCIe* #6	PCIe* #7	PCIe* #8	PCIe* #9	PCIe* #10	PCIe* #11	PCIe* #12	PCIe* #13	PCIe* #14	PCIe* #15	PCIe* #16	PCIe* #17	PCIe* #18	PCIe* #19	PCIe* #20	PCIe* #21	PCIe* #22	PCIe* #23	PCIe* #24
							PCIe* #1		PCIe* #2	PCIe* #3		GBE			GBE		SATA 0a	SATA 1a	GBE	SATA 1b	SATA 2	SATA 3	SATA 4	SATA 5						
Intel® RST Support											No Support		No Support		Yes			No Support			Yes			Yes						

SKU	USB3.1 Gen1/Gen2 #1	USB3.1 Gen1/Gen2 #2	USB3.1 Gen1/Gen2 #3	USB3.1 Gen1/Gen2 #4	USB3.1 Gen1/Gen2 #5	USB3.1 Gen1/Gen2 #6	USB3.1 Gen1/Gen2 #7	USB3.1 Gen1/Gen2 #8	USB3.1 Gen1/Gen2 #9	USB3.1 Gen1/Gen2 #10	PCIe #5	PCIe #6	PCIe #7	PCIe #8	PCIe #9	PCIe #10	PCIe #11	PCIe #12	SATA 0a	SATA 1a	SATA 1b	SATA 2	SATA 3	SATA 4	SATA 5	PCIe #13	PCIe #14	PCIe #15	PCIe #16	PCIe #17	PCIe #18	PCIe #19	PCIe #20	PCIe #21	PCIe #22	PCIe #23	PCIe #24
HM370	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2
QM370	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2
CM246	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2	Gen1/Gen2

- Added 4 new PCIe 3.0 lanes versus KBL-H platform.
- GbE LAN removed from lane 10 and SATA #0/#1 option moved from lanes 15/16 to 19/20 to better balance PHY clocking.

HM370(SATA/PCIE/USB_OC/DDI)



CannonLake PCH-H HM370(QNYF)

Functional Strap Definitions

SMBALERT# / GPP_C2

This signal has a weak internal pull-down.
0 = Disable Intel ME Crypto Transport Layer Security (TLS) cipher suite (no confidentiality). (Default)

SML0ALERT# / GPP_C5

This signal has a weak internal pull-down.
0 = LPC is selected for EC. (Default)
1 = eSPI is selected for EC.

HDA_SDO

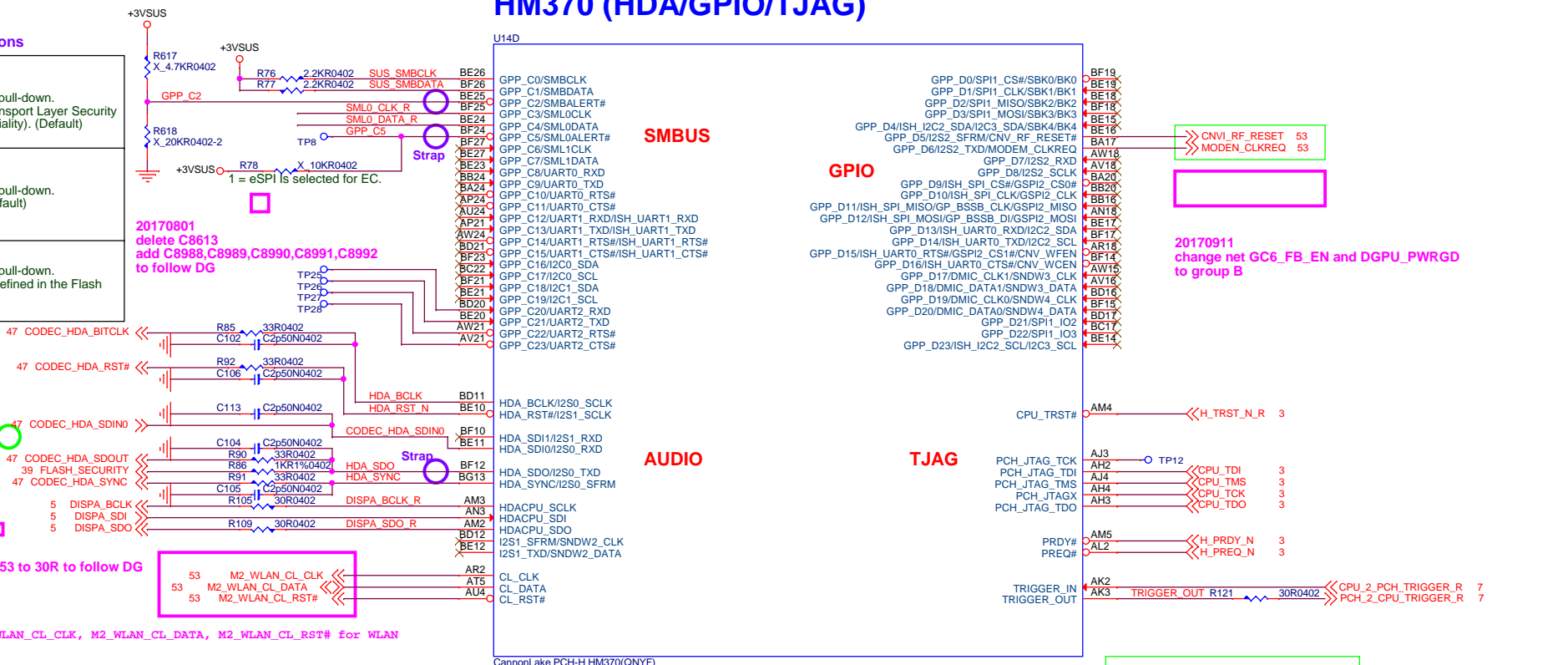
This signal has a weak internal pull-down.
0 = Enable security measures defined in the Flash Descriptor. (Default)

20170801 delete C8613
add C8988, C8989, C8990, C8991, C8992 to follow DG

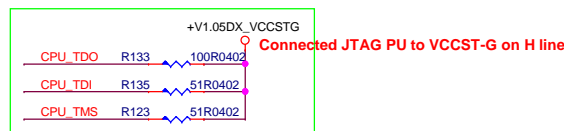
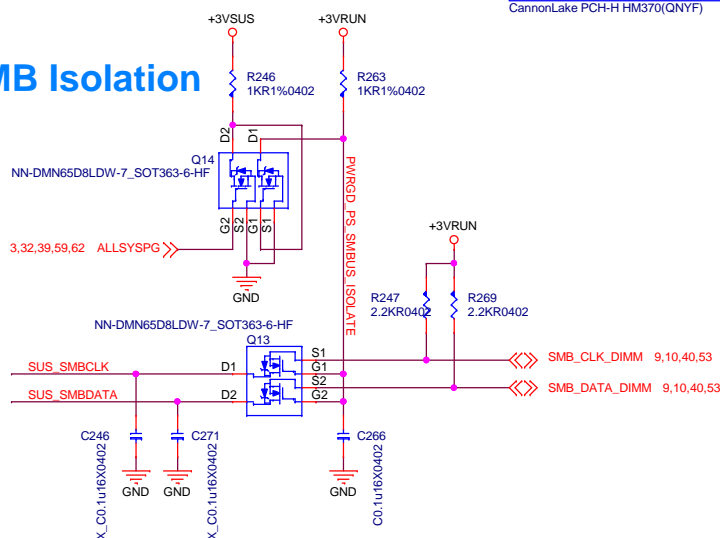
20170731 change R2352 and R2353 to 30R to follow DG

2016012 Add M2_WLAN_CL_CLK, M2_WLAN_CL_DATA, M2_WLAN_CL_RST# for WLAN

HM370 (HDA/GPIO/TJAG)

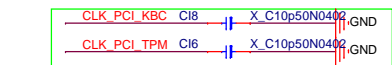


SMB Isolation

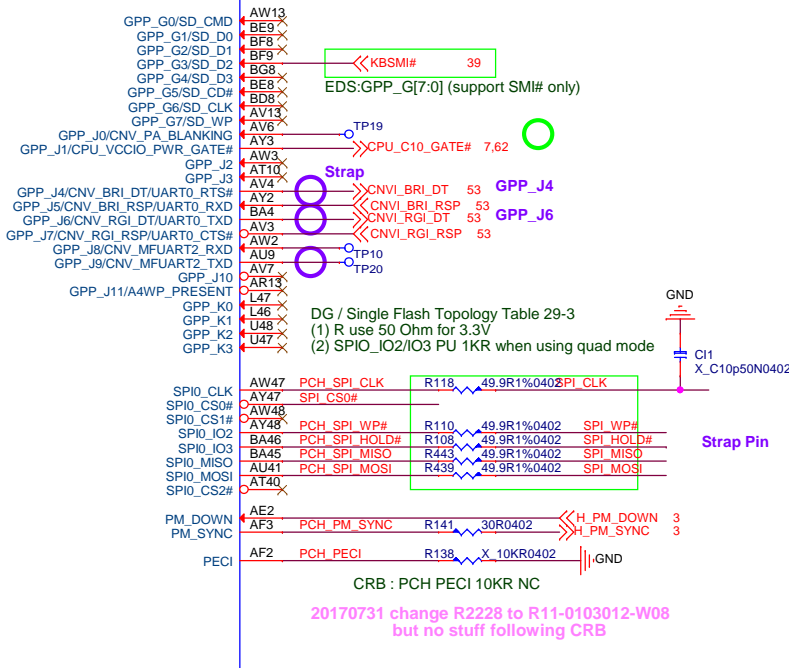
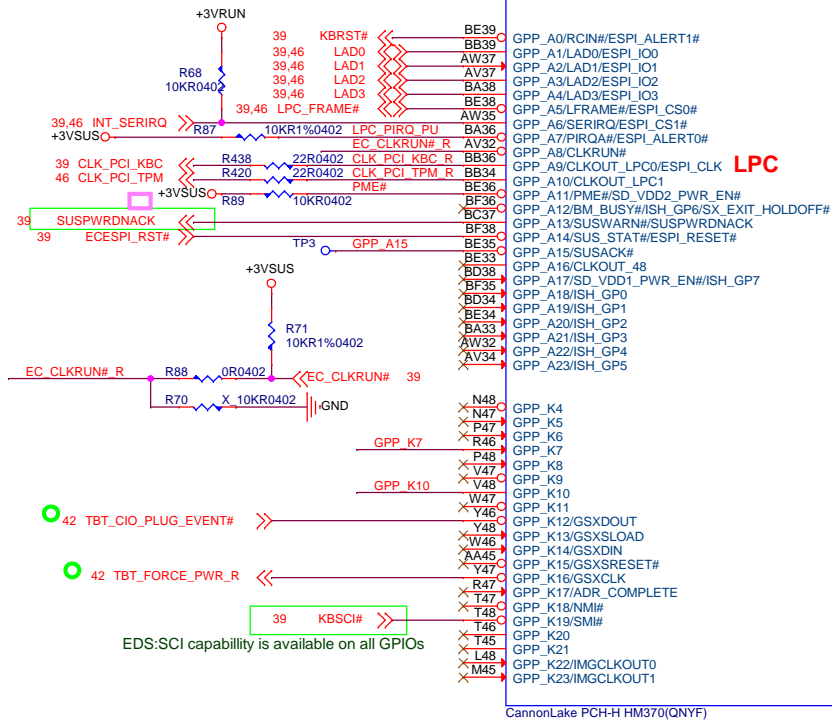


ref DG / Chapter Platform and Test Hooks
CPU_TDO : PU 100R Near CPU (DG : R1)
PU 100R Near PCH (DG : R3)
CPU_TDI : PU 51R Near PCH (DG : R4)
CPU_TMS : PU 51R Near PCH (DG : R5)
CPU_TCK : 51R to GND Near CPU (DG : R2)

20170731 change R2226 unstuff to follow CRB



HM370 (UART/I2C/SPI)



Functional Strap Definitions

GPP_J4

This signal has a weak internal pull-down. An external pull-up is required on this strap since 38.4 MHz XTAL is not supported on the PCH. 0 = 38.4 XTAL frequency selected. (Default) 1 = 24MHz XTAL frequency selected.

GPP_J6

An external pull-up or pull-down is required. 0 = Integrated CNVt enable. 1 = Integrated CNVt disable.

GPP_J9

The signal has a weak internal pull-down 0 = VCCSPI is connected to 3.3V rail 1 = VCCSPI is connected to 1.8V rail

SPI0_I02

External pull-up is required. Recommend 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.

SPI0_I03

External pull-up is required. Recommend 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.

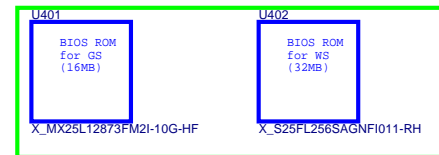
SPI0_MOSI

External pull-up is required. Recommend 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.

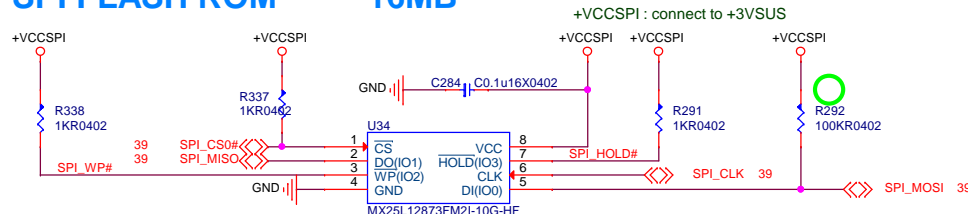
MISO isn't Strap



BIOS ROM type



SPI FLASH ROM 16MB



20170809 U79 change from socket to ROM P/N M31-2512832-M24

M31-2512893-W03
M-IC FLASH,128M(16Mx8bit),10ms,SOIC-8pin(208mil),WINBOND/W25Q128JVSQ,2.7V,3.6V,SPI,,HALOGEN FREE

M31-2512832-M24
M-IC FLASH,128M(16Mx8bit),40ms,SOP-8pin,MXICMX25L12873FM2I-10G(T),2.7V,3.6V,SPI,,HALOGEN FREE

msi MICRO-STAR INT'L CO.,LTD.	
Title	
PCH-5(UART/I2C/SPI)	
Size	Document Number
MS-16K71	
Date:	Thursday, January 18, 2018
Sheet	36 of 80
Rev	10

ref DG / Table 50-6 Decoupling Requirements

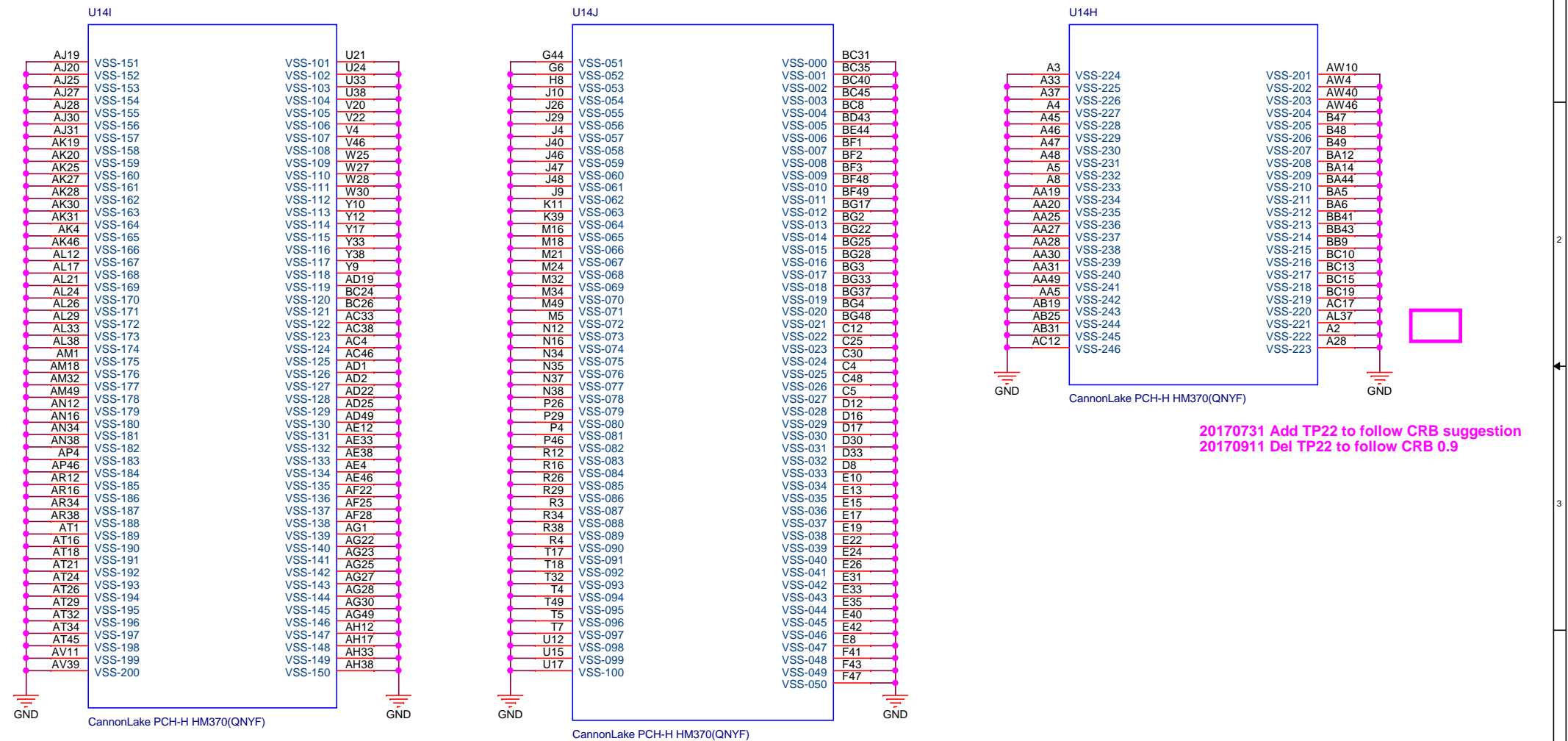


GPIO Group	Power Pins	Voltage
Primary Well Group A (GPP_A)	VCCPGPPA	1.8V or 3.3V
Primary Well Group B (GPP_B)	VCCPGPPBC	1.8V or 3.3V
Primary Well Group C (GPP_C)	VCCPGPPD	1.8V or 3.3V
Primary Well Group D (GPP_D)	VCCPGPPD	1.8V or 3.3V
Primary Well Group E (GPP_E)	VCCPGPPEF	1.8V or 3.3V
Primary Well Group F (GPP_F)	VCCPGPPEF	1.8V or 3.3V
Primary Well Group G (GPP_G)	VCCPGPPG_3P3 or VCCPRIM_1P8	1.8V or 3.3V
Primary Well Group H (GPP_H)	VCCPGPPHK	1.8V or 3.3V
Primary Well Group K (GPP_K)	VCCPGPPHK	1.8V or 3.3V
Primary Well Group I (GPP_I)	VCCPRIM_3P3	3.3V Only
Primary Well Group J (GPP_J)	VCCPRIM_1P8	1.8V Only
Deep Sleep Well Group (GPD)	VCCDSW_3P3	3.3V Only

Note: Except for GPP_G group, the operating voltage of a GPIO group having voltage configurability (3.3V or 1.8V) is selected by both connecting the corresponding power pin and setting the group-voltage-selection soft strap to the desired voltage. GPP_G group voltage is selected by setting the corresponding soft strap only.

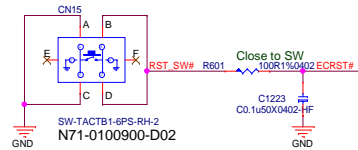
Name	Description
VCCA_BCLK_1P05	Analog supply for BCLK circuitries: 1.05V
VCCA_SRC_1P05	Analog supply for PCIe clock circuitries: 1.05V
VCCA_XTAL_1P05	Analog supply for XTAL circuitries: 1.05V
VCCDUSB_1P05	Supply for USB digital logic: 1.05V
VCCAPLL_1P05	Analog supply for BCLK/DMI/Audio PLLs: 1.05V. This rail can be derived from the VCCPRIM_1P05 rail with the proper isolation. Refer to the Platform Design Guide for implementation detail.
VCCPRIM_1P05	Primary Well: 1.05V. For PCIe//USB3/SATA MPHY logic, I/O blocks, SRAM, JTAC, CNVI.
VCCDSW_1P05	Deep Sx Well: 1.05V. This rail is generated by on the DSW low dropout (LDO) linear regulator to supply DSW core logic. Board needs to connect a 1uF capacitor to this rail and power should NOT be driven from the board.
VCCPRIM_MPHY_1P05	Mod PHY Primary: 1.05V. Primary supply for PCIe/USB3/SATA MPHY logic and PCIe/USB PLL dividers.
VCCAMPHYPLL_1P05	Analog supply for USB3, PCIe Gen 2/Gen 3, and SATA3 PLLs: 1.05V. Refer to the Platform Design Guide for filtering and decoupling recommendations.
VCCPRIM_1P8	1.8V Primary Well.
VCCPRIM_3P3	3.3V Primary Well.
VCCSPI	SPI Primary Well 3.3V or 1.8V, for SPI interface.
VCCHDA	HDA Audio Power 3.3V, 1.8V, or 1.5V, for Intel® High Definition Audio.
VCCDSW_3P3	3.3V Deep Sx Well.
VCCRTC	RTC Well Supply. This rail can drop to 2.0V if all other planes are off. This power is not expected to be shut off unless the RTC battery is removed or drained. Note: VCCRTC nominal voltage is 3.0V. This rail is intended to always come up first and always stay on. It should NOT be power cycled regularly on non-chip battery designs. Refer to the Platform Design Guide, RTC Design Guidelines chapter for latest design recommendations. Note: Implementation should not attempt to clear CMOS by using a jumper to pull VCCRTC low. Clearing CMOS can be done by using a jumper on RTCRST# or GPI.
DCPRTC	RTC decoupling capacitor only. This rail should NOT be driven.
VCCDPHY_1P24	1.24V for CNVI logic. This rail is generated internally with a LDO and needs to be routed to the motherboard so that the rail can be supplied back to the SoC. Refer to the Platform Design Guide for implementation details.
VCCDPHY_EC_1P24	For decoupling capacitor only. This rail should NOT be driven from the motherboard. This rail can optionally be connected to VCCDPHY_1P24 on the motherboard.
VCCPHVLD0_1P8	1.8V Primary Well. On the motherboard, this power pin must be connected to VCCPRIM_1P8 rail in Internal 1.8 V VRM Mode and left as no connect in External 1.8V VRM Mode.
VCCGPAPA	1.8V or 3.3V for GPP_A group.
VCCGPPBC	1.8V or 3.3V for GPP_B and GPP_C groups.
VCCGPPD	1.8V or 3.3V for GPP_D group.
VCCGPPEF	1.8V or 3.3V for GPP_E and GPP_F groups.
VCCGPPG_3P3	3.3V for GPP_G group.
VCCGPPHK	1.8V or 3.3V for GPP_H and GPP_K groups.
VCCMPHY_SENSE	1.05V Sense Line.
VSSMPHY_SENSE	0V (Ground) Sense Line.
VSS	Ground.

PCH-H(GND)



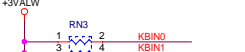
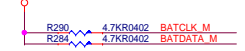
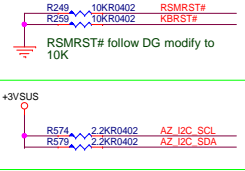
20170731 Add TP22 to follow CRB suggestion
20170911 Del TP22 to follow CRB 0.9

Hardware Reset



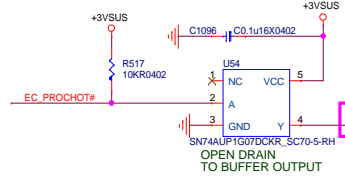
remove OVERT# (Active Low)

PU/PD

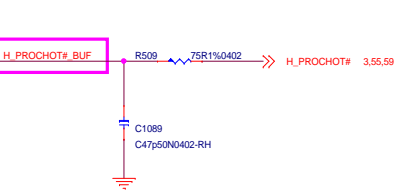


20170829 add R3528

EC_PROCHOT#



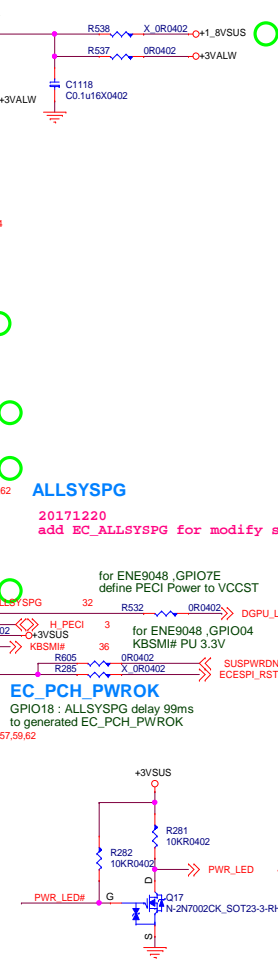
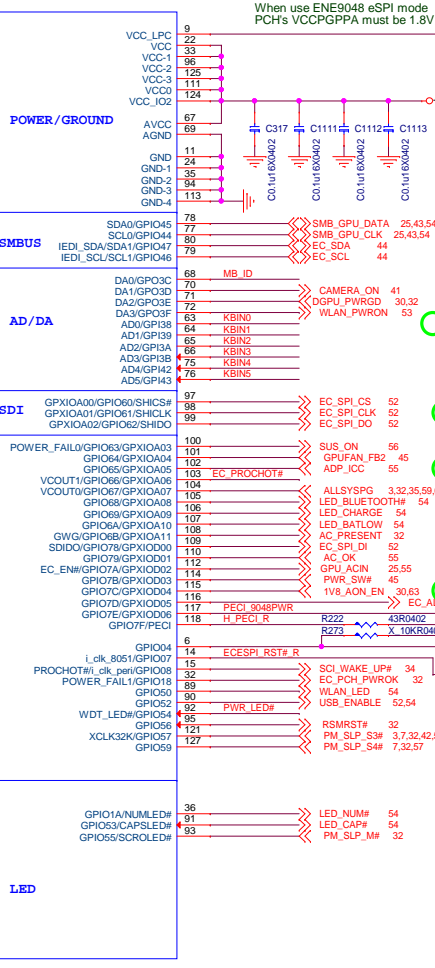
20170814 add net name H_PROCHOT#_BUF



KBC/EC/uP (ENE9028)



Remove MB_ID



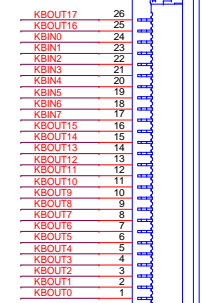
ENE9028 & 9048 Power Notes :

pin9 VCCLPC :
3.3V for ENE9028's LPC mode.
1.8V for ENE9048's eSPI mode.

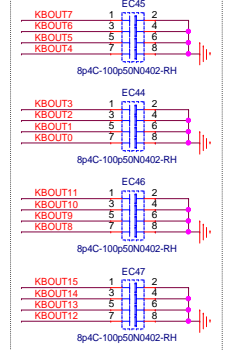
pin111 VCCO :
3.3V for ENE9028's PLC function
3.3V for ENE9048's eSPI operation with Pre-Driver.

N5A-26F0450-H06

CN14
FPC26P-1PITCH_NATURAL-RH-1

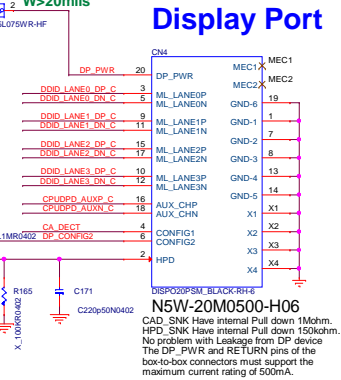
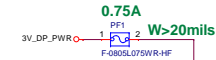
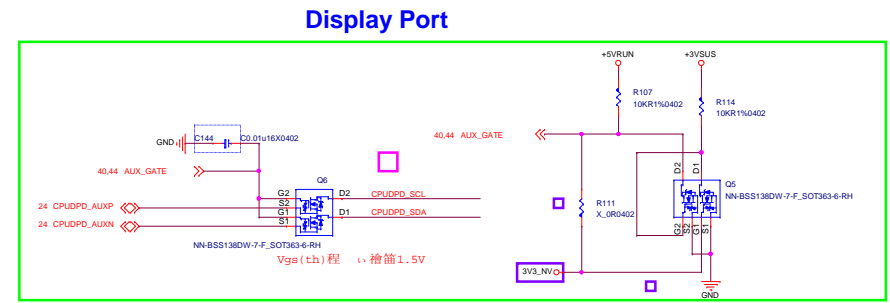
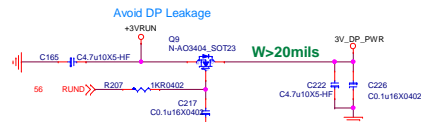
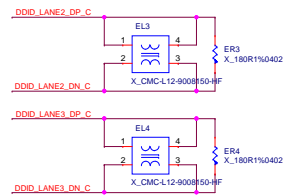
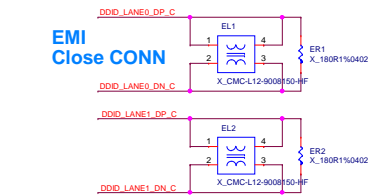
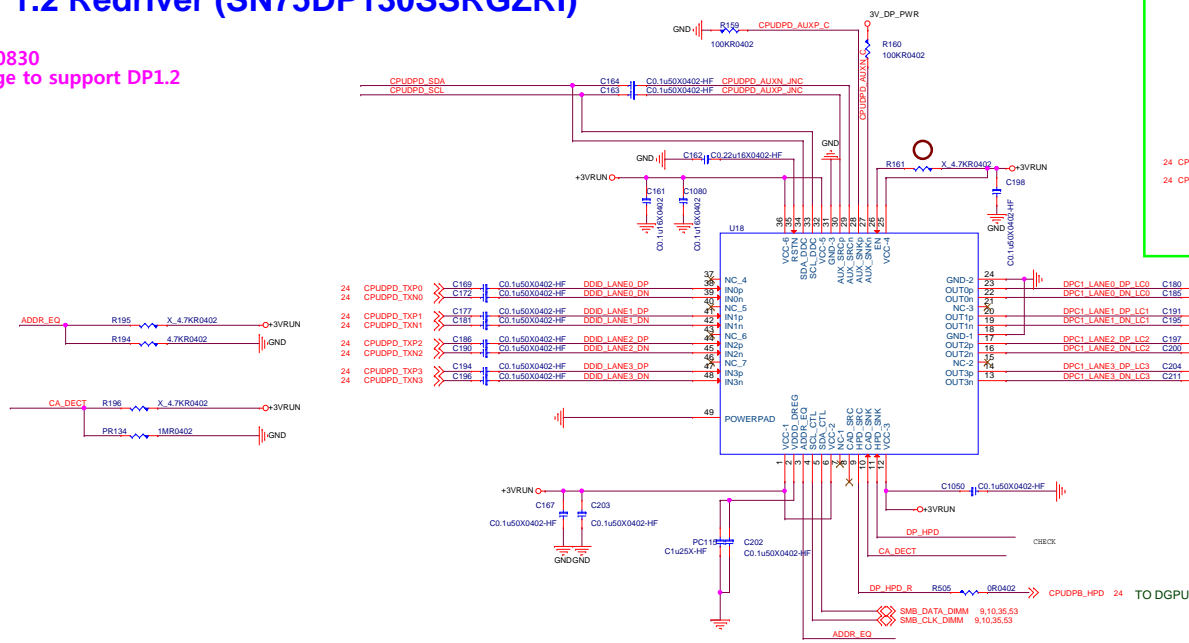


For EMI

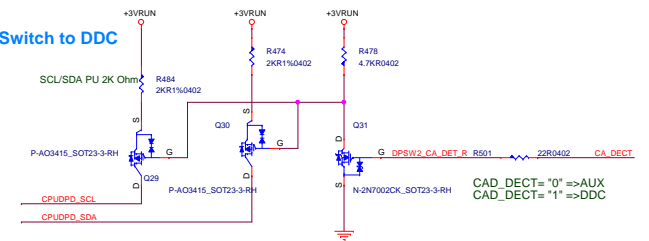


MB_ID	GS	WS
1	per key	White Color
0	3 Area	NA

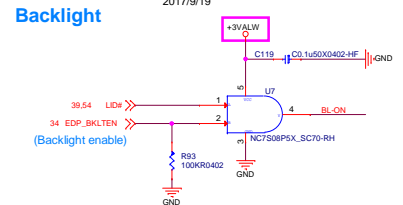
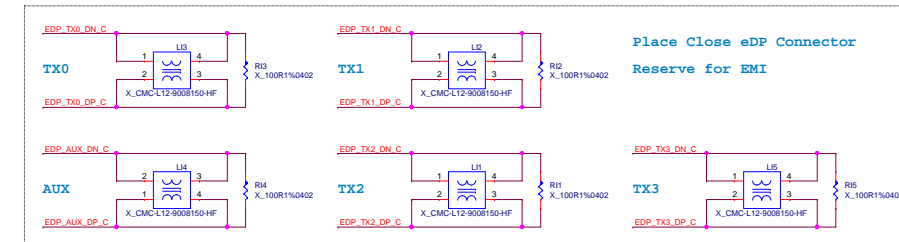
20170830
change to support DP1.2



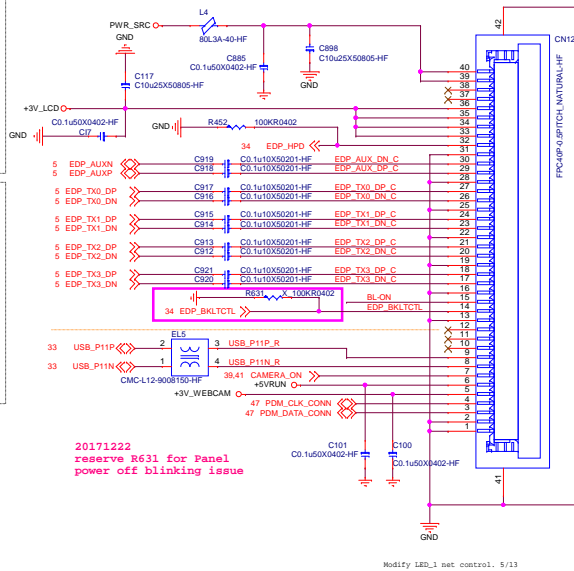
For Dual Mode Switch to DDC



Pannel Device Logic Power 20171220
change input to +3VSUS for panel sequence
reserve R625 for Panel power off
blinking issue

[illegible]

eDP CONN

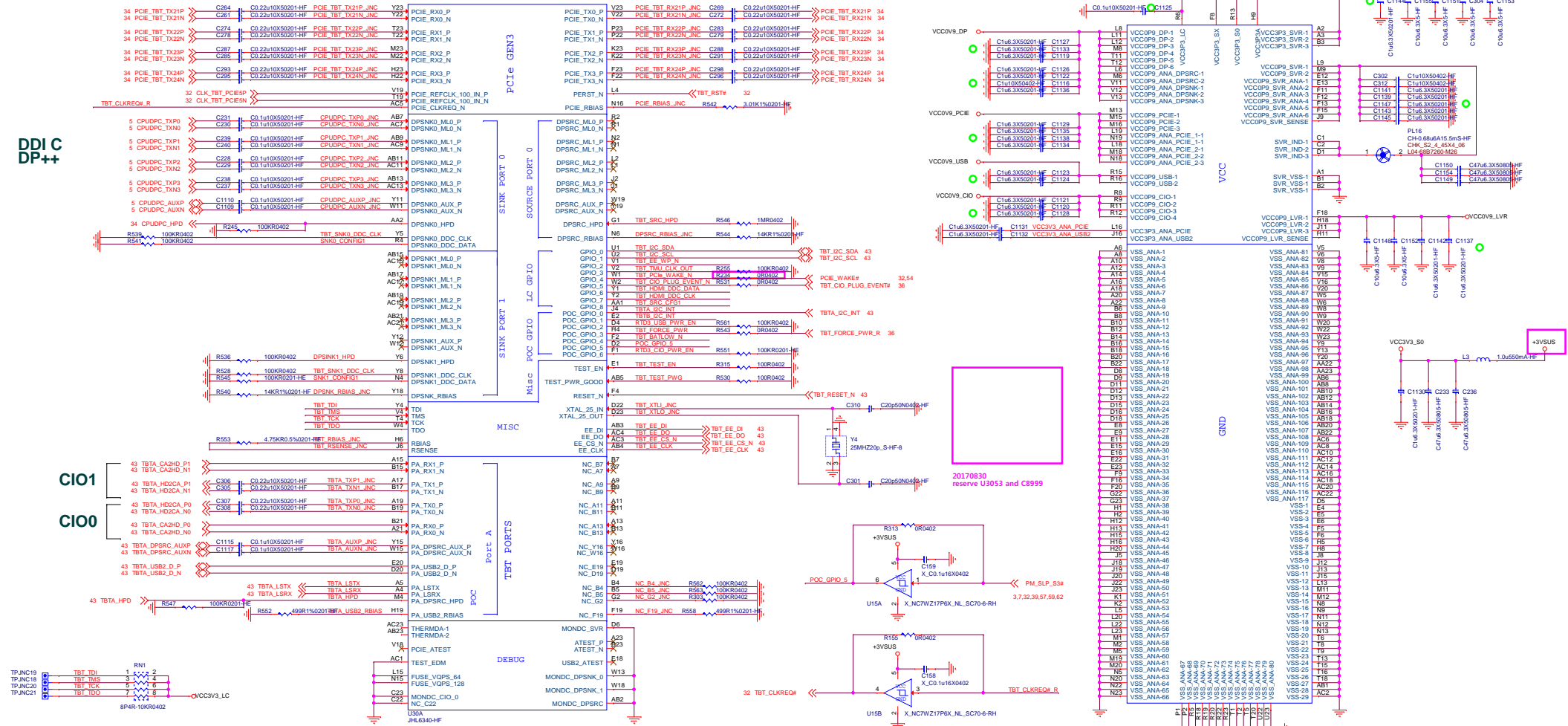


Pin No	Symbol	Description
1	Vcom_SDA	Vcom IIC SDA
2	H_GND	High Speed Ground
3	LAN1_N	Complement Signal-Lane 1
4	LAN1_P	True Signal-Main Lane 1
5	H_GND	High Speed Ground
6	LAN0_N	Complement Signal-Lane 0
7	LAN0_P	True Signal-Main Lane 0
8	H_GND	High Speed Ground
9	AUX+	True Signal-Auxiliary Channel
10	AUX-	Complement Signal-Auxiliary Channel
11	H_GND	High Speed Ground
12	LCD_VCC	Power Supply +3.3 V (typical)
13	LCD_VCC	Power Supply +3.3 V (typical)
14	NC	No Connection (Reserved for CMI test)
15	H_GND	Ground
16	H_GND	Ground
17	HPD	Hot Plug Detect
18	BL_GND	BL Ground
19	BL_GND	BL Ground
20	BL_GND	BL Ground
21	BL_GND	BL Ground
22	BL_EN	BL Enable Signal of LED Converter
23	BL_PWM	PWM Dimming Control Signal of LED Converter
24	Vcom_SCL	Vcom IIC SCL
25	NC	No Connection (Reserved)
26	LED_VCCS	BL Power
27	LED_VCCS	BL Power
28	LED_VCCS	BL Power
29	LED_VCCS	BL Power
30	NC	No Connection (Reserved)

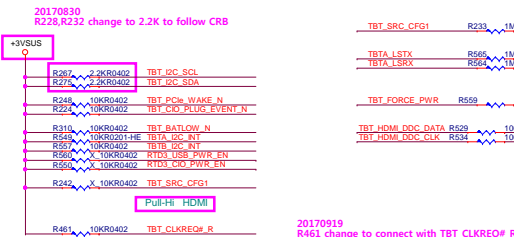
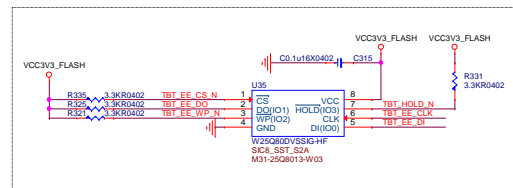
Pin No	Symbol	Description
1	NC	Reserved for LCD manufacturer's use
2	H_GND	High Speed Ground
3	Lane3_N	Complement Signal Link Lane 3
4	Lane3_P	True Signal Link Lane 3
5	H_GND	High Speed Ground
6	Lane2_N	Complement Signal Link Lane 2
7	Lane2_P	True Signal Link Lane 2
8	H_GND	High Speed Ground
9	Lane1_N	Complement Signal Link Lane 1
10	Lane1_P	True Signal Link Lane 1
11	H_GND	High Speed Ground
12	Lane0_N	Complement Signal Link Lane 0
13	Lane0_P	True Signal Link Lane 0
14	H_GND	High Speed Ground
15	AUX_CH_P	True Signal Auxiliary Channel
16	AUX_CH_N	Complement Signal Auxiliary Channel
17	H_GND	High Speed Ground
18	VDD	LCD logic and driver power(3.3V)
19	VDD	LCD logic and driver power(3.3V)
20	VDD	LCD logic and driver power(3.3V)
21	VDD	LCD logic and driver power(3.3V)
22	BIST	BIST patterns selection L : Disable (default), H : Enable
23	LCD_GND	LCD logic and driver ground
24	LCD_GND	LCD logic and driver ground
25	LCD_GND	LCD logic and driver ground
26	LCD_GND	LCD logic and driver ground
27	HPD	HPD signal pin
28	BL_GND	Backlight ground
29	BL_GND	Backlight ground
30	BL_GND	Backlight ground
31	BL_GND	Backlight ground
32	BL_ENABLE	Backlight On/off
33	BL_PWM_DIM	System PWM
34	NC	Reserved for LCD manufacturer's use
35	NC	Reserved for LCD manufacturer's use
36	VBL	Backlight power
37	VBL	Backlight power
38	VBL	Backlight power
39	VBL	Backlight power
40	NC	No Connection (Reserved)

Pin No	Symbol	Description
1	NC	Reserved for LCD manufacturer's use
2	H_GND	High Speed Ground
3	Lane3_N	Complement Signal Link Lane 3
4	Lane3_P	True Signal Link Lane 3
5	H_GND	High Speed Ground
6	Lane2_N	Complement Signal Link Lane 2
7	Lane2_P	True Signal Link Lane 2
8	H_GND	High Speed Ground
9	Lane1_N	Complement Signal Link Lane 1
10	Lane1_P	True Signal Link Lane 1
11	H_GND	High Speed Ground
12	Lane0_N	Complement Signal Link Lane 0
13	Lane0_P	True Signal Link Lane 0
14	H_GND	High Speed Ground
15	AUX_CH_P	True Signal Auxiliary Channel
16	AUX_CH_N	Complement Signal Auxiliary Channel
17	H_GND	High Speed Ground
18	NC	Reserved for LCD manufacturer's use
19	NC	Reserved for LCD manufacturer's use
20	VDD	LCD logic and driver power(3.3V)
21	VDD	LCD logic and driver power(3.3V)
22	VDD	LCD logic and driver power(3.3V)
23	VDD	LCD logic and driver power(3.3V)
24	VDD	LCD logic and driver power(3.3V)
25	NC	Reserved for LCD manufacturer's use
26	LCD_GND	LCD logic and driver ground
27	LCD_GND	LCD logic and driver ground
28	LCD_GND	LCD logic and driver ground
29	LCD_GND	LCD logic and driver ground
30	LCD_GND	LCD logic and driver ground
31	HPD	Backlight ground
32	NC	Reserved for LCD manufacturer's use
33	PWM_OUT	PWM_OUT
34	PWM_IN	PWM_IN
35	NC	Reserved for LCD manufacturer's use
36	NC	Reserved for LCD manufacturer's use
37	NC	Reserved for LCD manufacturer's use
38	VBL	LED Anode
39	VBL	LED Anode
40	NC	Reserved for LCD manufacturer's use
41	LED_C1	LED Cathode 1
42	LED_C2	LED Cathode 2
43	LED_C3	LED Cathode 3
44	LED_C4	LED Cathode 4
45	LED_C5	LED Cathode 5
46	LED_C6	LED Cathode 6
47	LED_C7	LED Cathode 7
48	LED_C8	LED Cathode 8
49	NC	Reserved for LCD manufacturer's use
50	NC	Reserved for LCD manufacturer's use

Thunderbolt

20170830
modify for AR b-step, c-step chip and wake function

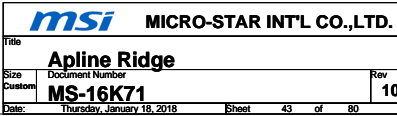
B07-L634015-I06

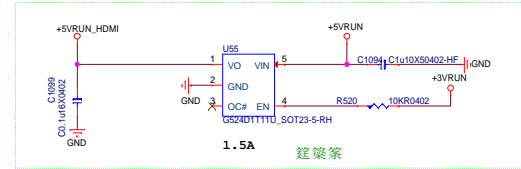
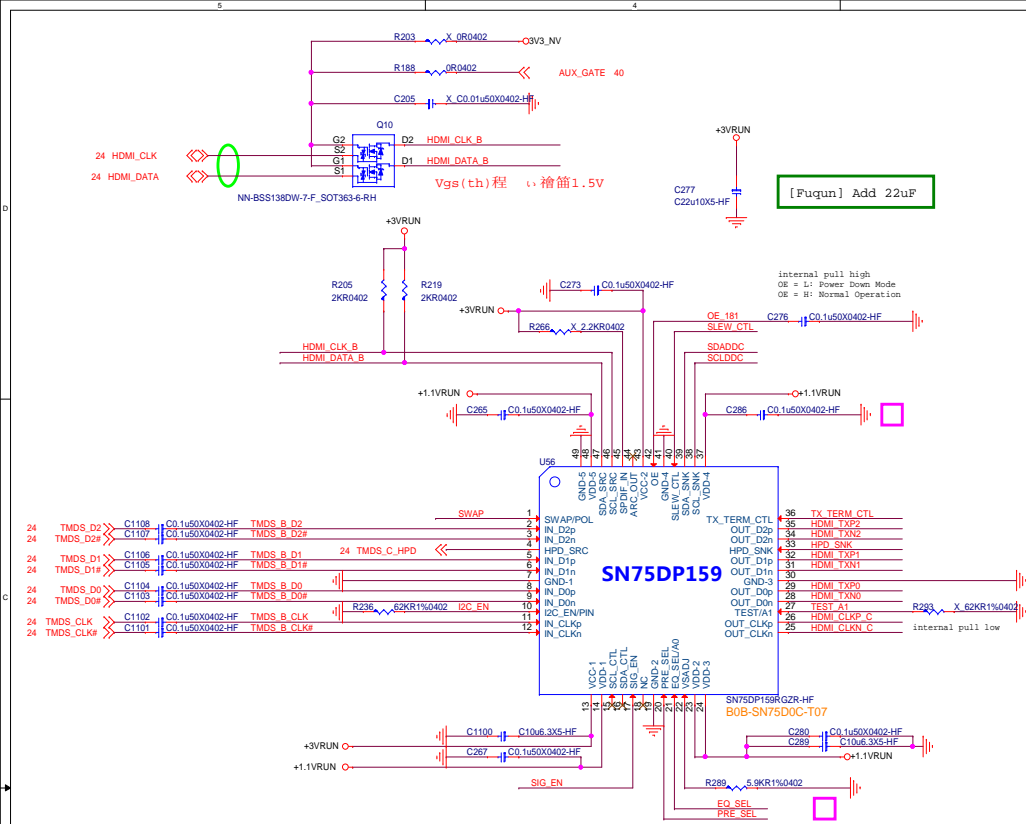


20170919
R461 change to connect with TBT_CLKREQ#_F

GPIO	TERMINATION	Power Rail
GPIO 0	10K PU	VCC3V3_LC
GPIO 1	10K PU	VCC3V3_LC
GPIO 2	100K PD	
GPIO 3	100K PD	
GPIO 4	10K PU	VCC3V3_LC
GPIO 5	10K PU	VCC3V3_LC
GPIO 6	100K PD	
GPIO 7	100K PD	
GPIO 8	100K PD	

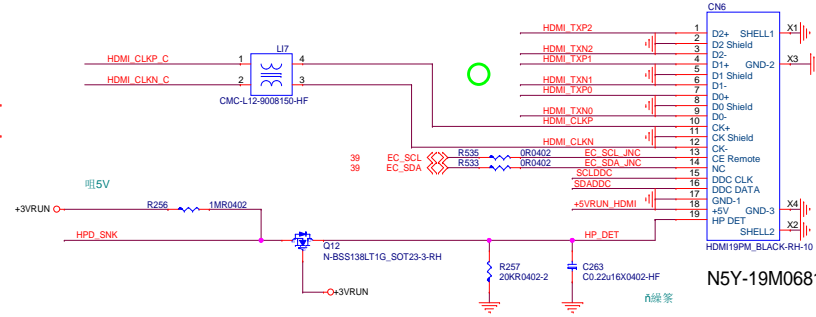
POC_GPIO 0	10K PU	VCC3V3_TBT_S1
POC_GPIO 1	10K PU	VCC3V3_TBT_S1
POC_GPIO 2	100K PD	
POC_GPIO 3	100K PD	
POC_GPIO 4	10K PU	VCC3V3_TBT_S1
POC_GPIO 5	10K PU	VCC3V3_TBT_S1
POC_GPIO 6	100K PD	



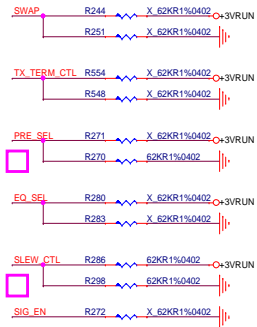


HDMI connector

An HDMI Source shall have +5V Power signal over-current protection of no more than 0.5A.
HPD_SNK Internal PD 150kohm



N5Y-19M0681-AF2



VCC/2 Normal operation

TX_TERM_CTL = H, No transmit Termination
TX_TERM_CTL = L, Transmit Termination impedance in 75-150
TX_TERM_CTL = Vcc/2, Automatically selects the termination

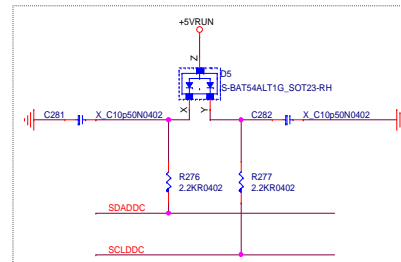
PRE_SEL = L: -2.5dB
PRE_SEL = Vcc/2: 0dB
PRE_SEL = H: -5dB

EQ_SEL = L: Fixed EQ at 7.5dB @ 3GHz
EQ_SEL = Vcc/2: Adaptive EQ
EQ_SEL = H: Fixed at 14B @ 3GHz

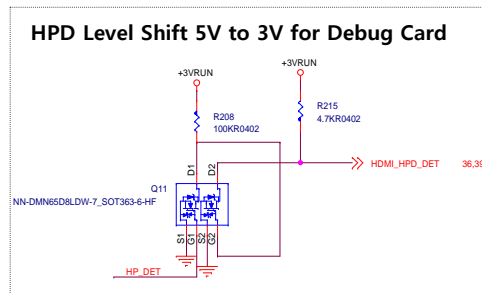
SLEW_CTL = H, Fastest data rate(Default)
SLEW_CTL = L, 20ps slow
SLEW_CTL = Vcc/2, 40ps slow

SIG_EN = L: Signal Detect Circuit Disabled (Default)
SIG_EN = H: Signal Detect Circuit Enabled:
When no valid clock device enters Standby Mode
internal pull low

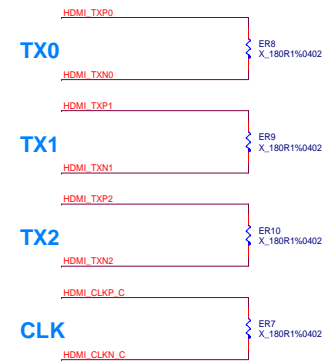
20171227
change R270 and R286 stuff for SA
change R289 to 5.9K(R11-0592T12-W08) for SA



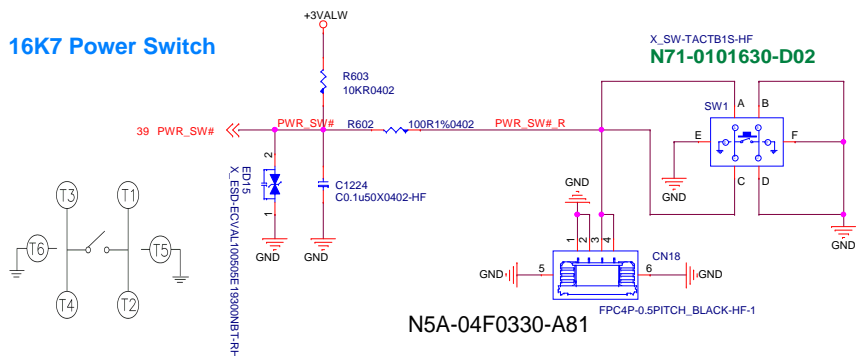
HPD Level Shift 5V to 3V for Debug Card



EMI Close Connector

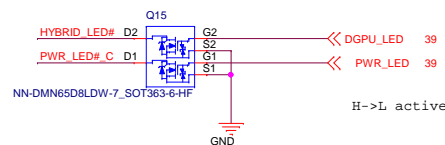


16K7 Power Switch



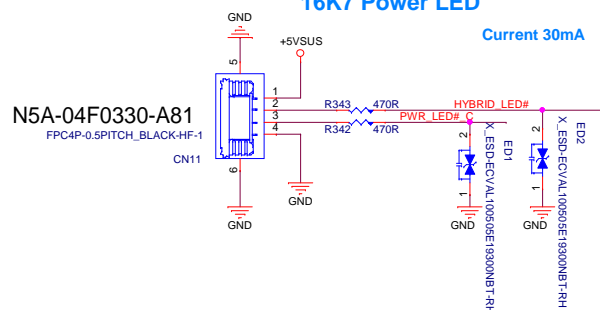
DGPU_LED	PWR_LED	LED_COLOR
L	H	RED
H	H	ORANGE
H	L	GREEN
L	L	X

Control PWR LED



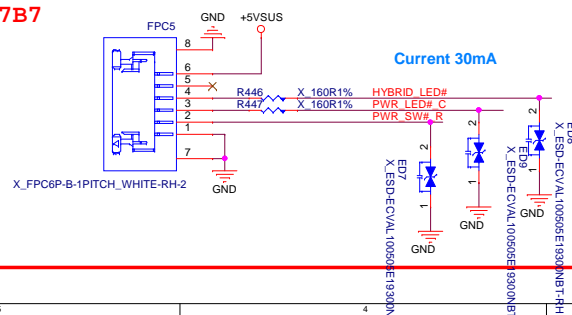
16K7 Power LED

Current 30mA



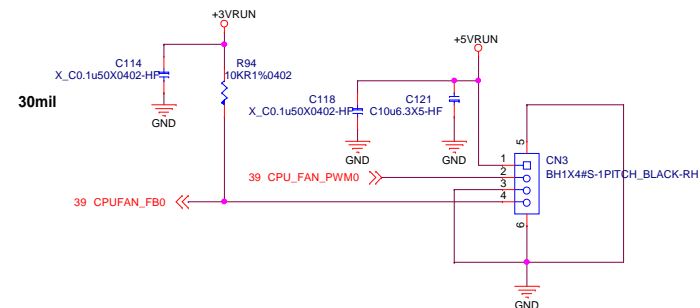
Power LED+SW For 17B7

Current 30mA

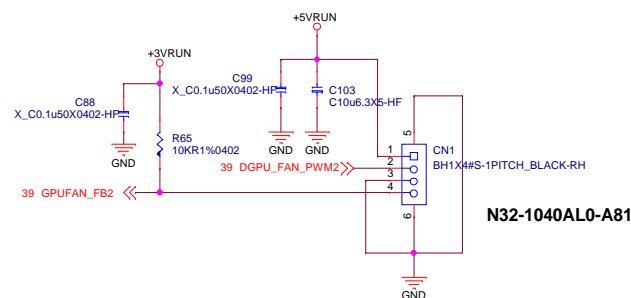
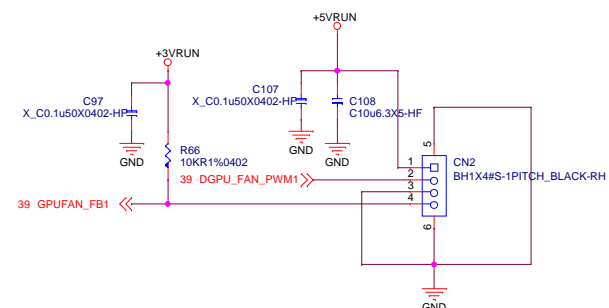


remove 16K2's LED_ACPI#_BR
and APCI_BR Circuit

CPU FAN

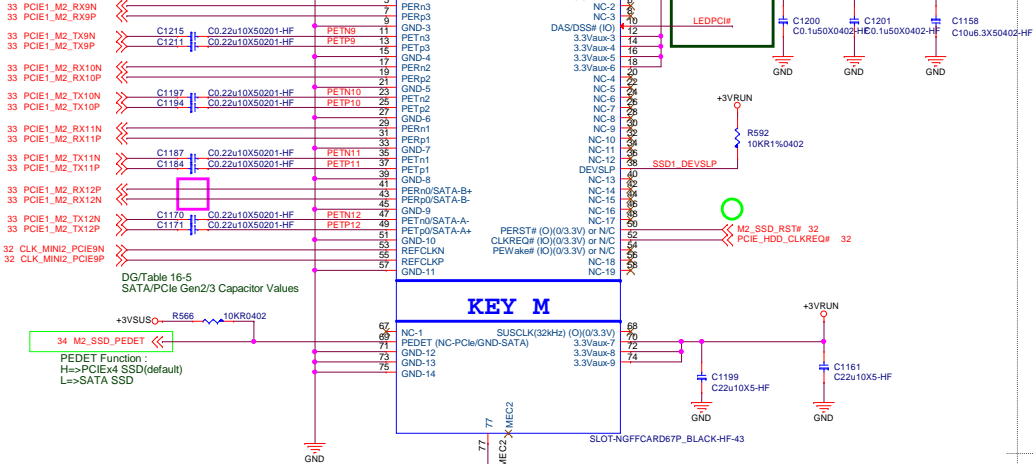


DGPU FAN



M2 SSD
PCIeX4 /SATA SSD

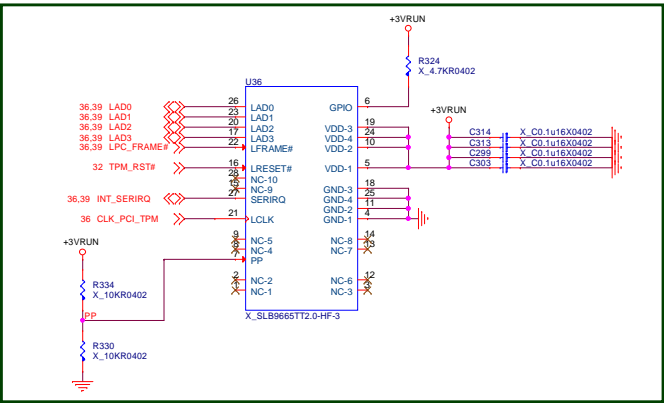
20170803
delete R2437,R2438 and net PERP12,PERN12



N15-0670530-L41

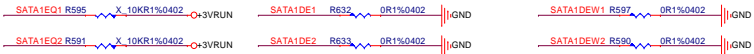
40	NC	No Connect
41	SATA-B+/PERn0	Host receiver differential signal pair
42	NC	No Connect
43	SATA-B-/PERp0	Host receiver differential signal pair
44	NC	No Connect
45	GND	Ground
46	NC	No Connect
47	SATA-A-/PETn0	Host Transmitter differential signal pair
48	NC	No Connect
49	SATA-A+/PETp0	Host transmitter differential signal pair

TPM
FOR WS



Physical Presence(PP)
The standard position of the jumper should connect the pin to GND. If the pin is connected to VDD, some special commands are enabled .

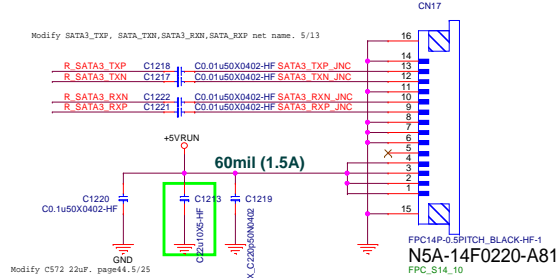
DE1/DE2	CH1/CH2De-Emphasis dB (at 6Gbps)	EQ1/EQ2	CH1/CH2Equalization dB (at 6Gbps)
NC (default)	-4	NC (default)	0
0	0	0	7
1	-2	1	14
DEW1/DEW2	Device Function → DE Width for CH1/CH2		
0	De-emphasis pulse duration, short (recommended setting when link operates at SATA 1.5/3/6 Gbps)		
1 (default)	De-emphasis pulse duration, long (recommended setting when link operates at SATA 1.5/3 Gbps speed only)		



TI SN75LVCP601RTJR HW Setting

20171227
delete TPJNC24 and TPJNC25
add R632 and R633 for SA

HDD2



(Must used the gold fresh type)

msi MICRO-STAR INT'L CO.,LTD.		
Title M2 SSD/HDD/TPM		
Size	Document Number MS-16K71	Rev 10
Date	Thursday, January 18, 2018	Sheet 46 of 80

AUDIO(ALC1220)

ALC1220	AZ_GPIO3_DSD
PCM	H
Native DSD	L
DOP DSD	L

20170801 change R2248 to 33R to follow DG

To EC
To EC

To EC
Internal Mic

DIGITAL
Analog

To Mux

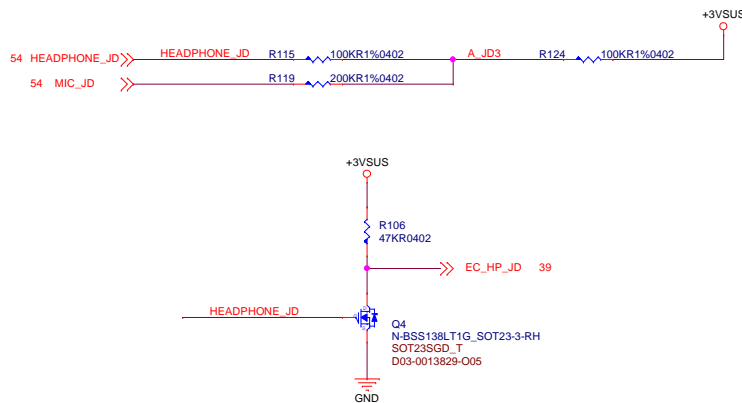
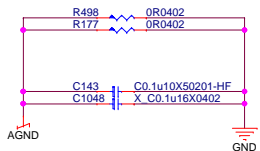
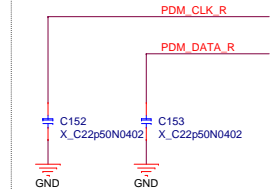
Impedance DECT
Woffor FOR 17B5

MIC In

20170817 change R2255 and R2257 unstuff
(OD pin and no use)

20171118 change U16 from B05-012201C-R09 to B05-012203C-R09
20171125 change U16 from B05-012203C-R09 to B05-012204C-R09

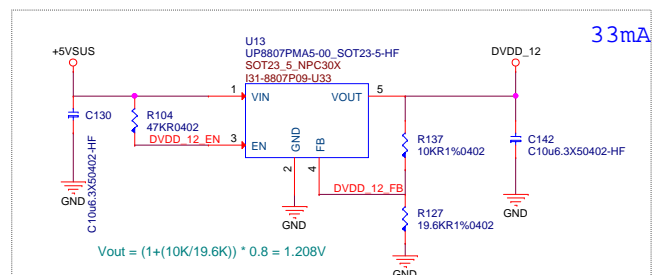
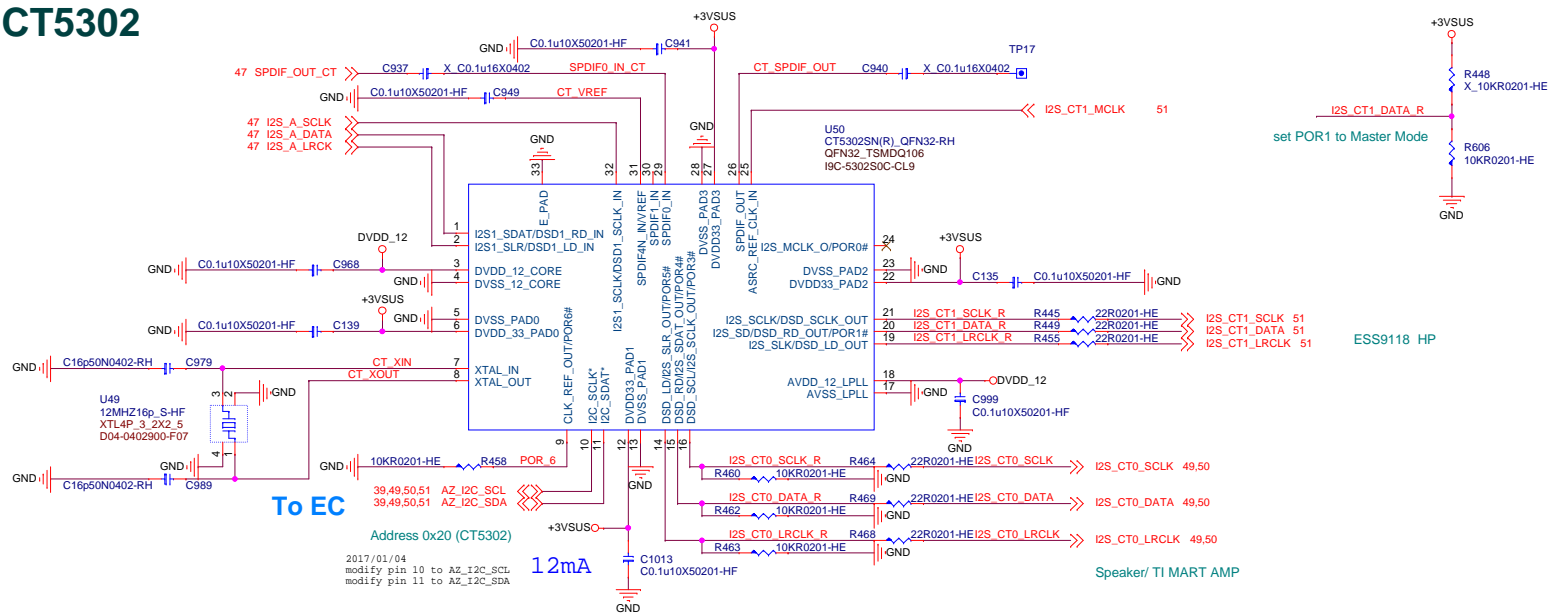
EMI
Close Codec



msi MICRO-STAR INT'L CO.,LTD.

Title	Audio(ALC1220)	Rev	10
Size	Document Number		
Custom	MS-16K71		
Date	Thursday, January 18, 2018	Sheet	47 of 80

CT5302



I2S output slave mode:

Select I2S1 output port

No.	POR1	Definition
0	0	I2S output master mode
1	1	I2S output slave mode

Hardware Crystal:

Select current external crystal frequency

No	POR4	POR3	Definition
0	0	0	12.0000MHz
1	0	1	11.2896MHz
2	1	0	12.2880MHz
3	1	1	14.3180MHz

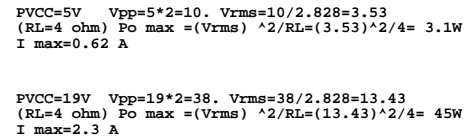
I2C Slave ID

Define chip I2C slave address

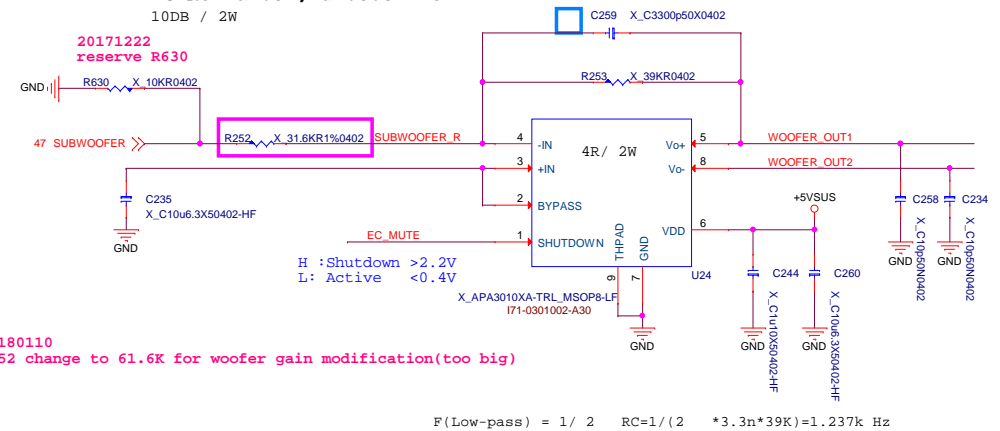
No	POR6	POR5	Definition
0	0	0	0x20
1	0	1	0x22
2	1	0	0x24
3	1	1	0x26

Pin Name	Description	Function Table
POR_IN_1	POWER_ON_LATCH_DC[1] = SEL_I2S_TX_SLAVE_MODE	Select I2S1 output port is master or slave mode
POR_IN_3	POWER_ON_LATCH_DC[4:3] = SEL_XTAL[1:0]	Select Crystal frequency
POR_IN_4		
POR_IN_5	POWER_ON_LATCH_DC[6:5] = I2C_ID[1:0]	I2C serial interface device ID selection
POR_IN_6		

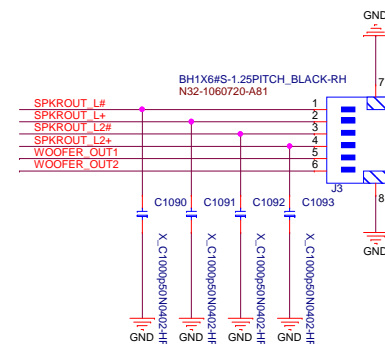
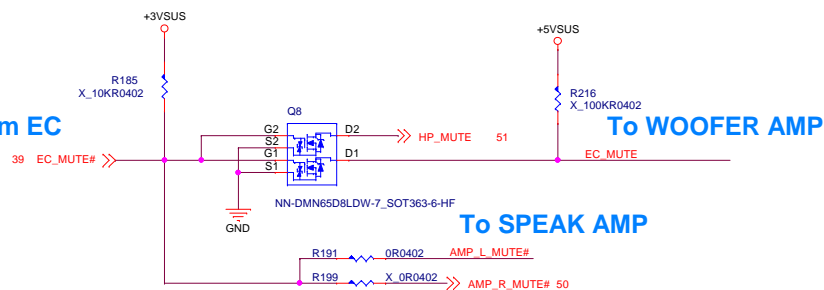
```
20180110
change smart Amp connect with PWR_SRC
```



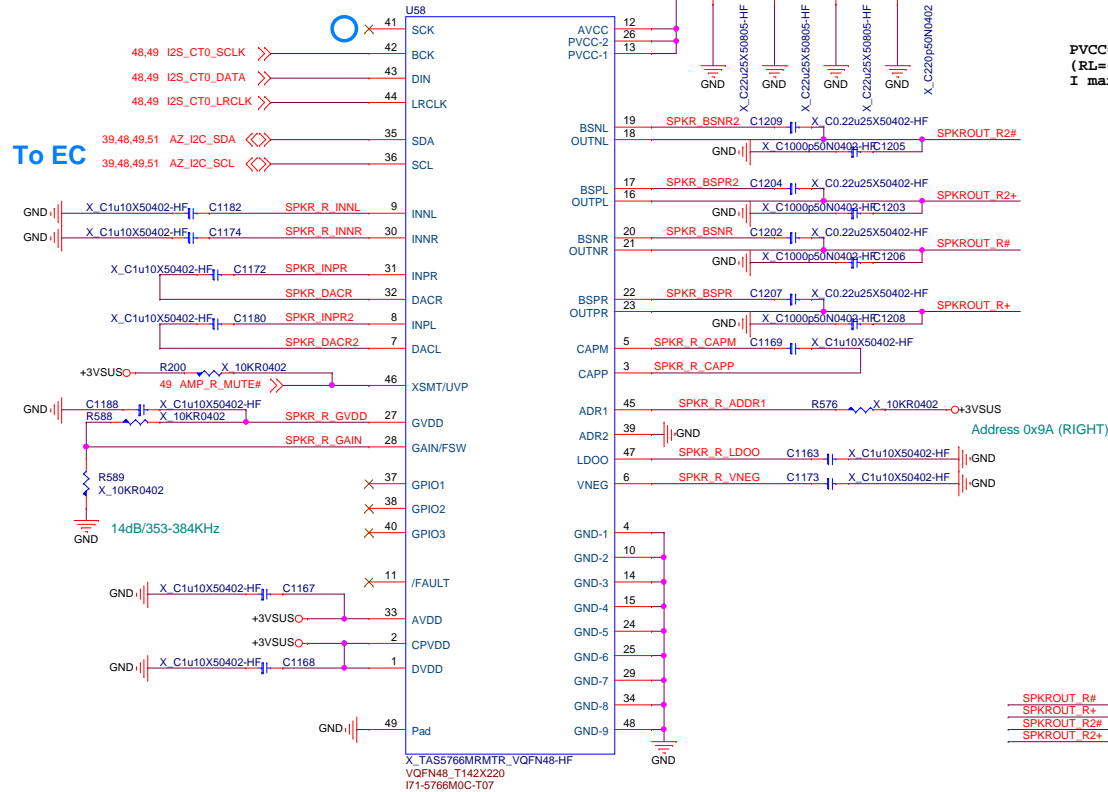
YG Normal:3W,Max:3.5W 4ohm
10DB / 2W



From EC



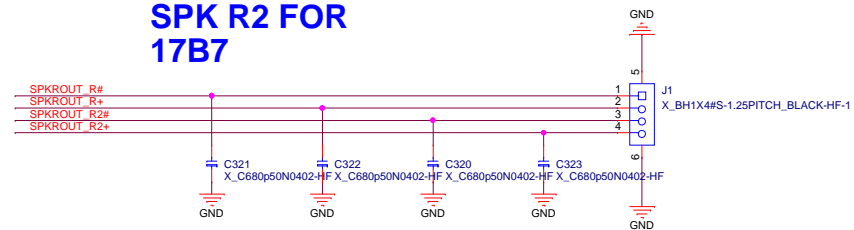
Speaker RIGHT



PVCC=5V Vpp=5*2=10. Vrms=10/2.828=3.53
(RL=4 ohm) Po max =(Vrms) ^2/RL=(3.53)^2/4= 3.1W
I max=0.62 A

PVCC=19V Vpp=19*2=38. Vrms=38/2.828=13.43
(RL=4 ohm) Po max =(Vrms) ^2/RL=(13.43)^2/4= 45W
I max=2.3 A

Right SPK Conn SPK R2 FOR 17B7



ESS9118

To EC

2017/01/04
modify pin 38 to AZ_I2C_SCL
modify pin 39 to AZ_I2C_SDA

Address 0x90 (ESS9118)

ES9118EQ

Audio MUX

20180110
R239 change to 10K for HP_SEL HIGH LEVEL low voltage
R626,R627 change to 20R for Headphone pop noise
when system turn off and decrease cross-talk

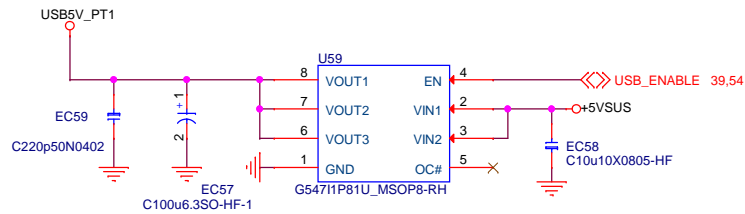
Power

Truth Table

INPUTS				OUTPUTS					
ACDC	DIR	MUTE	SEL	L1, R1	L2, R2	COM (L,R) CIP Shunts	L1, R1 CIP Shunts	L2, R2 CIP Shunts	
0	X	0	0	ON	OFF	OFF	OFF	OFF	OFF
0	X	0	1	OFF	ON	OFF	OFF	OFF	OFF
0	X	1	X	OFF	OFF	OFF	OFF	OFF	OFF
1	0	0	0	ON	OFF	OFF	OFF	ON	ON
1	0	0	1	OFF	ON	OFF	OFF	ON	OFF
1	0	1	X	OFF	OFF	OFF	ON	ON	ON
1	1	0	0	ON	OFF	OFF	OFF	OFF	OFF
1	1	0	1	OFF	ON	OFF	OFF	OFF	OFF
1	1	1	X	OFF	OFF	OFF	ON	ON	OFF

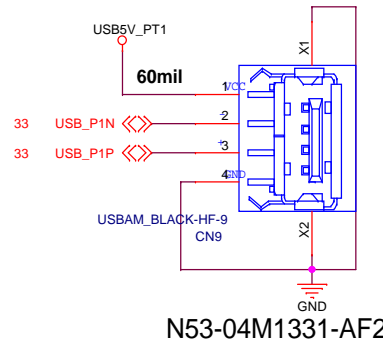
NOTE: MUTE, ACDC, DIR: Logic "0" ≤ 0.5V, Logic "1" ≥ 1.4V or Float with a 3.3V Supply or 5V supply.
SEL: Logic "0" ≤ 0.5V, Logic "1" ≥ 1.4V with a 3.3V Supply or 5V supply.
X = Don't Care

USB2.0 CONN

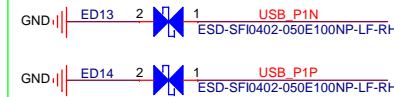


I36-5478102-G07

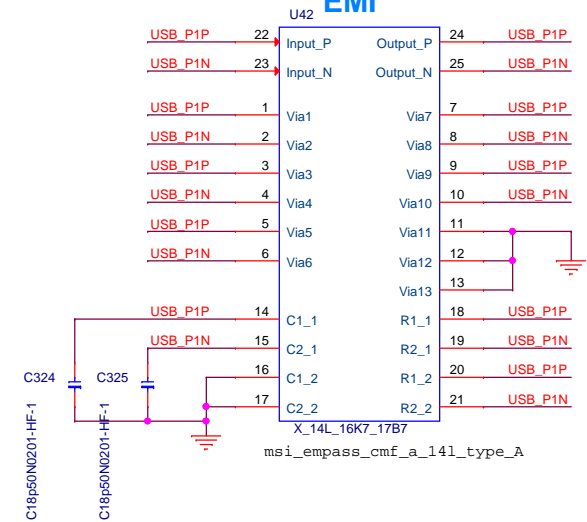
G547811 MAX :2.5A



ESD

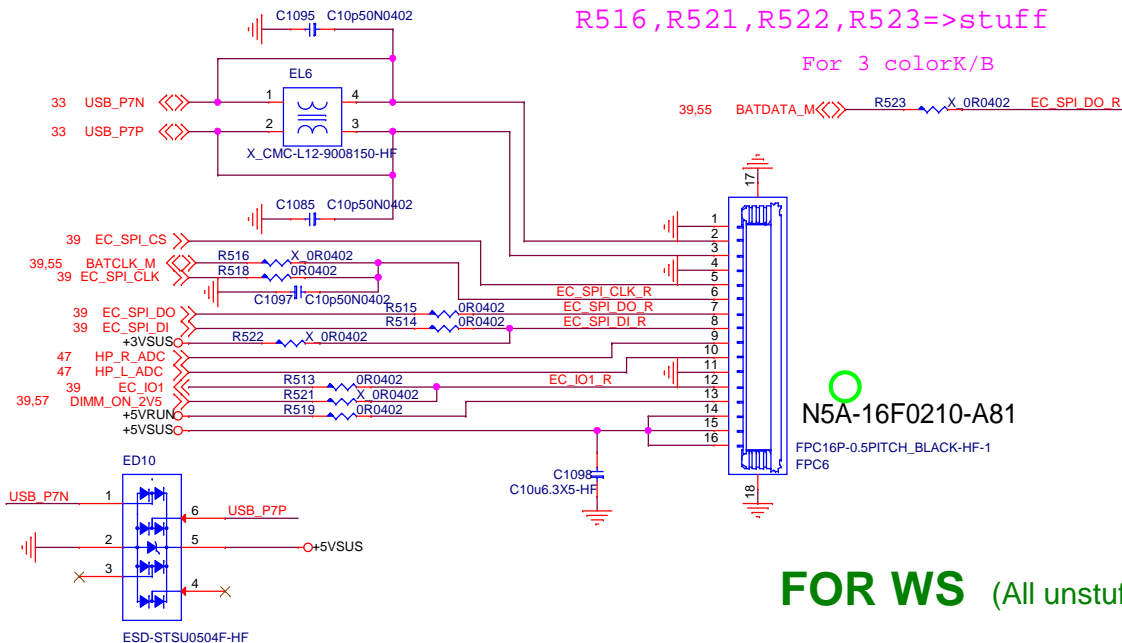


EMI



RGB Color Keyboard Control

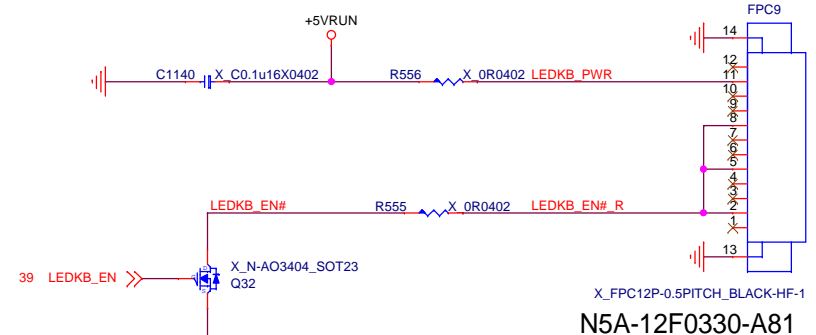
For 3 colorK/B
R513,R514,R515,R518,R519=>unstuff
C1097=>unstuff
R516,R521,R522,R523=>stuff



N5A-16F0210-A81

FOR WS (All unstuff)

White Color Keyboard Control FOR WS (All stuff)



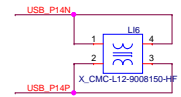
N5A-12F0330-A81

msi

MICRO-STAR INT'L CO.,LTD.

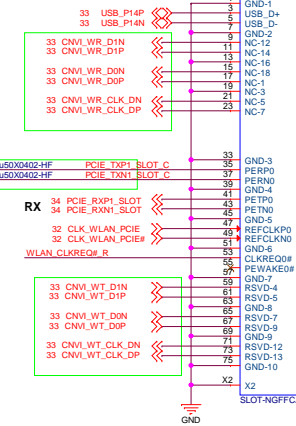
Title			USB2.0/Keyboard Control
Size	Document Number	Rev	
Custom	MS-16K71	10	
Date:	Thursday, January 18, 2018	Sheet	52 of 80

EMI



WLAN /ClickPad/FP

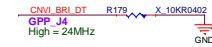
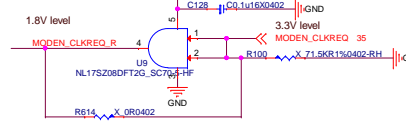
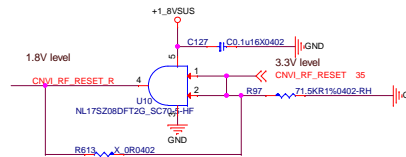
Ref DG Section 18.6
- use USB 2.0 Port 14 with CNVI Solution



N15-0670520-L41
SLOT_NGFFCARD67_H2_15

PN : T70-7S20870-O05
AND Gate/ NL17S208DFT2G

	V _{IH} Min	0.75*V _{CC}	V _{IL} Max	0.25*V _{CC}
1.65 to 1.95				
2.3 to 5.5	0.7*V _{CC}		0.3*V _{CC}	



Functional Strap Definitions

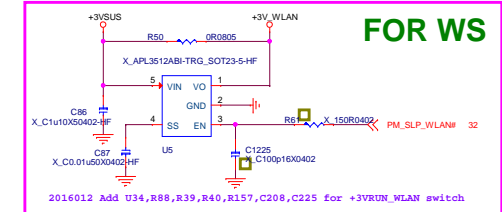
GPP_J4

This signal has a weak internal pull-down.
An external pull-up is required on this strap since 38.4 MHz XTAL is not supported on the PCH.
0 = 38.4 MHz XTAL frequency selected. (Default)
1 = 24 MHz XTAL frequency selected.

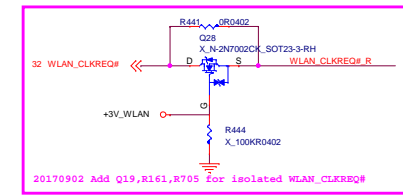
GPP_J6

An external pull-up or pull-down is required.
0 = Integrated CNVI enable.
1 = Integrated CNVI disable.

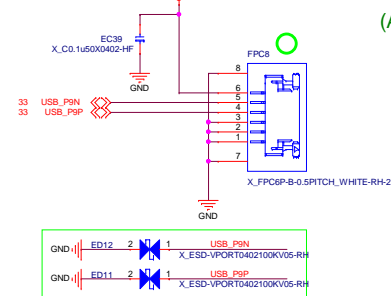
FOR WS



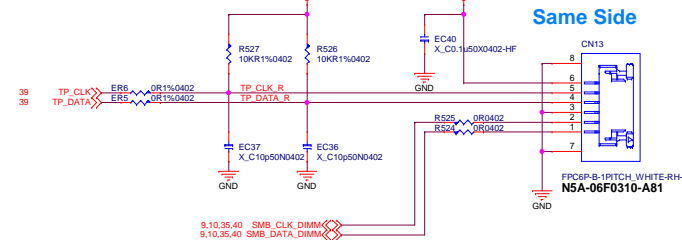
FOR WS



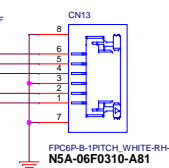
Finger Print

FOR WS
(All stuff)

Click Pad

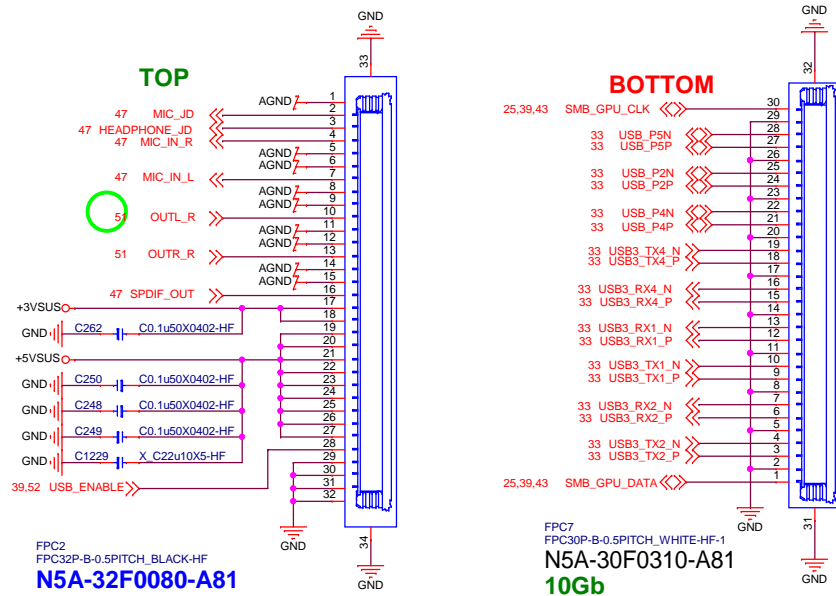


Same Side

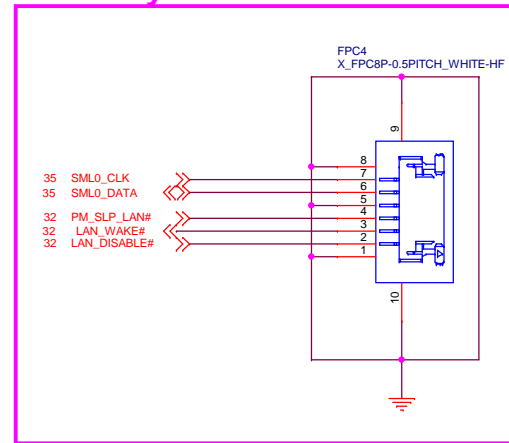


16K7/17B7 BTB CONN (Audio CONN/USB3.0)

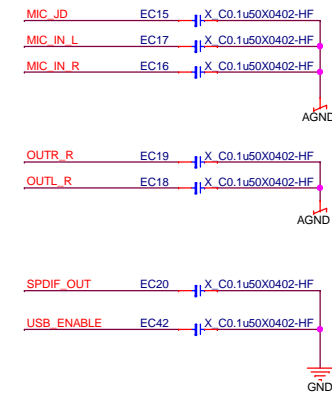
20171220
change FPC2 to 32pin and modify FPC7 pin define for new design
(Audio issue and USB3.1 solution change)



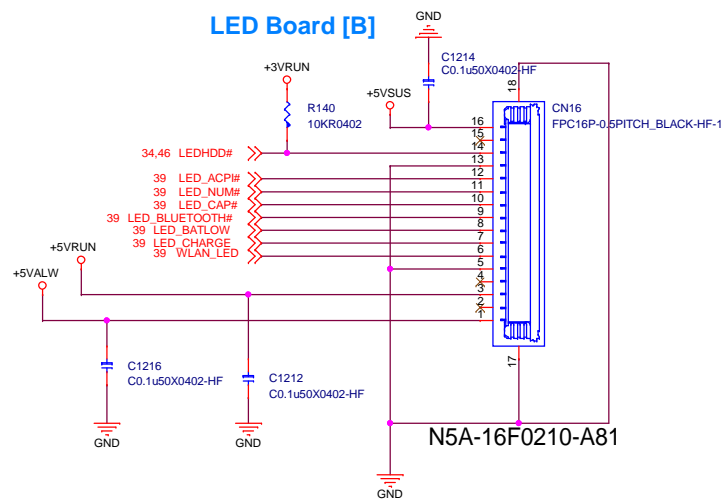
WS only



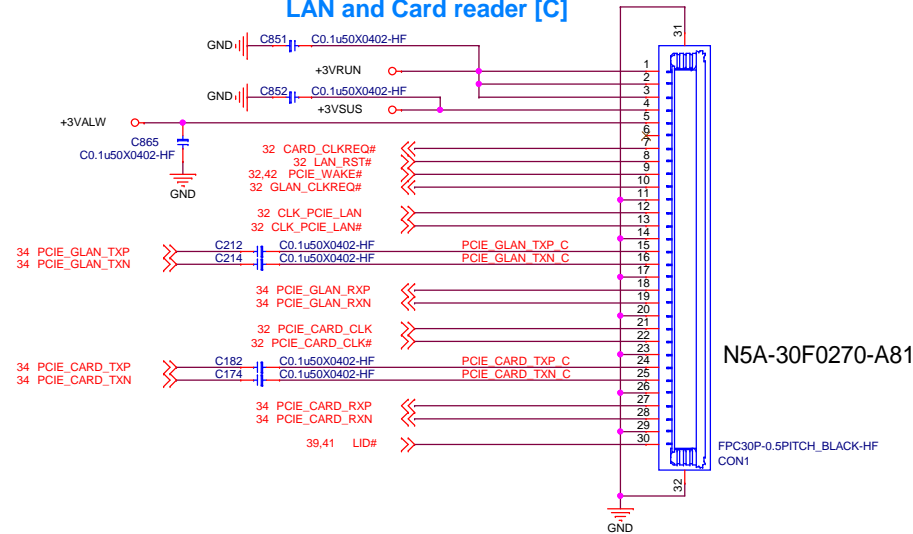
EMI



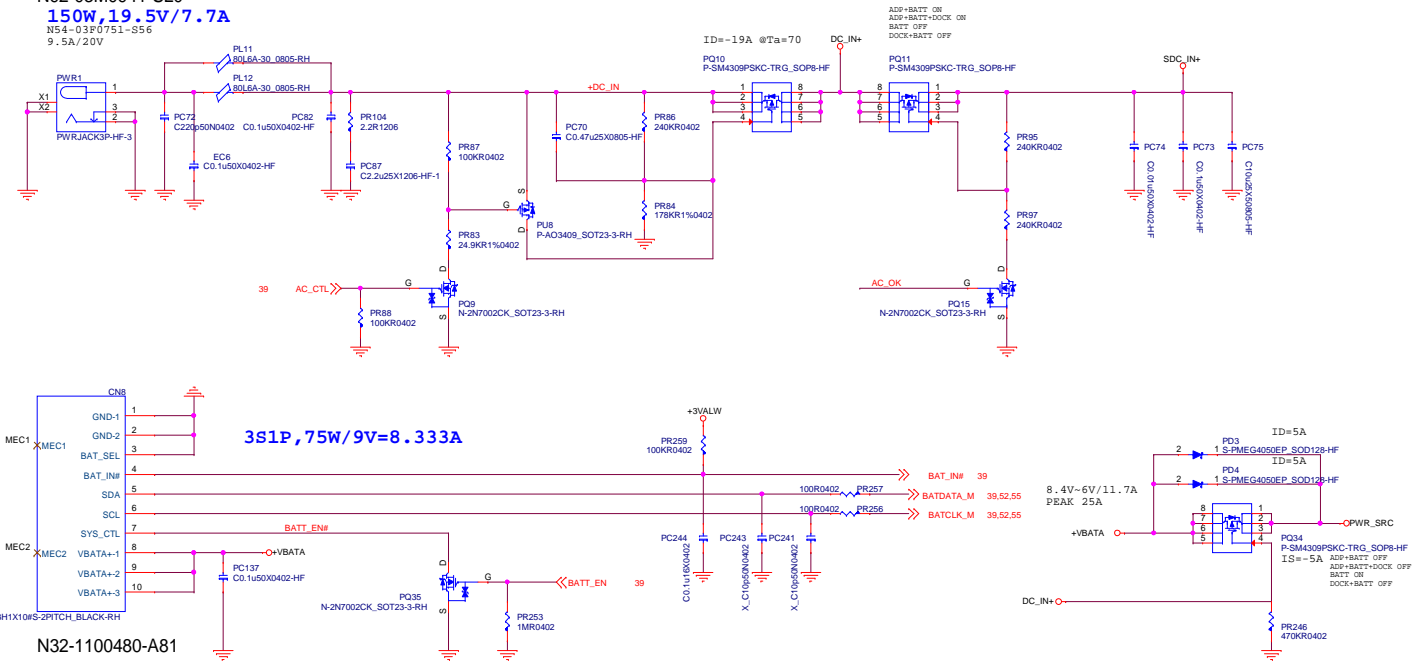
LED Board [B]



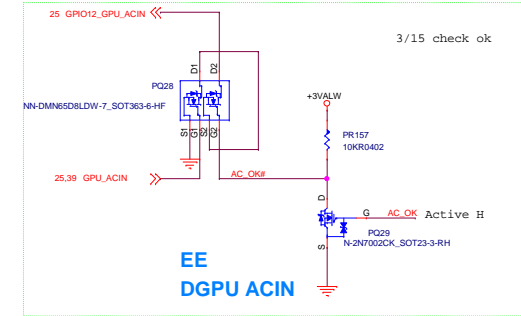
LAN and Card reader [C]



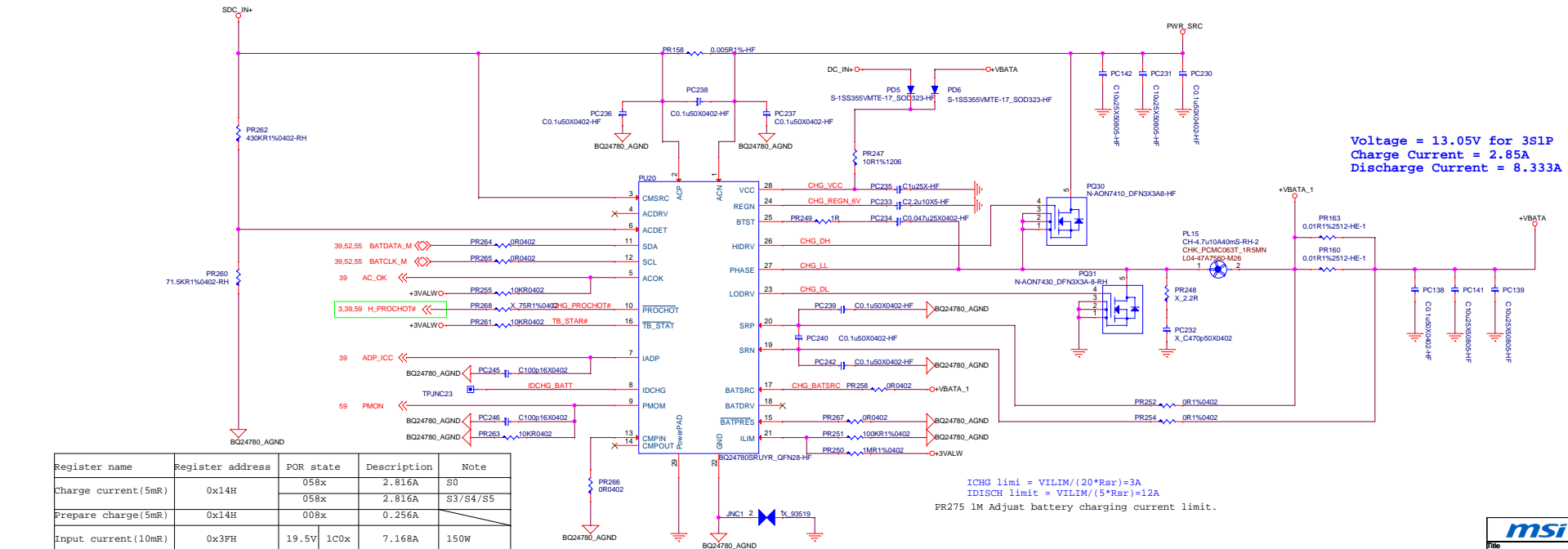
N92-03M0941-SL0
150W, 19.5V/7.7A
N54-03R0751-S56
9.5A/20V



AC_OK#	GPU_ACIN (EC control)	GPIO12_GPU_ACIN
0	0	AC
0	1	AC
1	0	AC
1	1	DC



N32-1100480-A81

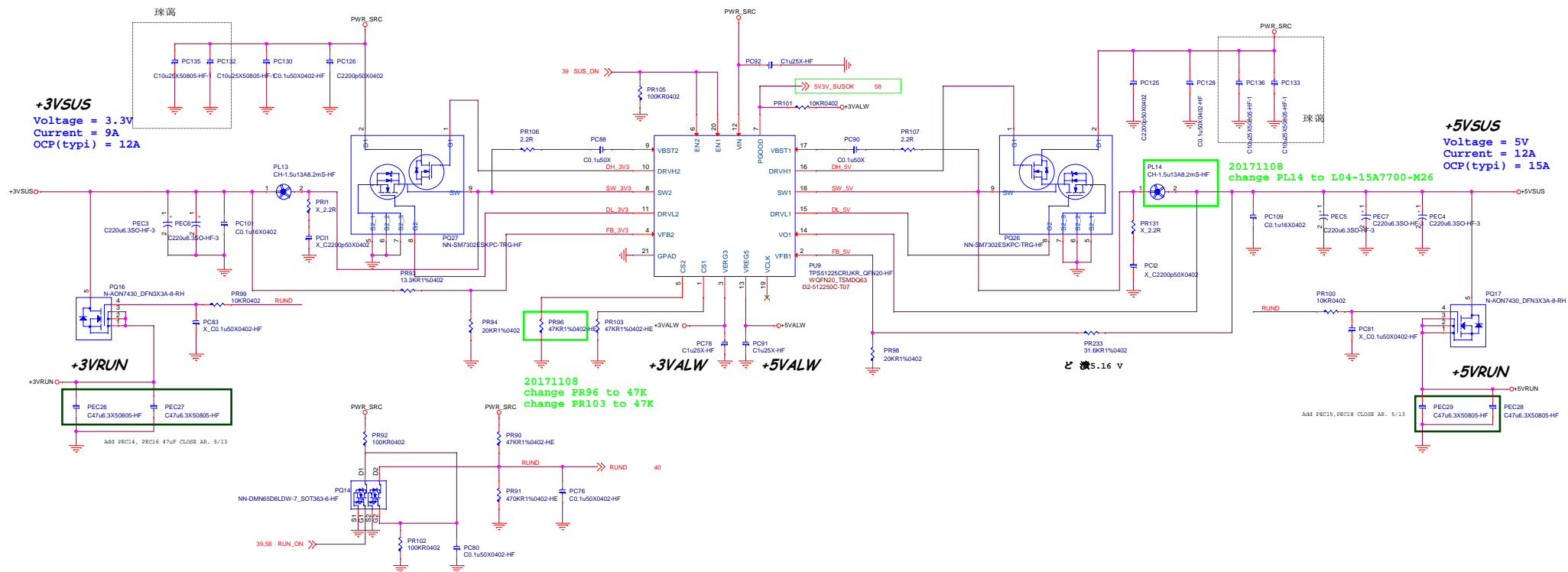


Voltage = 13.05V for 3S1P
Charge Current = 2.85A
Discharge Current = 8.333A

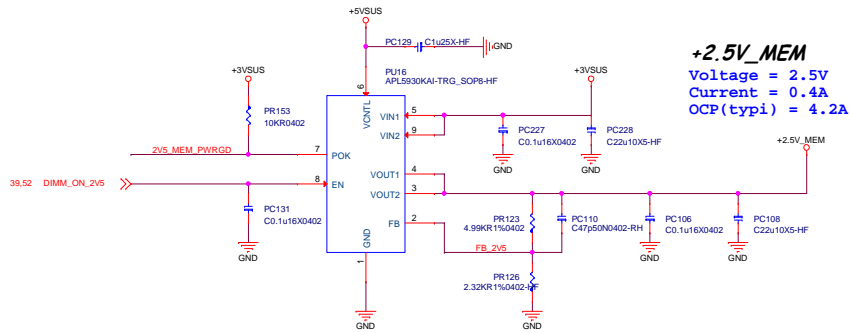
Register name	Register address	POR state	Description	Note
Charge current(5mR)	0x14H	058x	2.816A	S0
Prepare charge(5mR)	0x14H	008x	0.256A	S3/S4/S5
Input current(10mR)	0x3FH	19.5V 1C0x	7.168A	150W
Charge voltage	0x15H	330x	13.056V	3S1P
Discharge current(5mR)	0x39H	06xx	3.072A	BOOST current

ICHG limi = VILIM/(20*Rar)=3A
IDISCH limit = VILIM/(5*Rar)=12A
PR275 1M Adjust battery charging current limit.

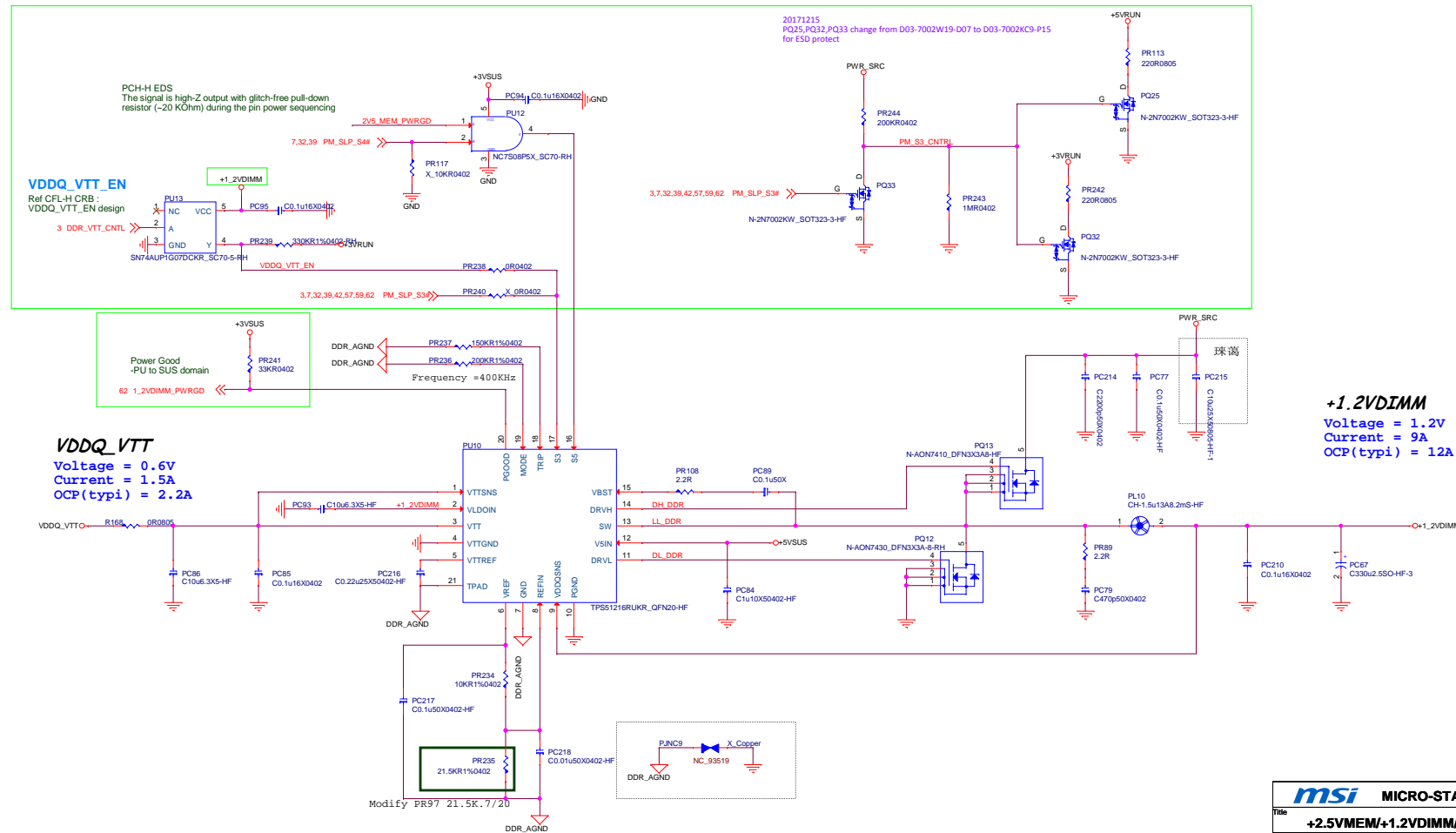
System Power



+2.5V_MEM (DDR4/Vpp)

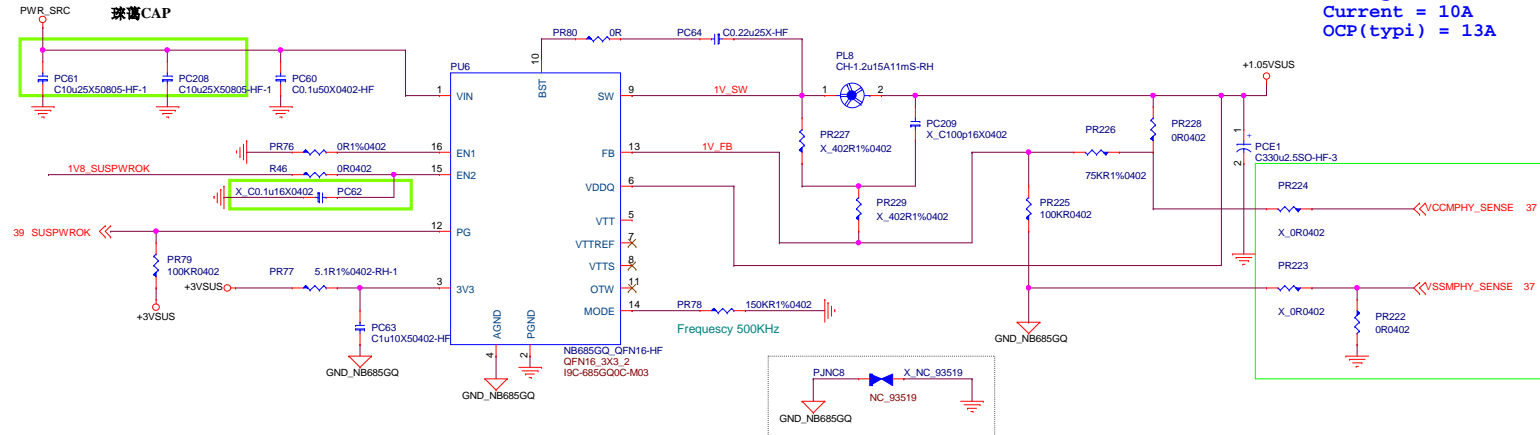


+1.2VDIMM / VDDQ_VTT(0.6V)



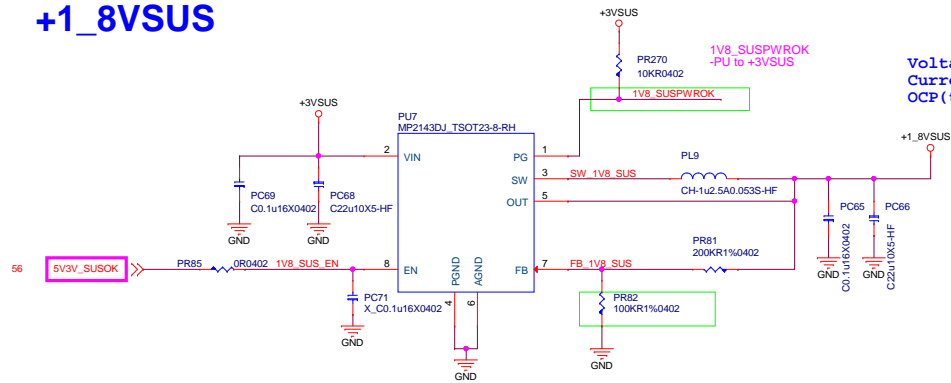
+1.05VSUS

20171108
change PC62 to unstuff

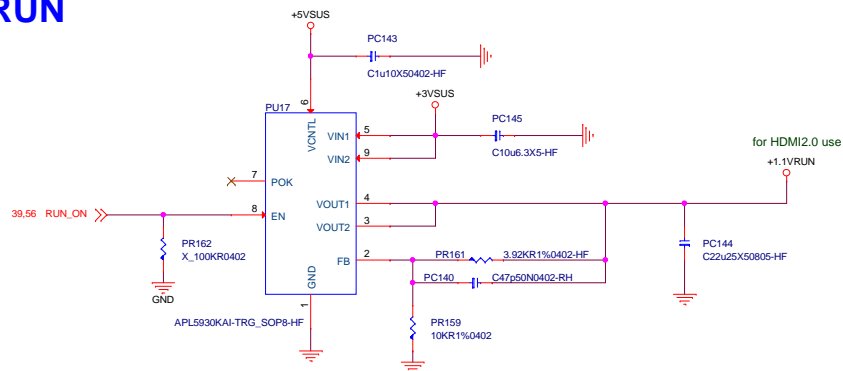


+1_8VSUS

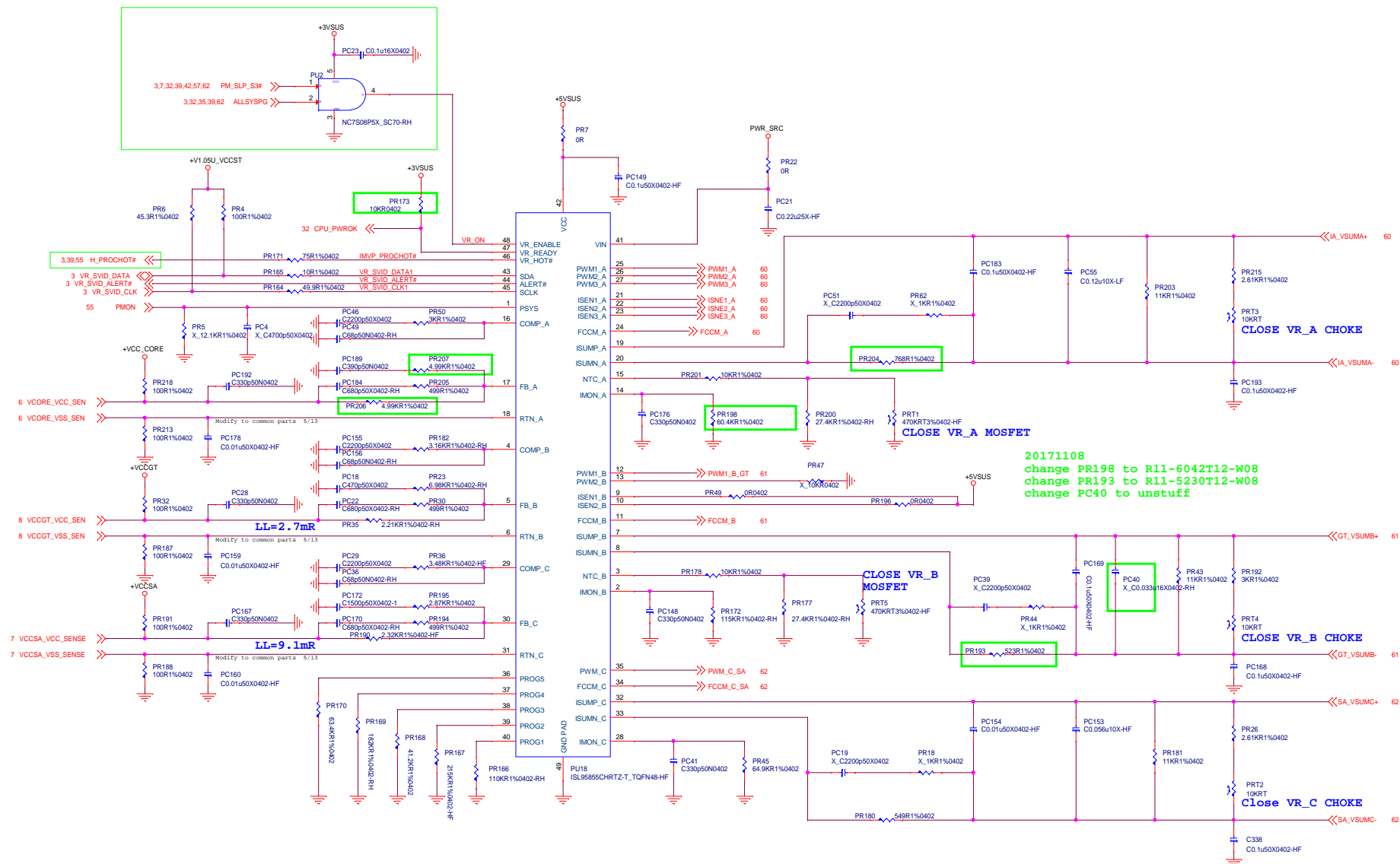
Voltage = 1.8V
Current = 1A
OCP(typi) = 2.5A



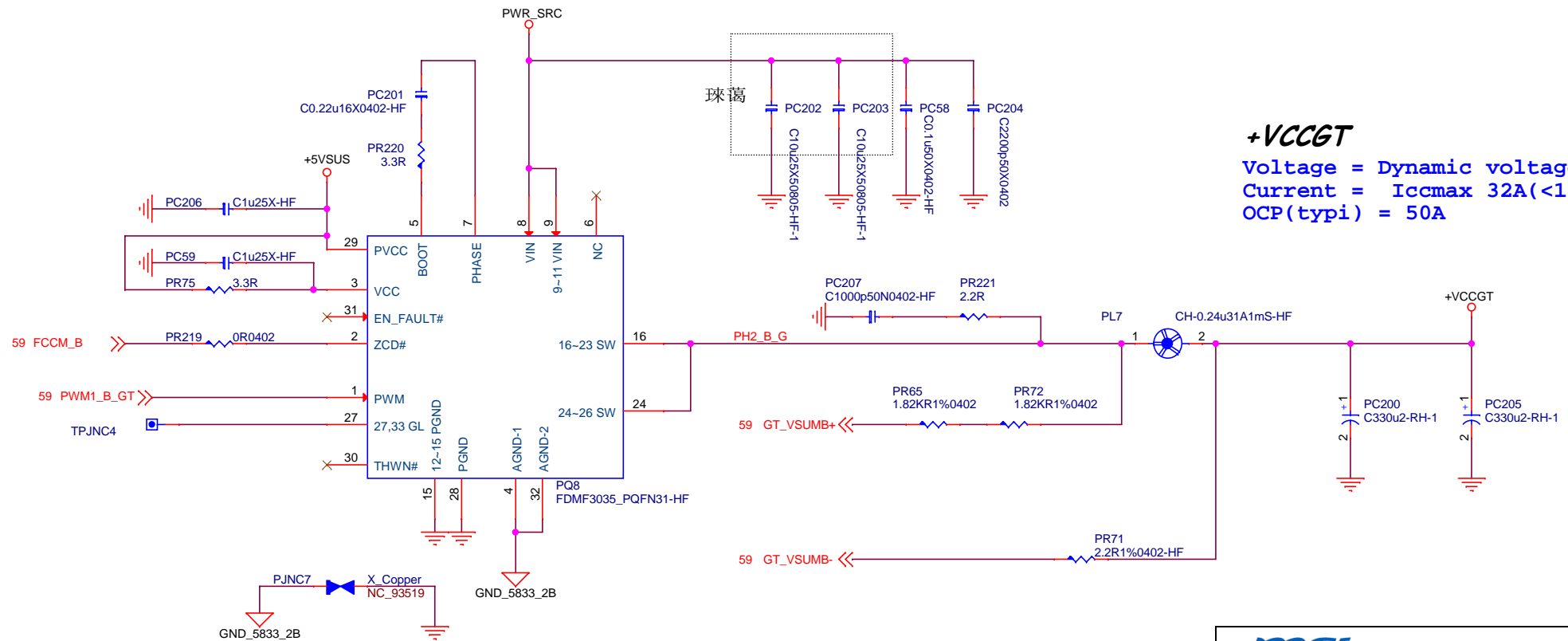
+1.1VRUN



Coffee Lake H-line 6+2 45W ISL95855A




+VCCGT

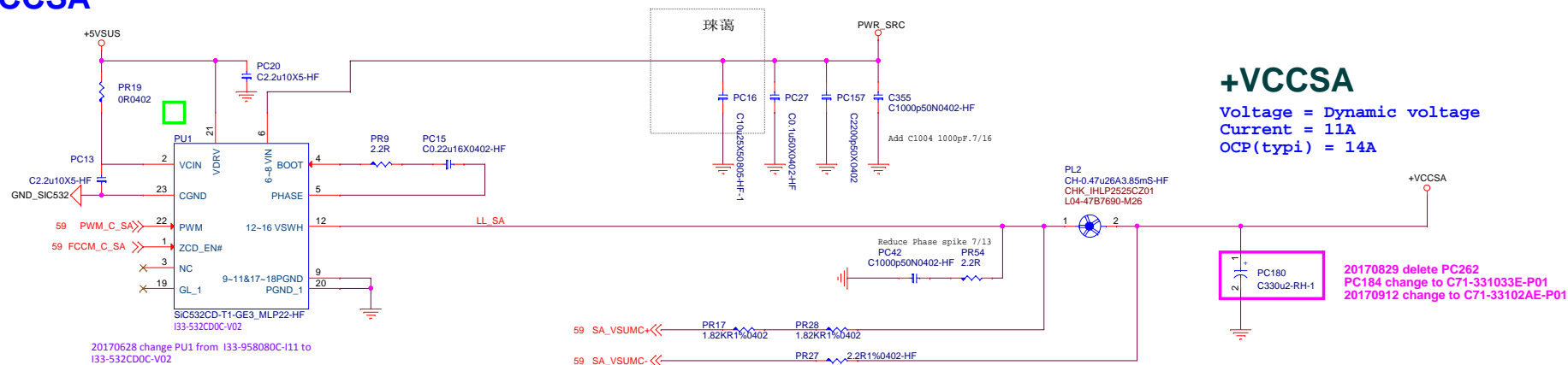


+VCCGT

```
Voltage = Dynamic voltage
Current = Iccmax 32A(<10mS)
OCP(typi) = 50A
```

		MICRO-STAR INT'L CO.,LTD.	
Title			
VCCGT			
Size	Document Number		Rev
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Date:	Thursday, January 18, 2018	Sheet	61 of 79

+VCCSA



+VCCSA

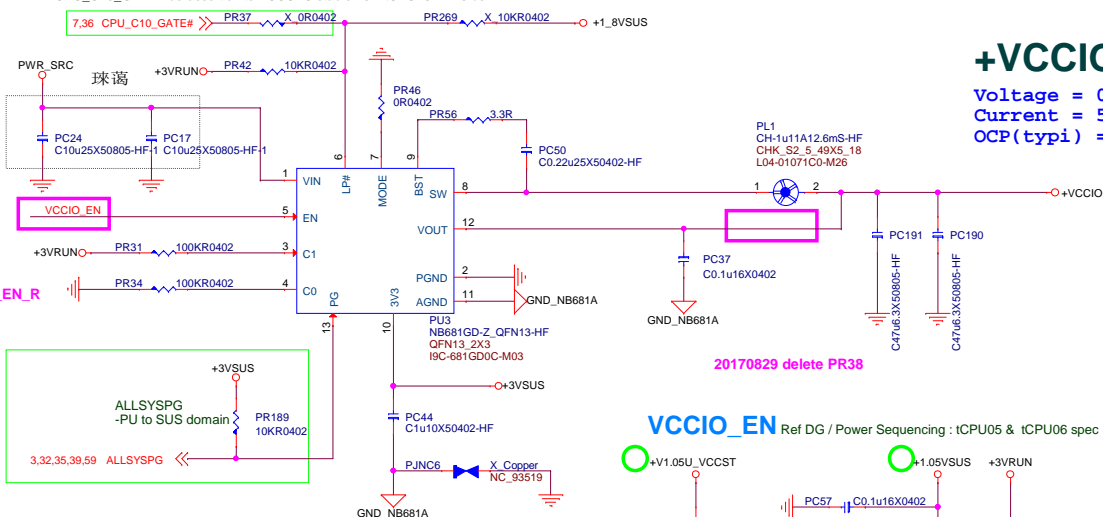
Voltage = Dynamic voltage
Current = 11A
OCP(typi) = 14A

PC180
C330u2-RH-1

20170829 delete PC262
PC184 change to C71-331033E-P01
20170912 change to C71-33102AE-P01

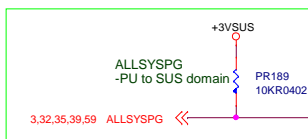
+VCCIO

Power Sequence spec ICPU27 :
CPU_C10_GATE# de-assertion to VCCSTG stable 10 < tCPU26 < 240 us

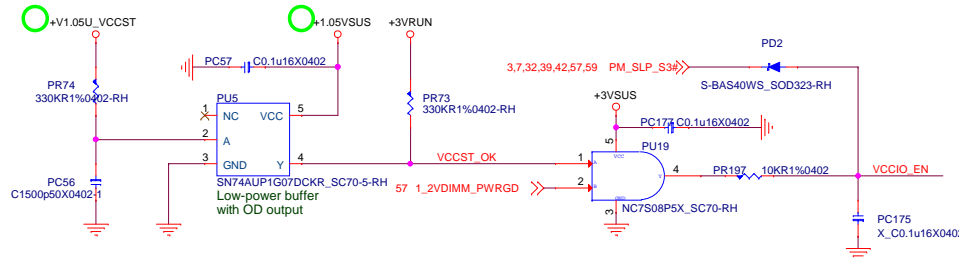


+VCCIO

Voltage = 0.95V
Current = 5.5A
OCP(typi) = 7.5A

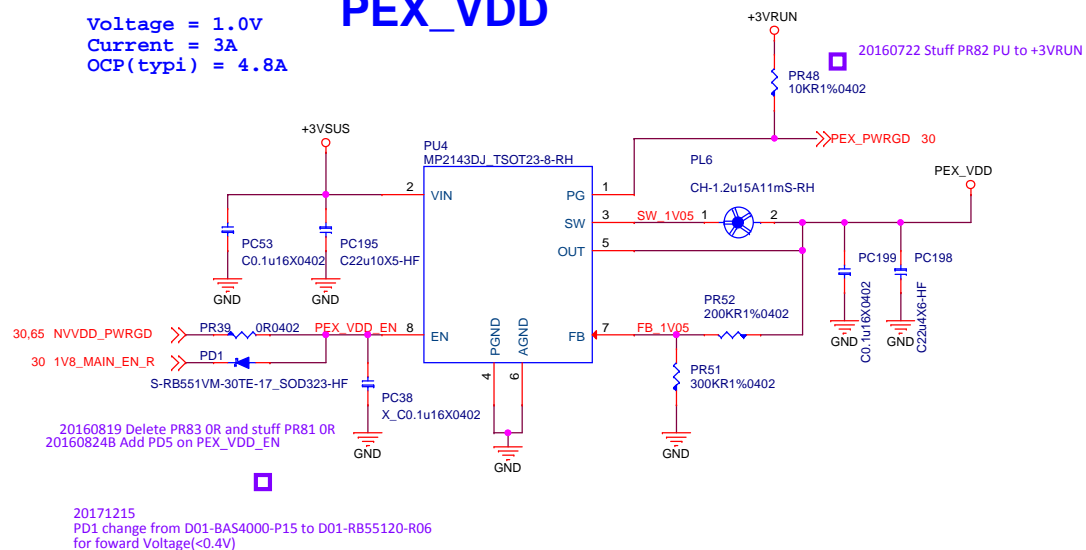


VCCIO_EN

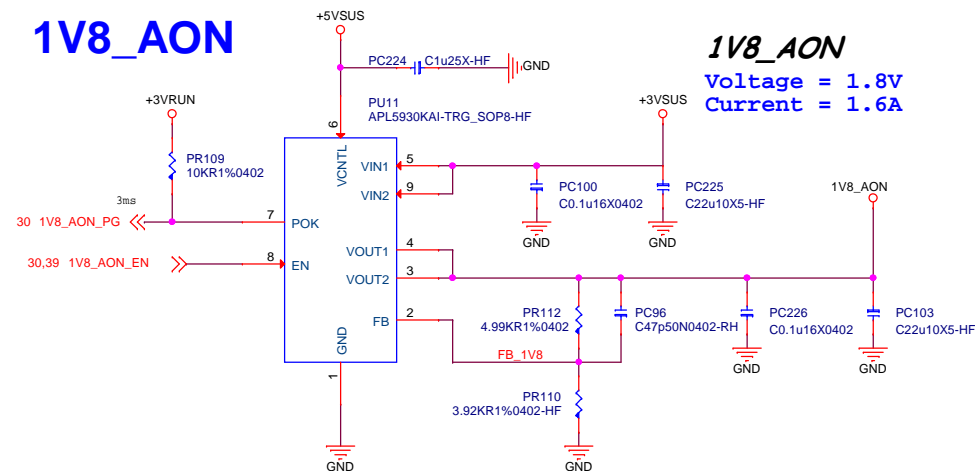


Voltage = 1.0V
Current = 3A
OCP(typi) = 4.8A

PEX_VDD



1V8_AON

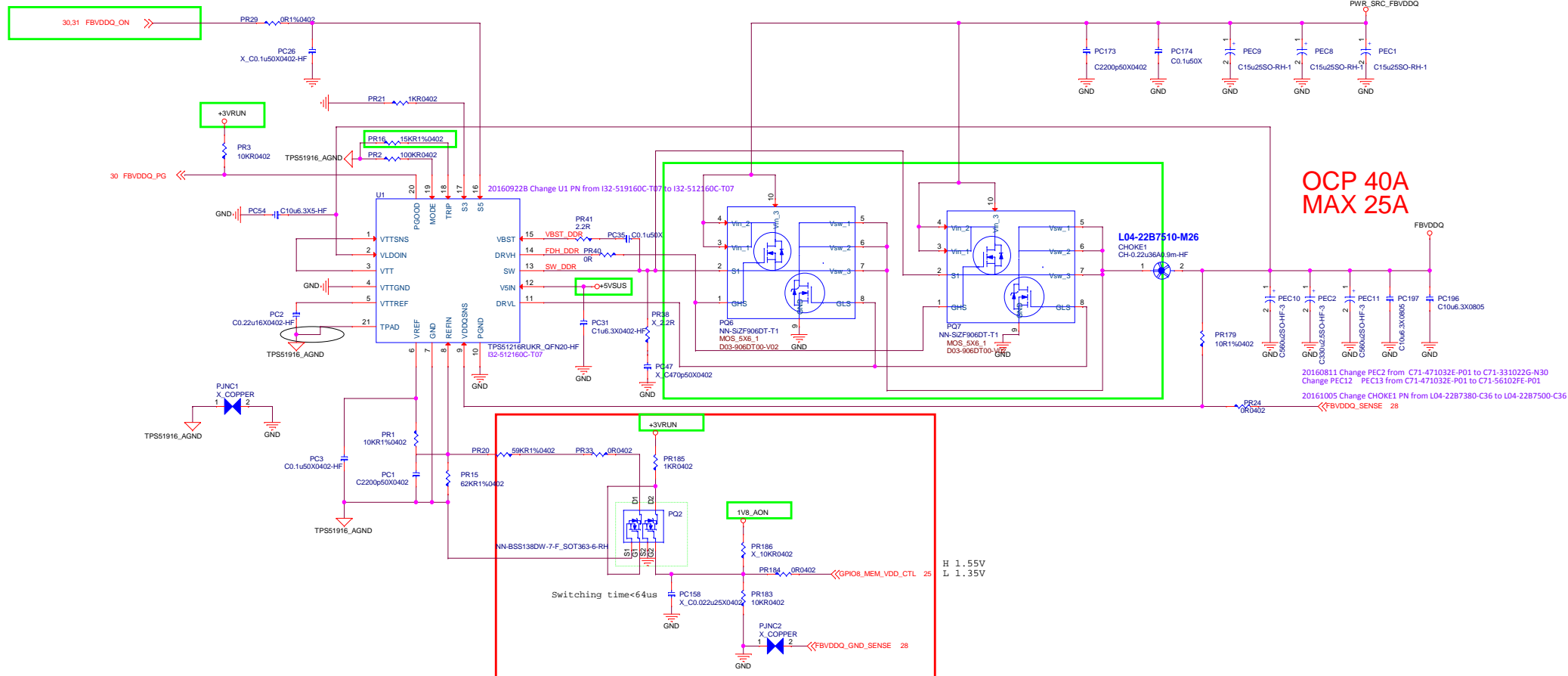



1V8_AON
Voltage = 1.8V
Current = 1.6A

msi MICRO-STAR INT'L CO.,LTD.

Title		
PEX_VDD/1.8V		
Size	Document Number	Rev
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Date: Thursday, January 18, 2018		
Sheet 63 of 79		

20171108
change PR16 to R11-0153T12-W08



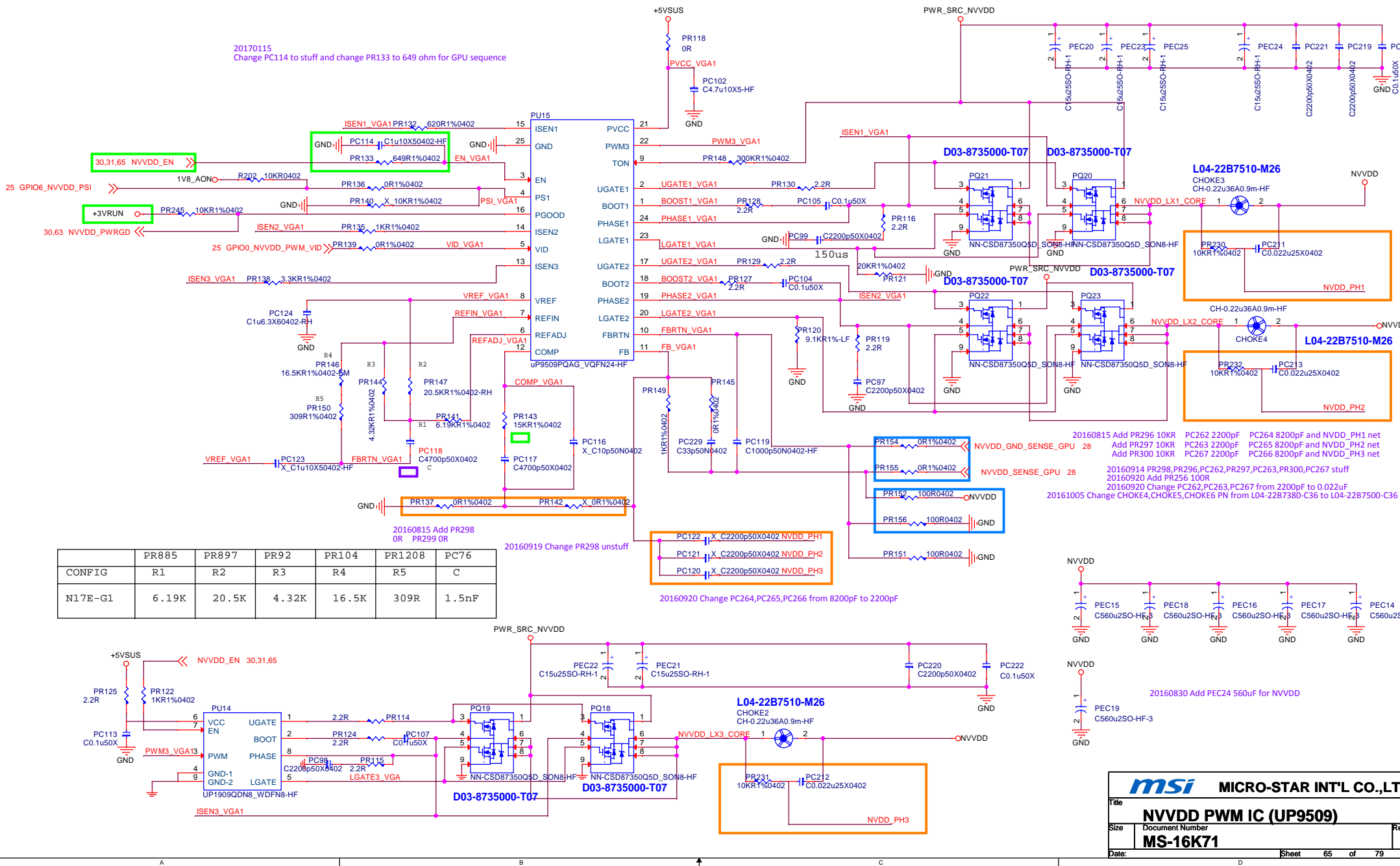
		MICRO-STAR INT'L CO.,LTD.	
Title DGPU POWER FBVDDQ			
Size	Document Number MS-16K71		Rev 10
Date:	Sheet		64 of 79

DGPU POWER / UP9509P

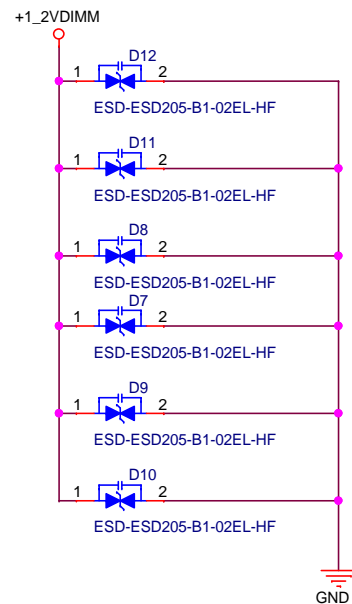
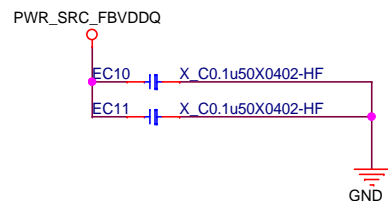
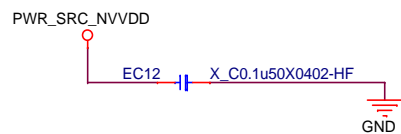
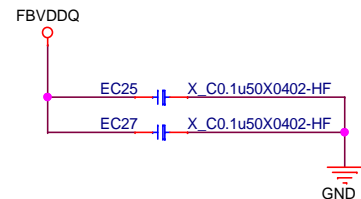
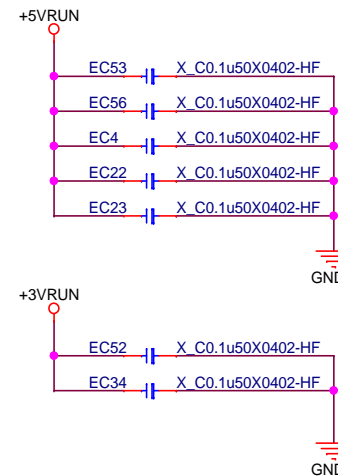
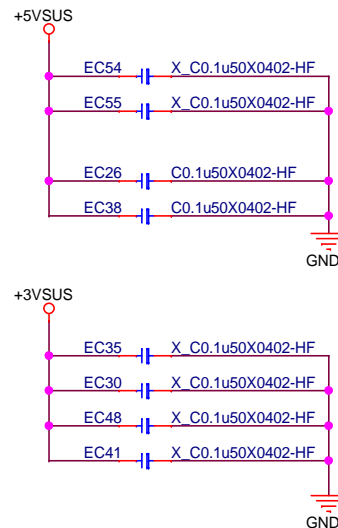
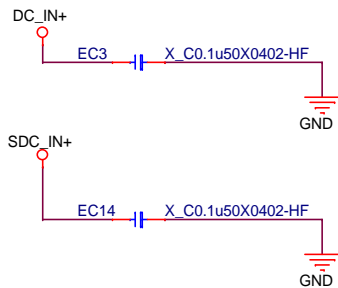
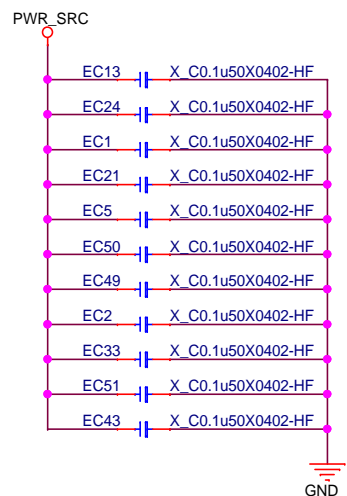
EDP-Peak 180A
EDP-Con 80A


DGPU POWER NVVDD

VBoot:0.8V
Vmin:0.3V / Vmax:1.3V



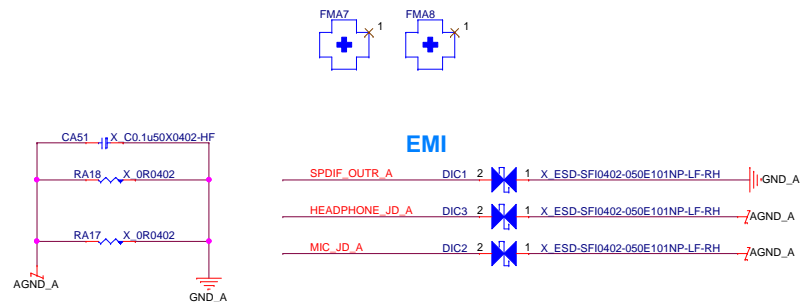
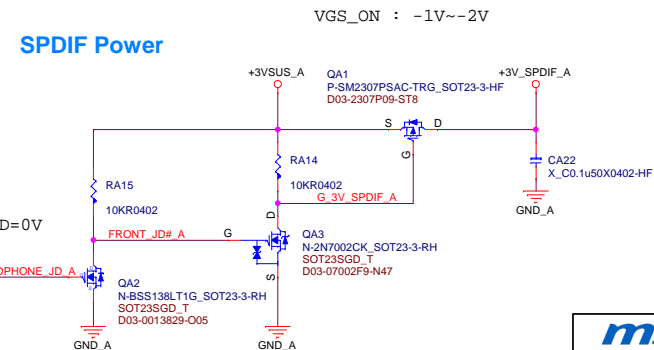
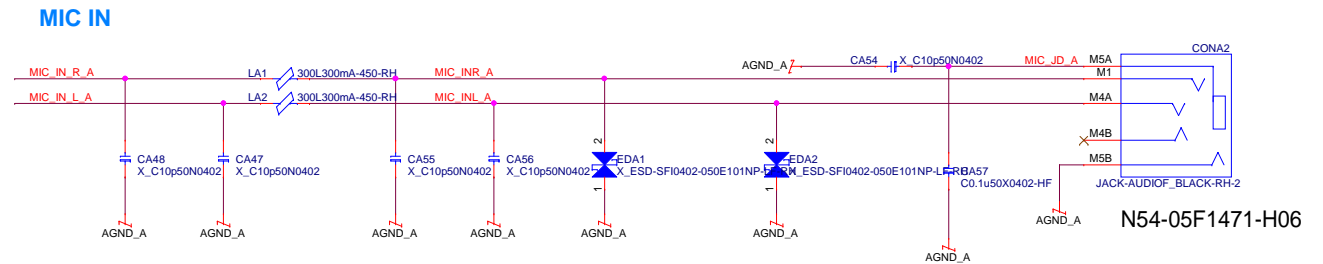
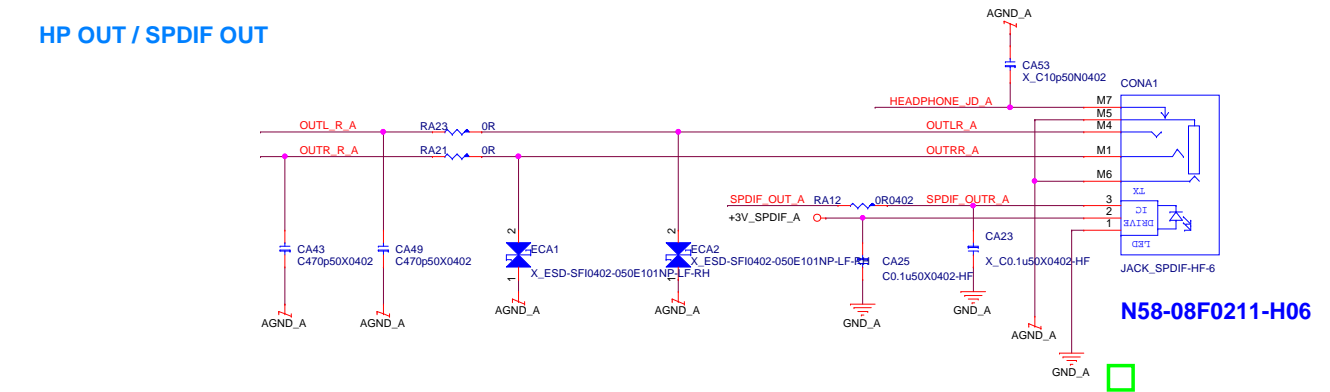
EMI



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20171220
change FPCA2 to 32pin and modify FPCA1 pin define for new design
(Audio issue and USB3.1 solution change)

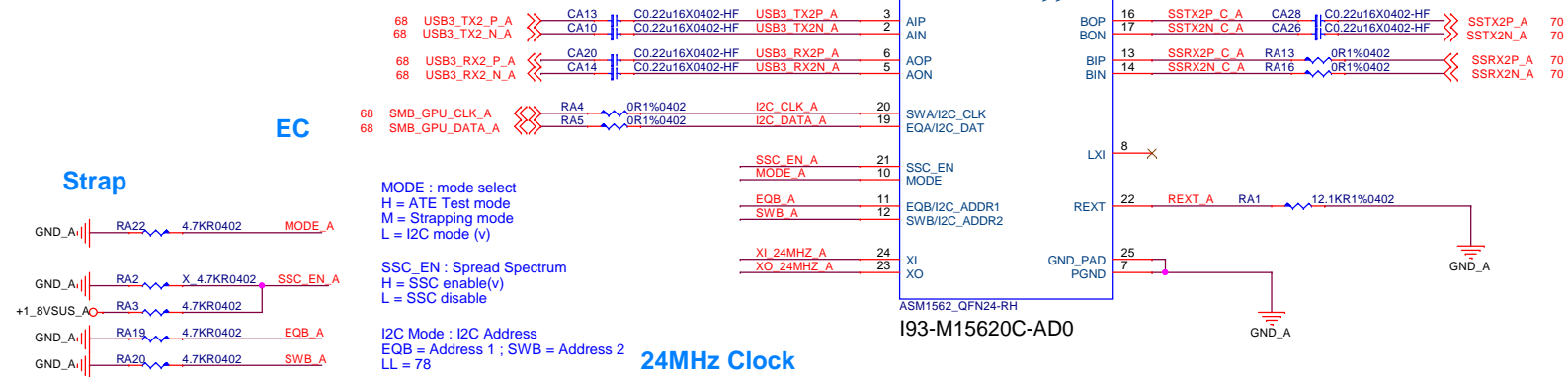
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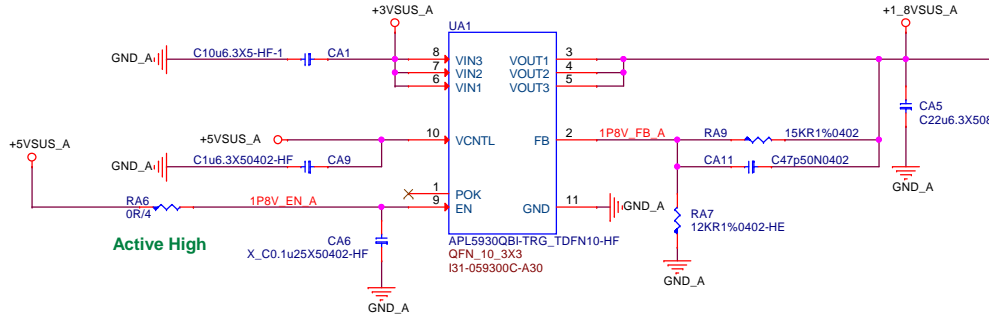
USB3.1 Gne2 Retimer ASM1562

20171101 ASM1562 retimer

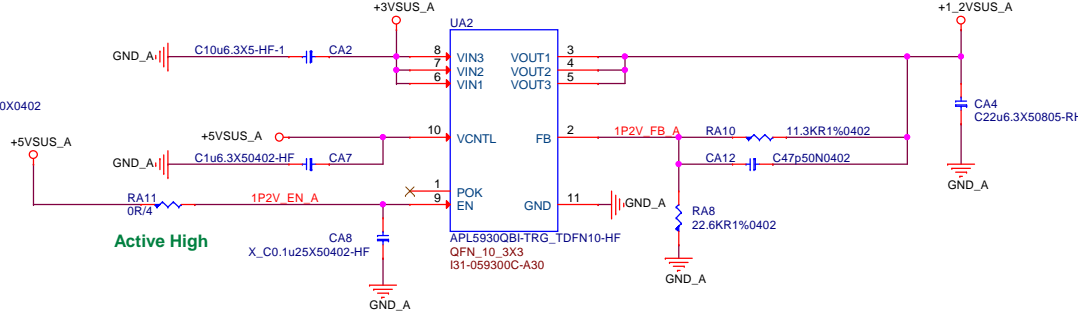
USB3.1 Gne2 Retimer



+1_8VSUS_A

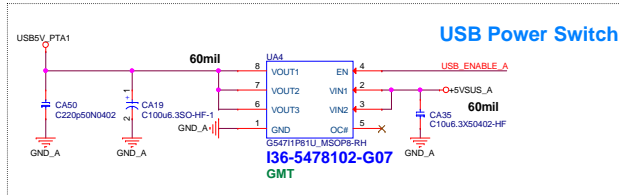
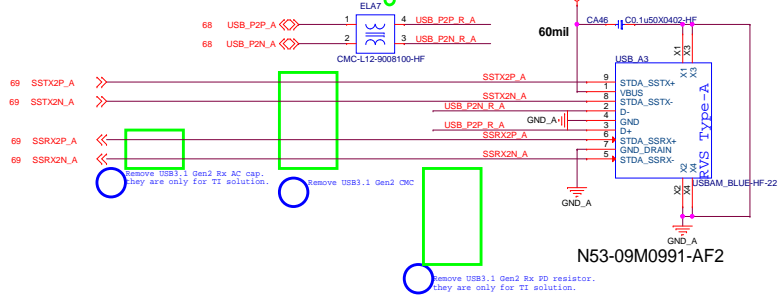


+1_2VSUS_A



[A] USB3.0 CNT-2/-3

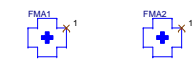
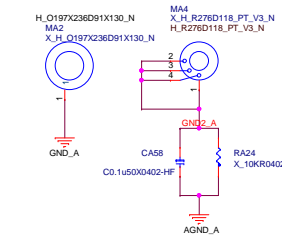
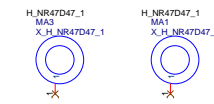
USB3.0 CNT-3 USB3.0 Port-2 USB2.0 Port-2



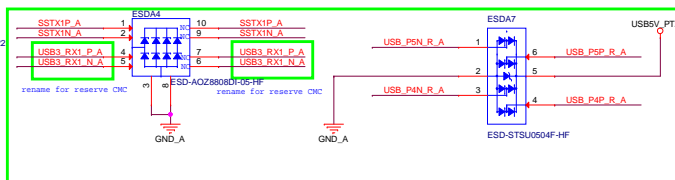
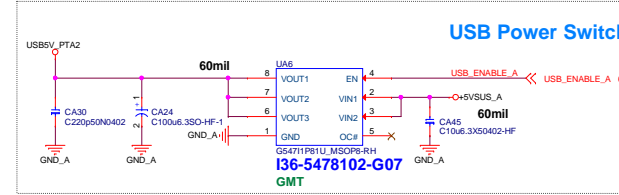
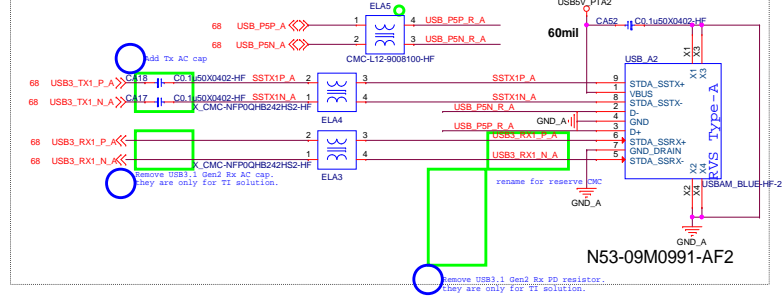
MYLARA4
E2P-6K50211-G40
USB_MYLAR



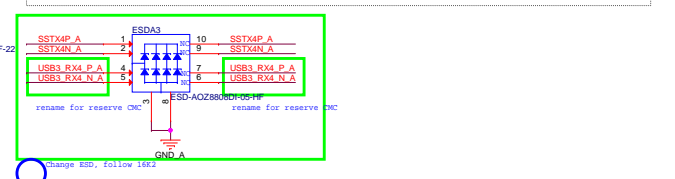
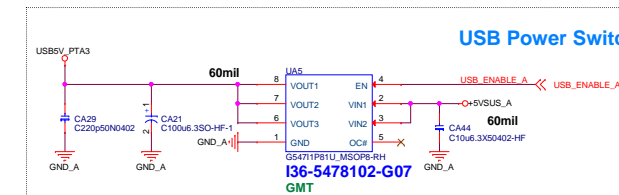
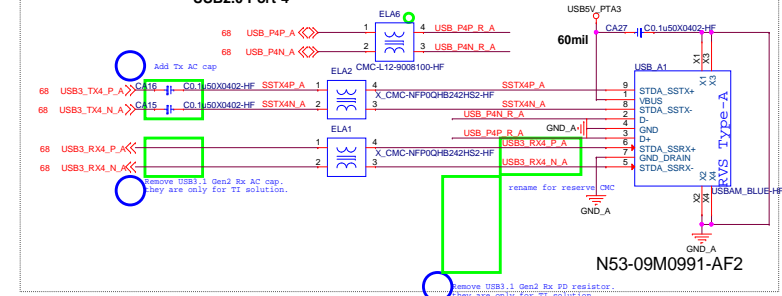
PD0-16K7A10-H73
PD0-16K7A10-H73

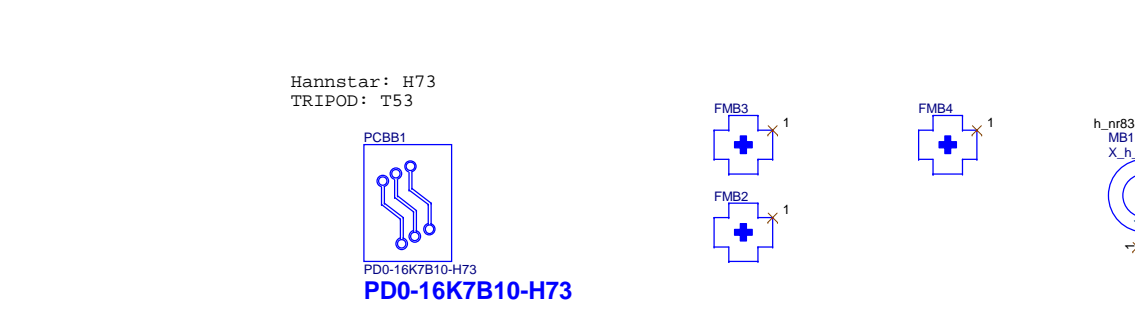
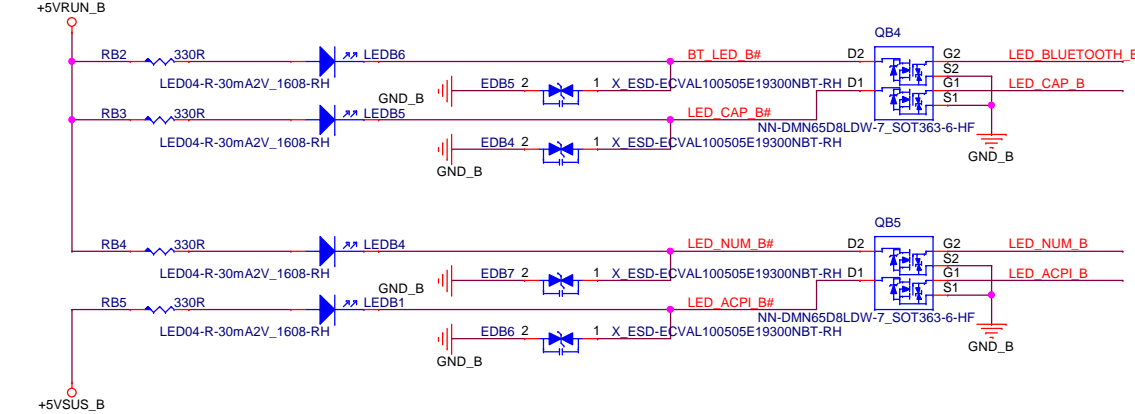
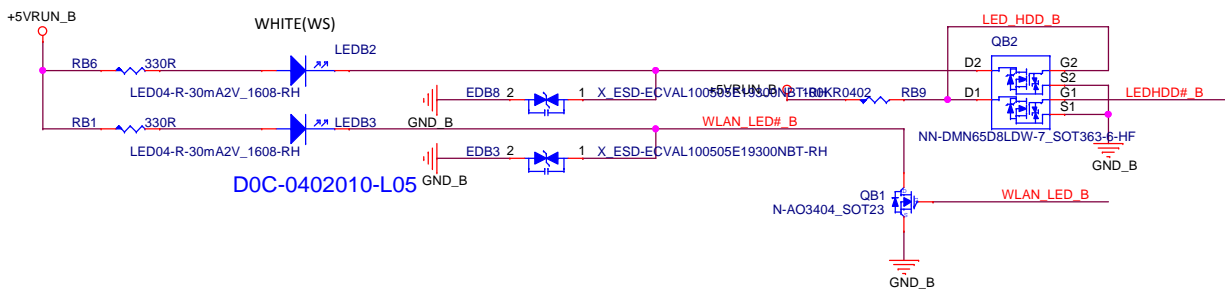
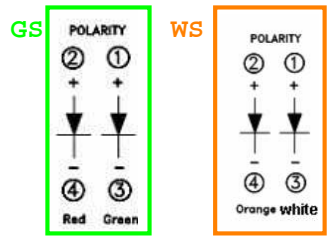
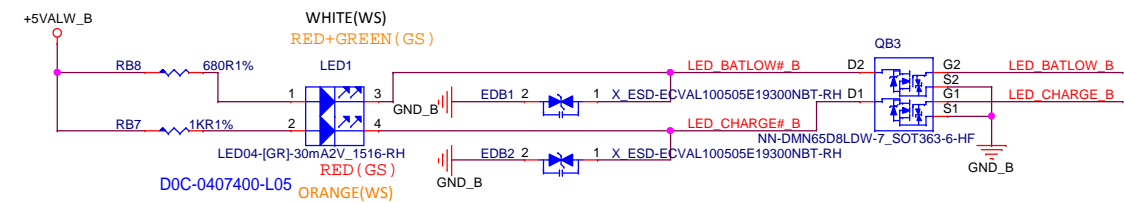


USB3.0 CNT-2 USB3.0 Port-1 USB2.0 Port-5

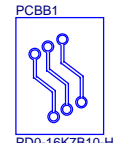


USB3.0 CNT-1 USB3.0 Port-4 USB2.0 Port-4

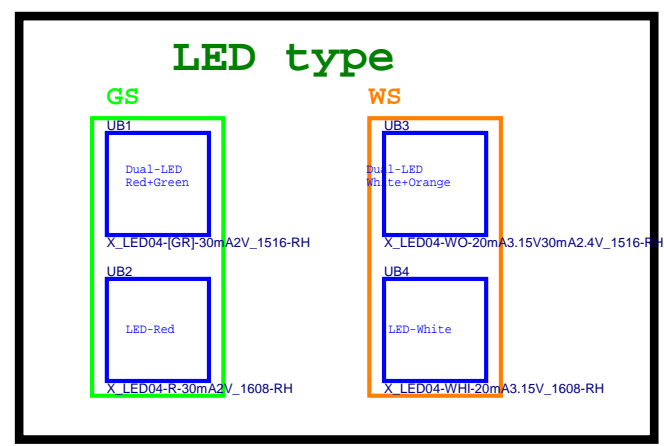
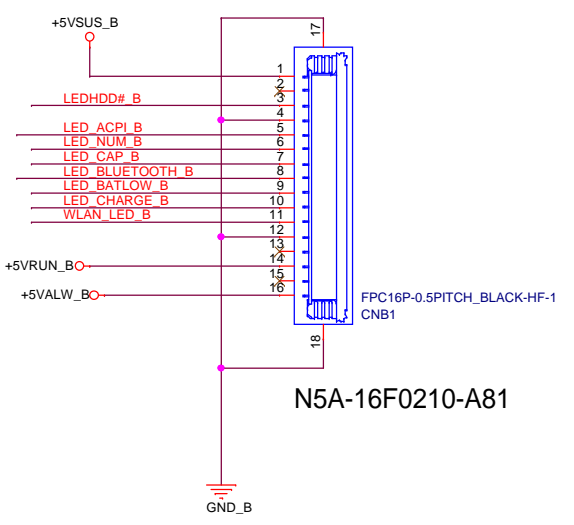
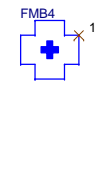
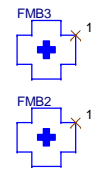





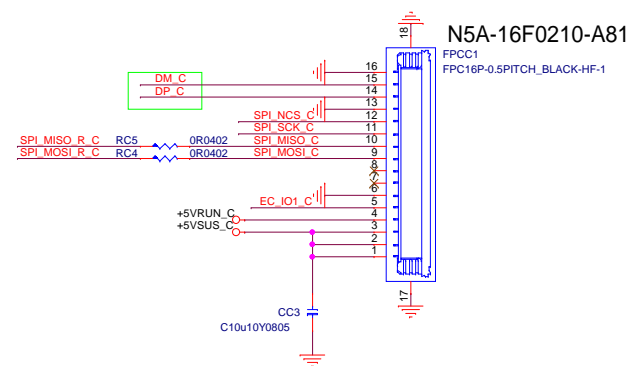
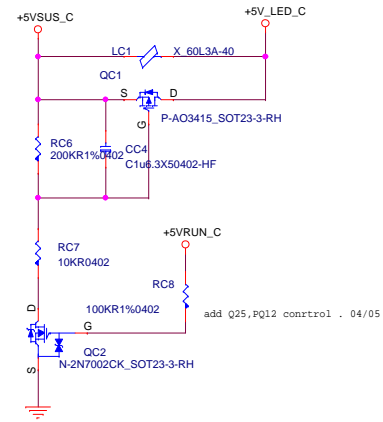
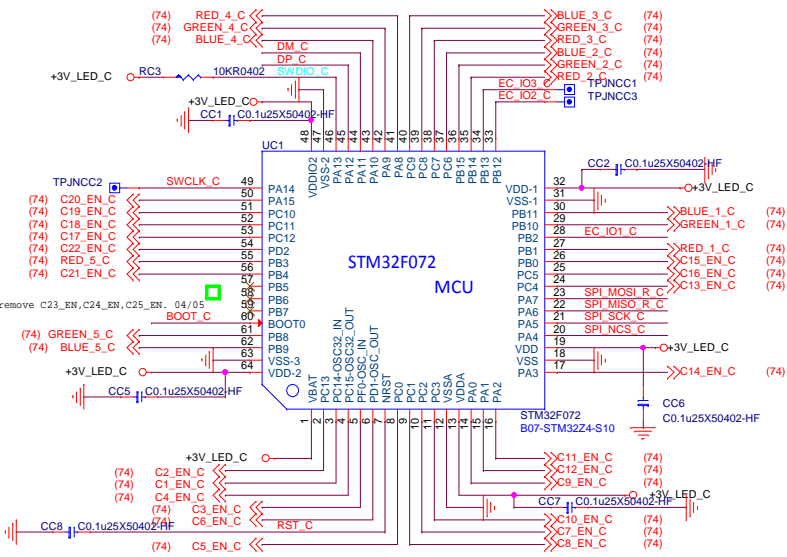
Hannstar: H73
TRIPOD: T53



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Confirm Pin 1 position

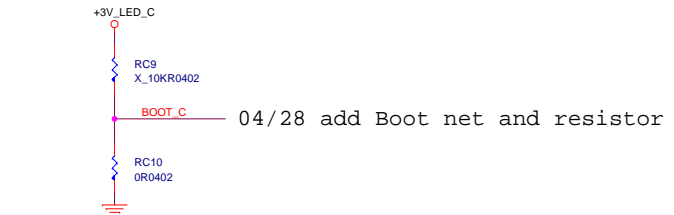
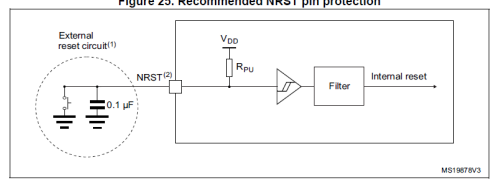
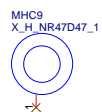


Figure 25. Recommended NRST pin protection



- The external capacitor protects the device against parasitic resets.
- The user must ensure that the level on the NRST pin can go below the $V_{IL(NRST)}$ max level specified in Table 56. NRST pin characteristics. Otherwise the reset will not be taken into account by the device.



UMEC5 16K7C BOM

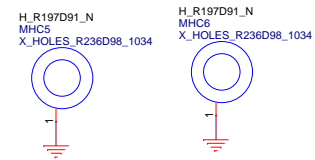
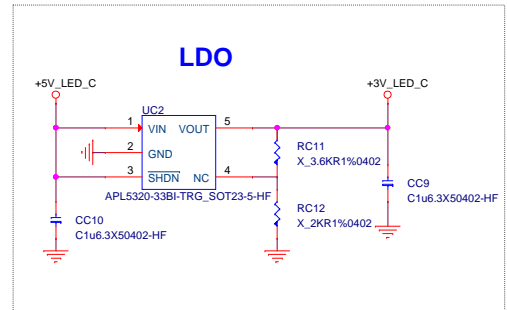
E2Y-Z001511-G40

MECH WASHER

UMEC6

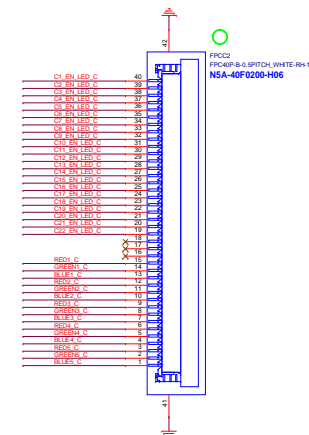
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MECH WASHER

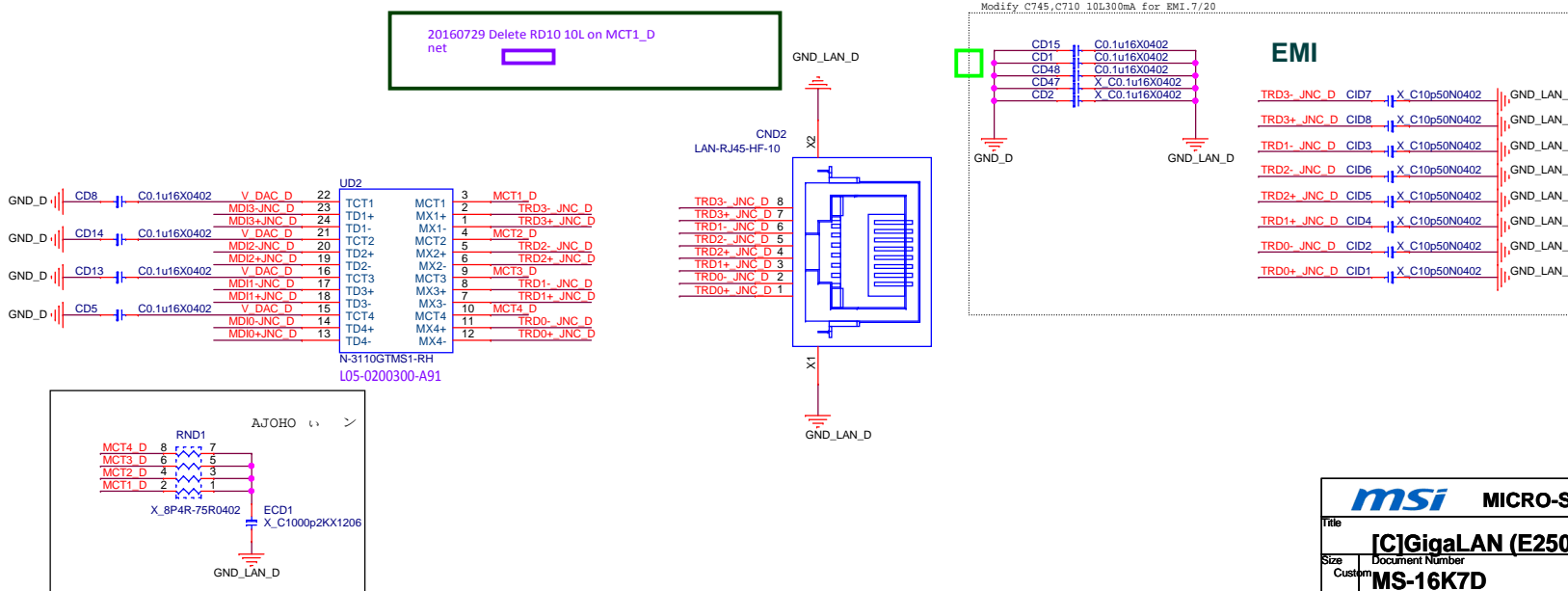
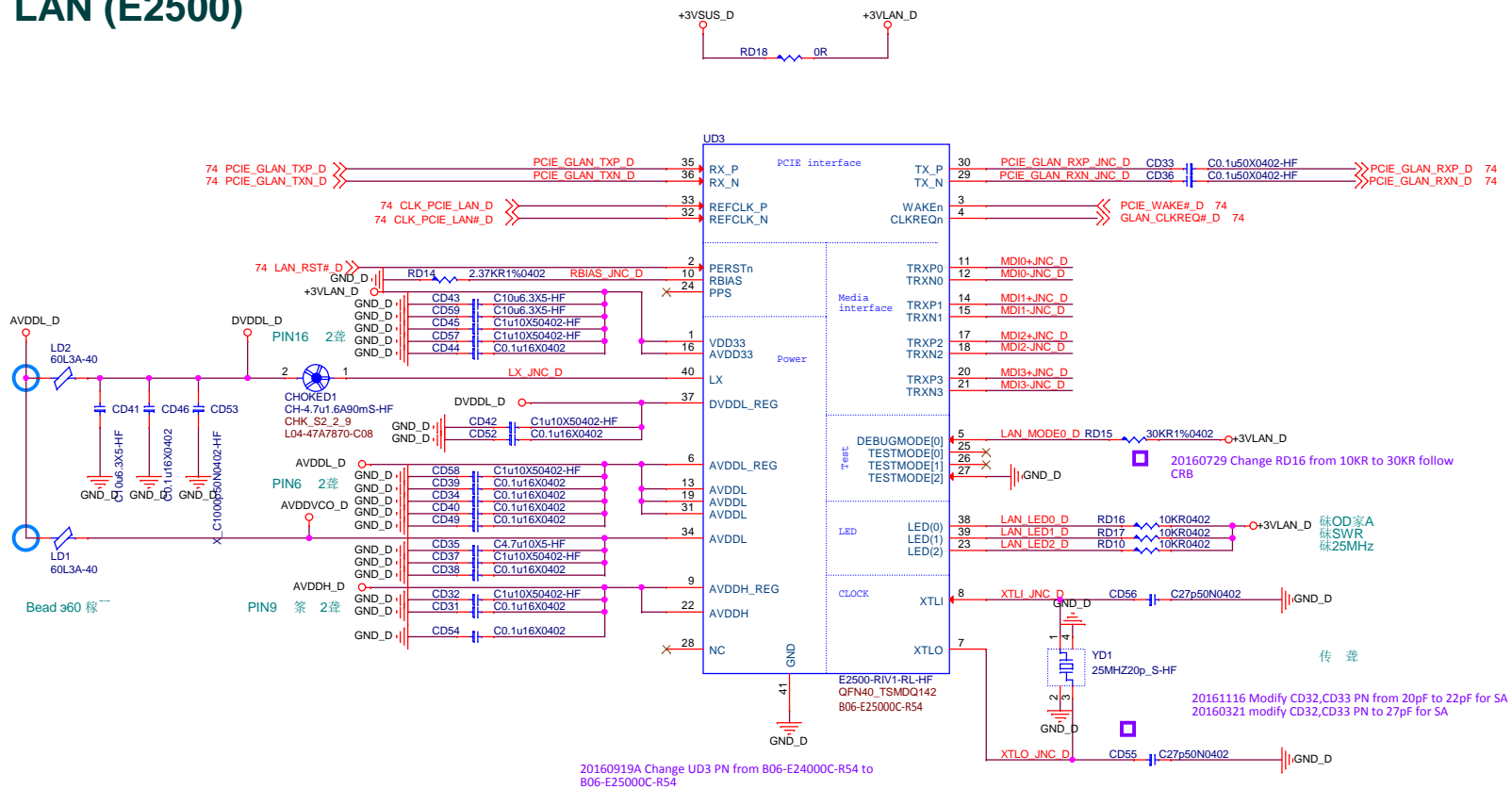


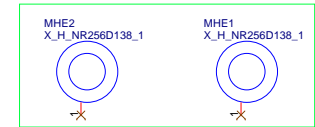
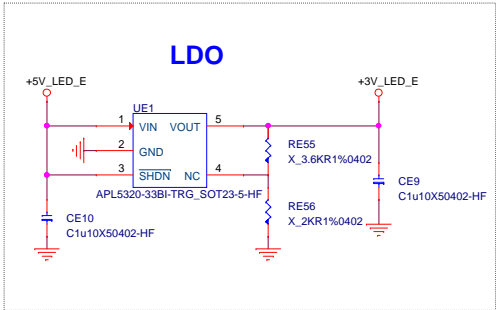
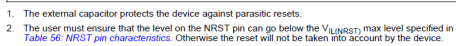



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LAN (E2500)





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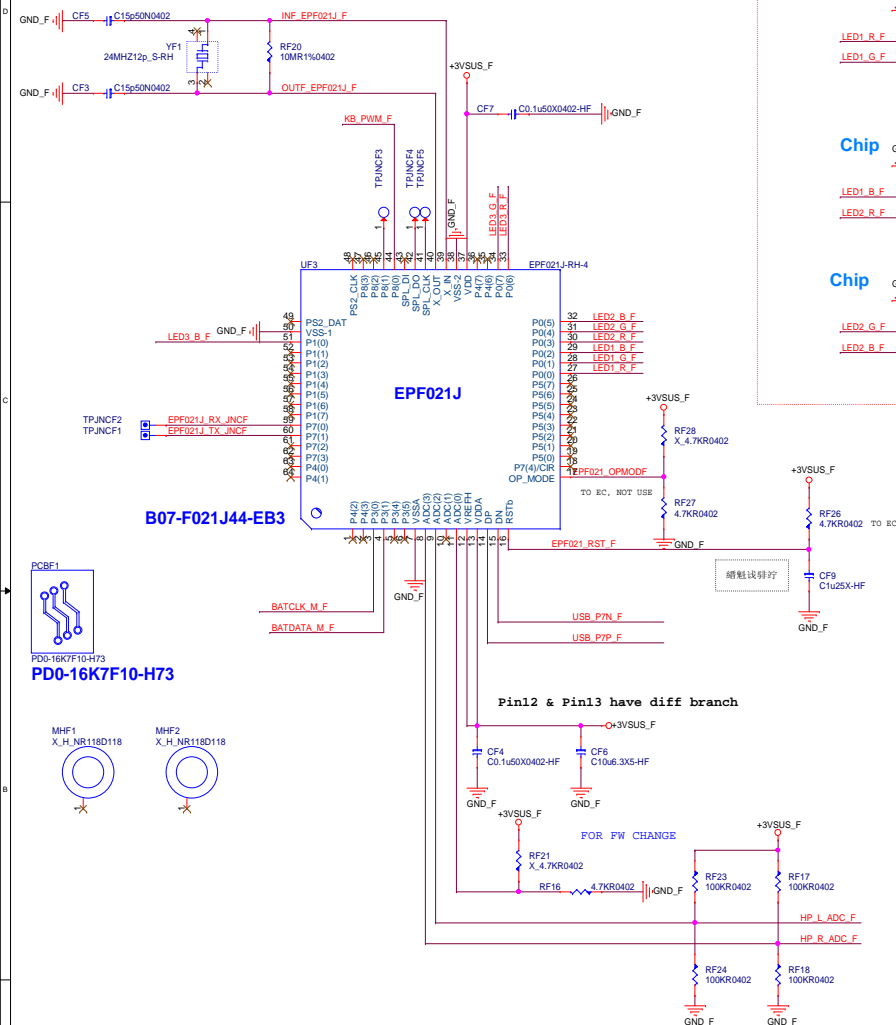



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 File **[E]LED control**
 Doc Document Number Rev
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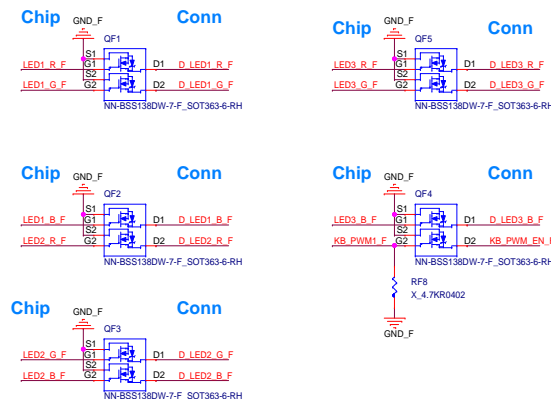
LED 8051 Controller

F PCB 8/21 楓椒

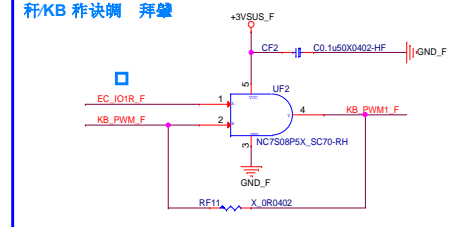
C749 and C750 change to 15pF for SA



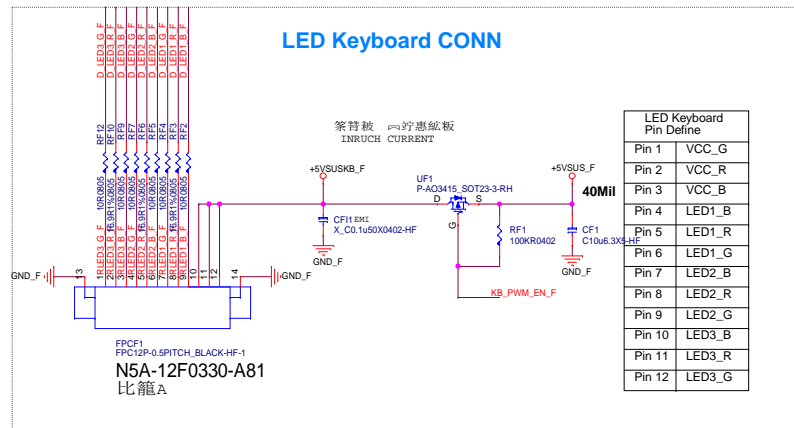
EPF021J Sink current not enough, only using BSS138 (0.22A)



杆/KB 祚诀绸 拜蠟



LED Keyboard CONN



Pin	Define
Pin 1	VCC_G
Pin 2	VCC_R
Pin 3	VCC_B
Pin 4	LED1_B
Pin 5	LED1_R
Pin 6	LED1_G
Pin 7	LED2_B
Pin 8	LED2_R
Pin 9	LED2_G
Pin 10	LED3_B
Pin 11	LED3_R
Pin 12	LED3_G

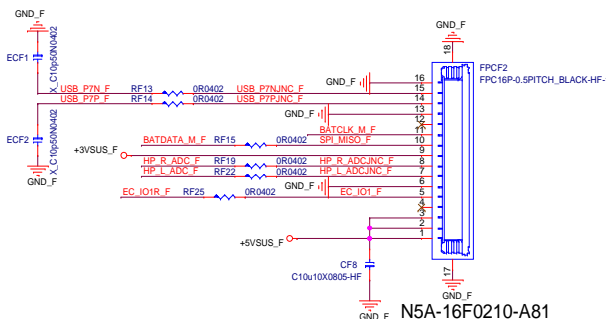
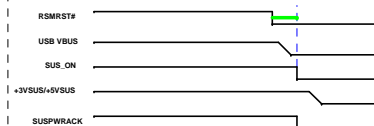
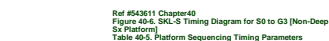



Figure 40-4. SKL-S Timing Diagram for G3 to S0/M0 (Non-Deep Sx Platform)



S0 to G3



16K7 0A

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